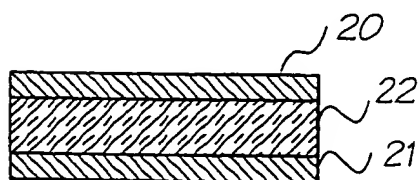


FIG. 3



↓ Cooling

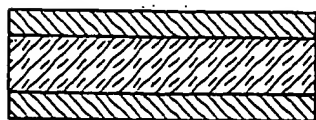
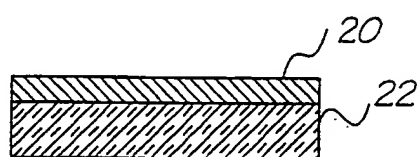


FIG. 4



↓ Cooling

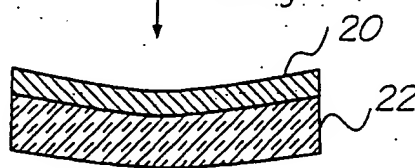


FIG. 5

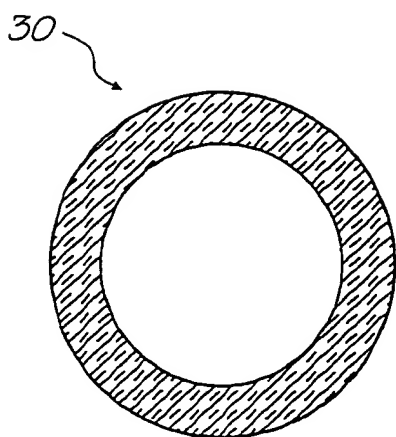


FIG. 6

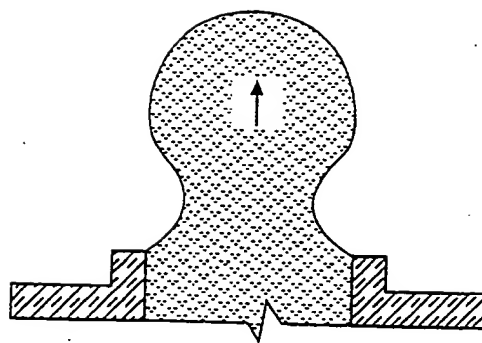


FIG. 7

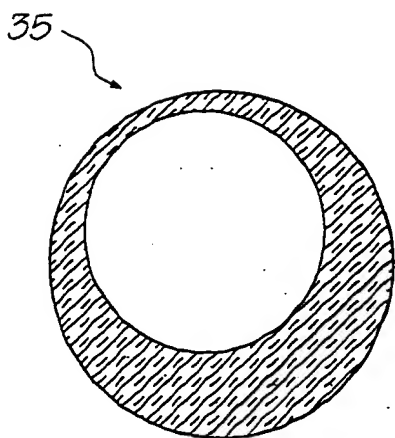


FIG. 8

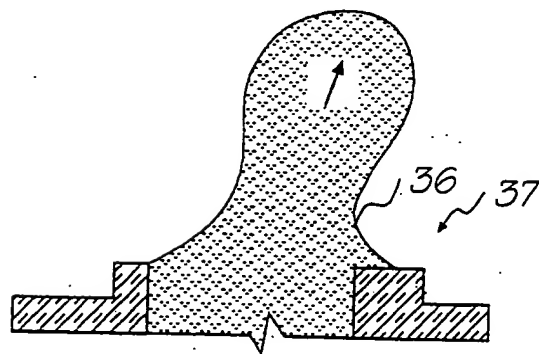


FIG. 9

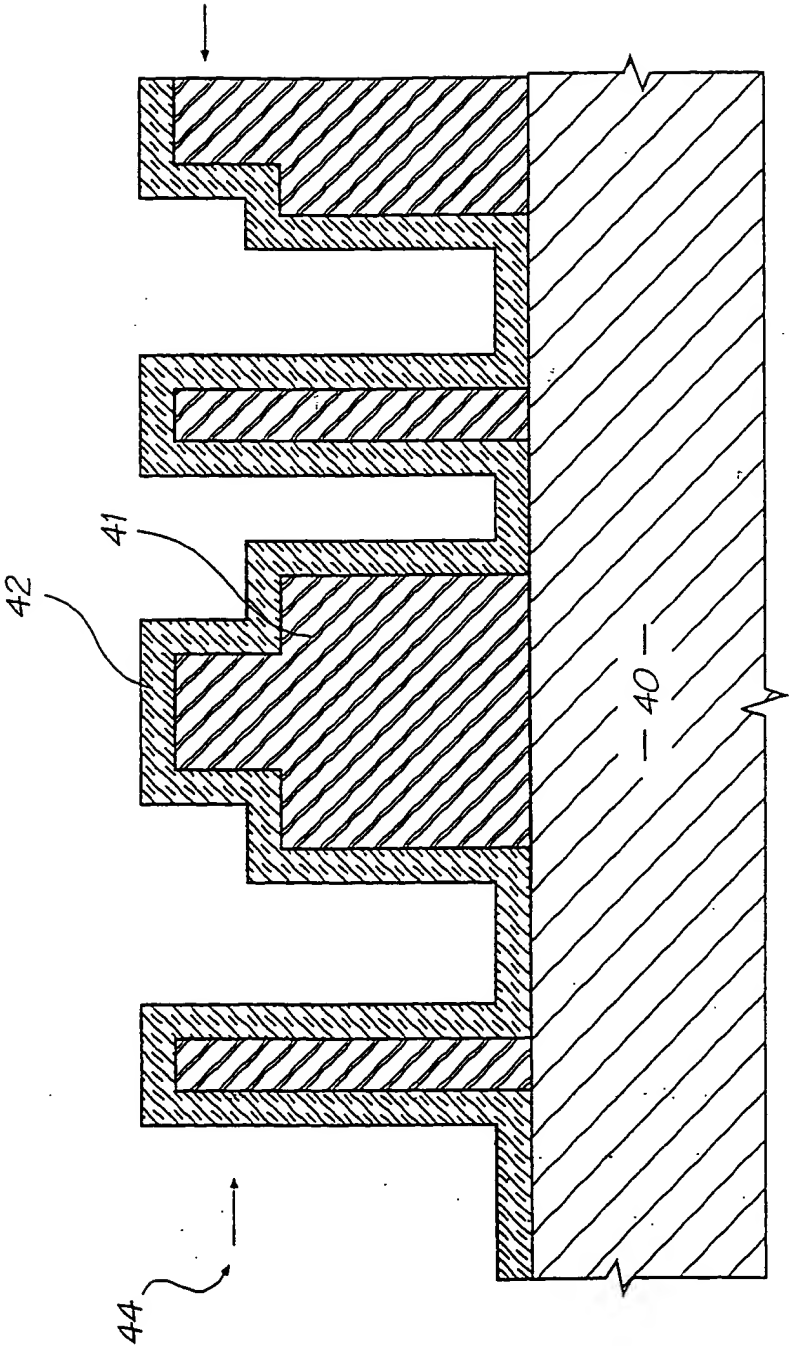


FIG. 10

FIG. 10

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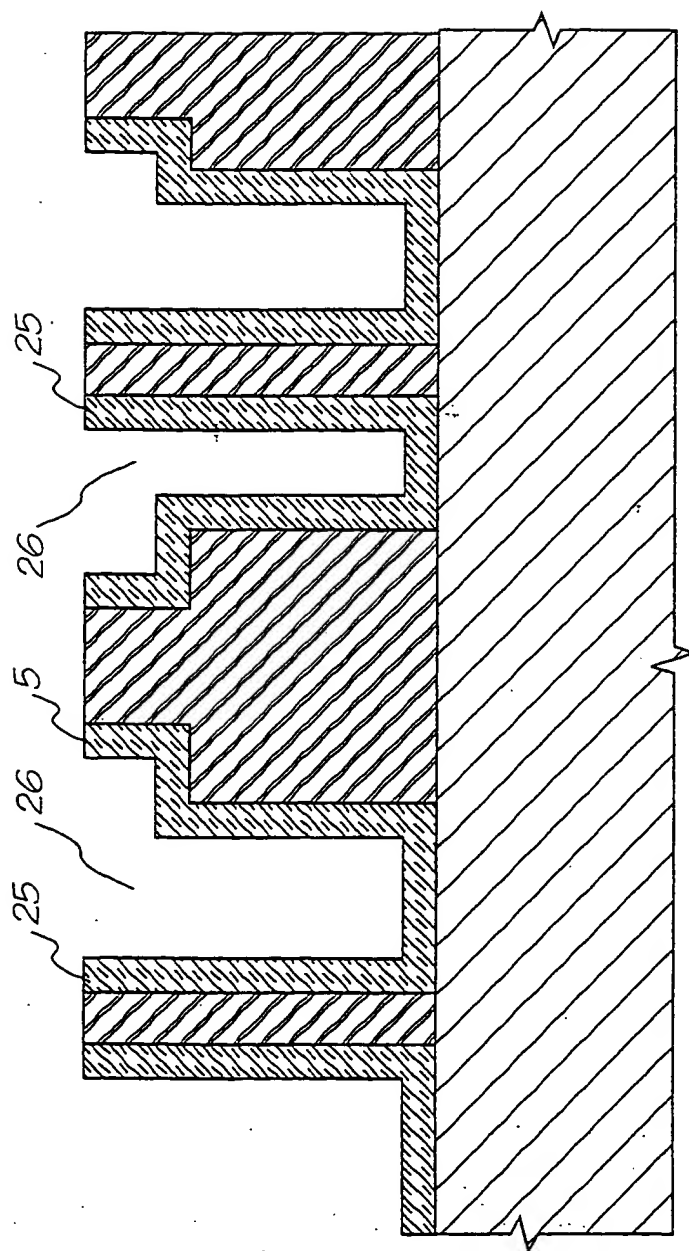


FIG. 11

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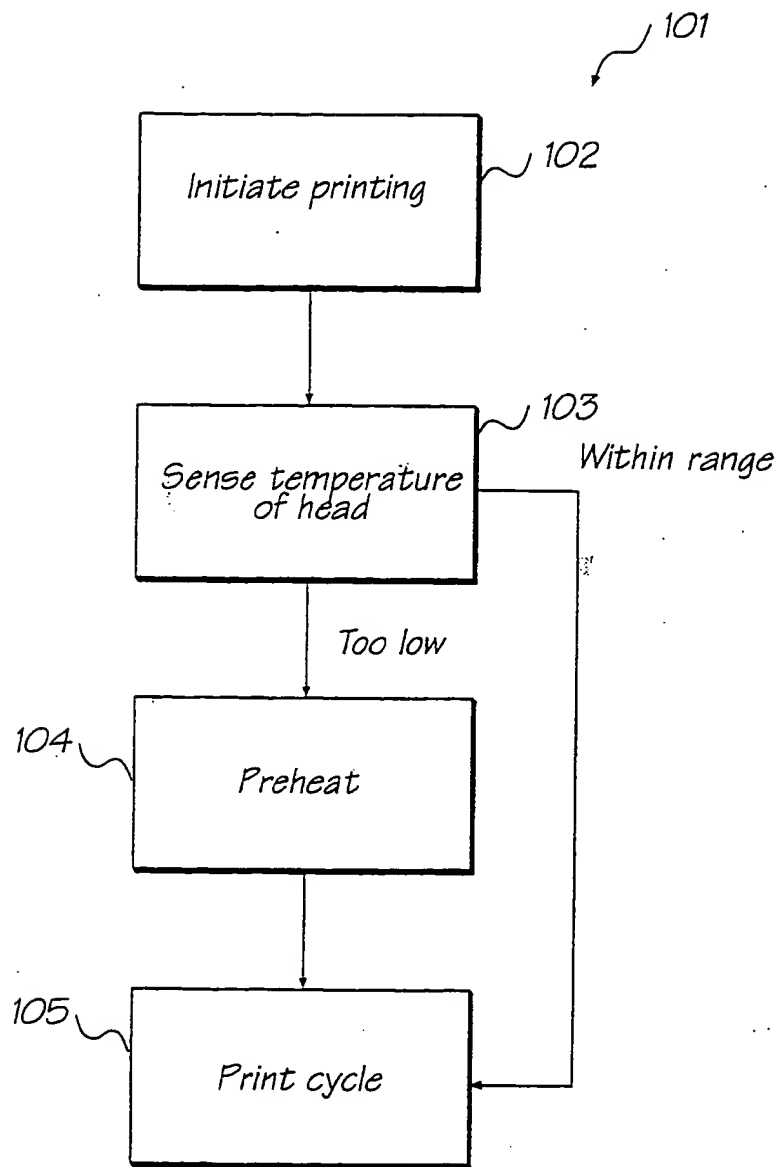


FIG. 12

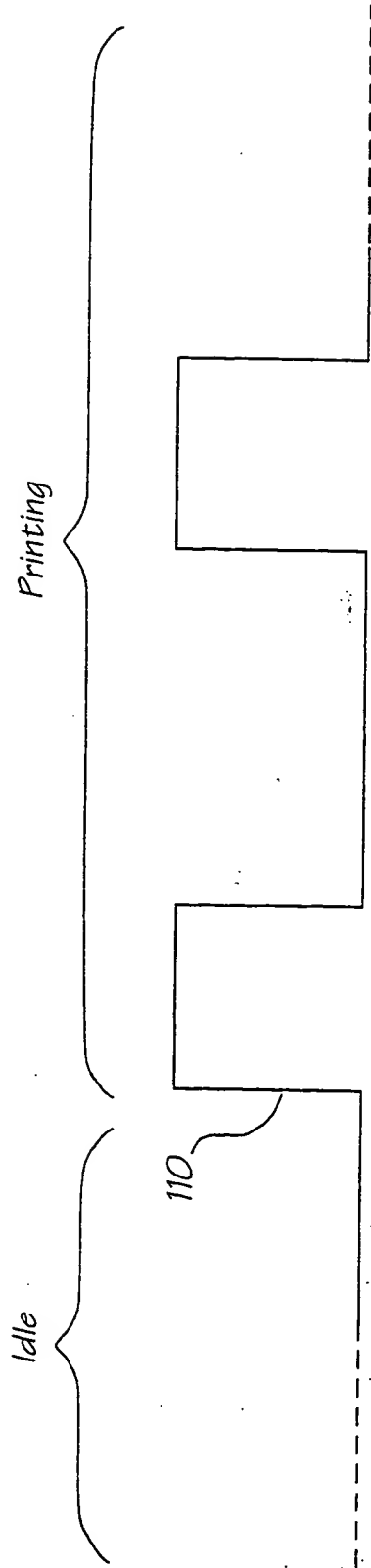


FIG. 13

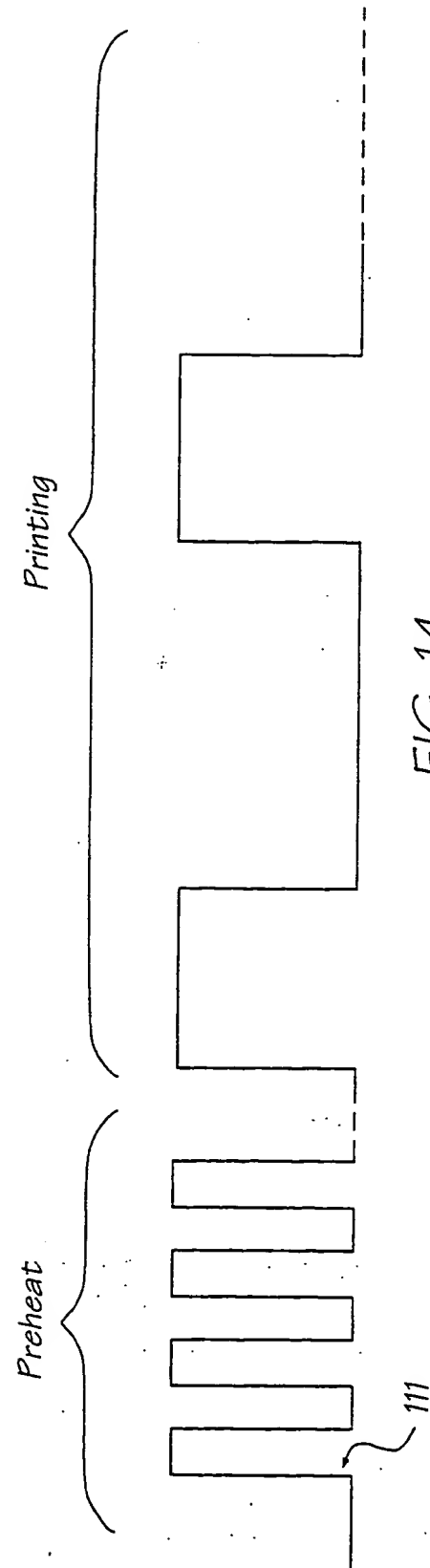


FIG. 14

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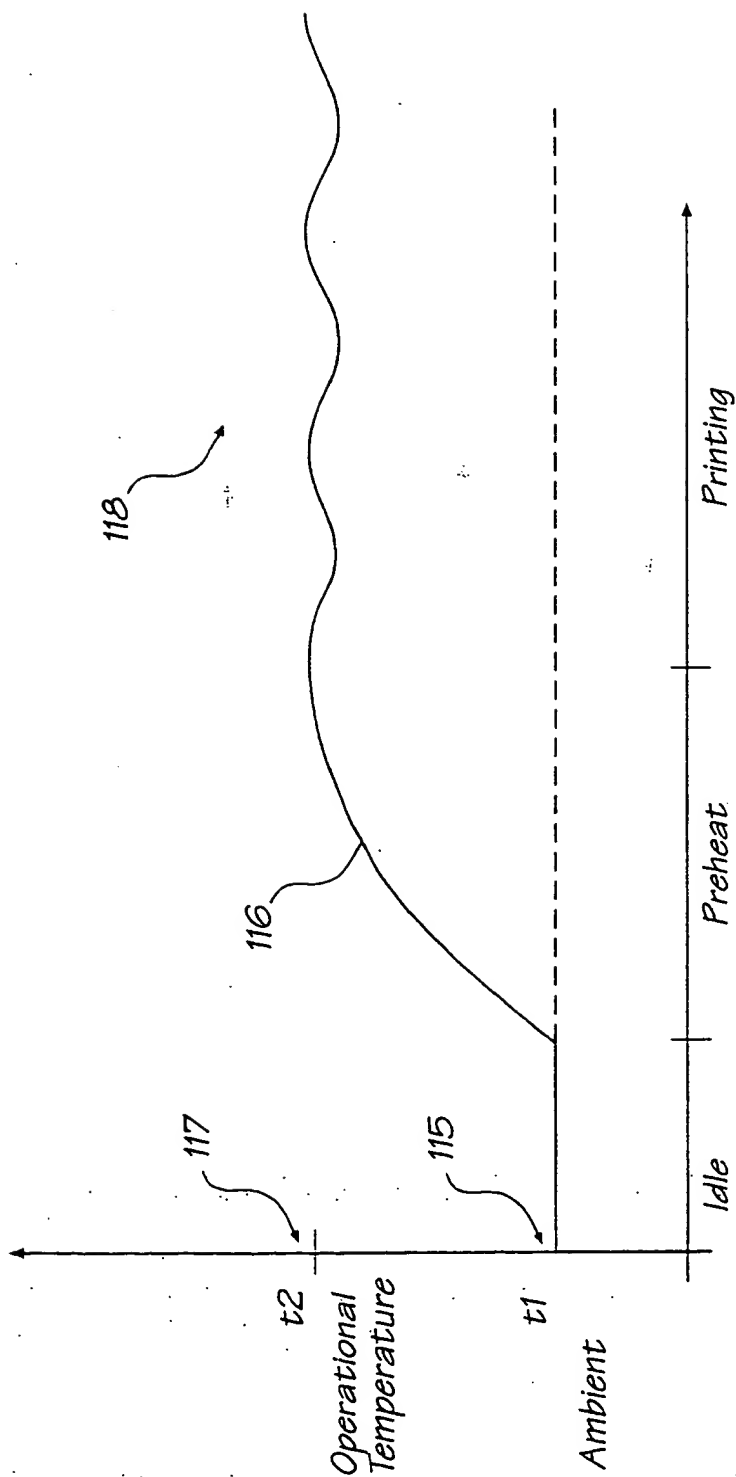


FIG. 15



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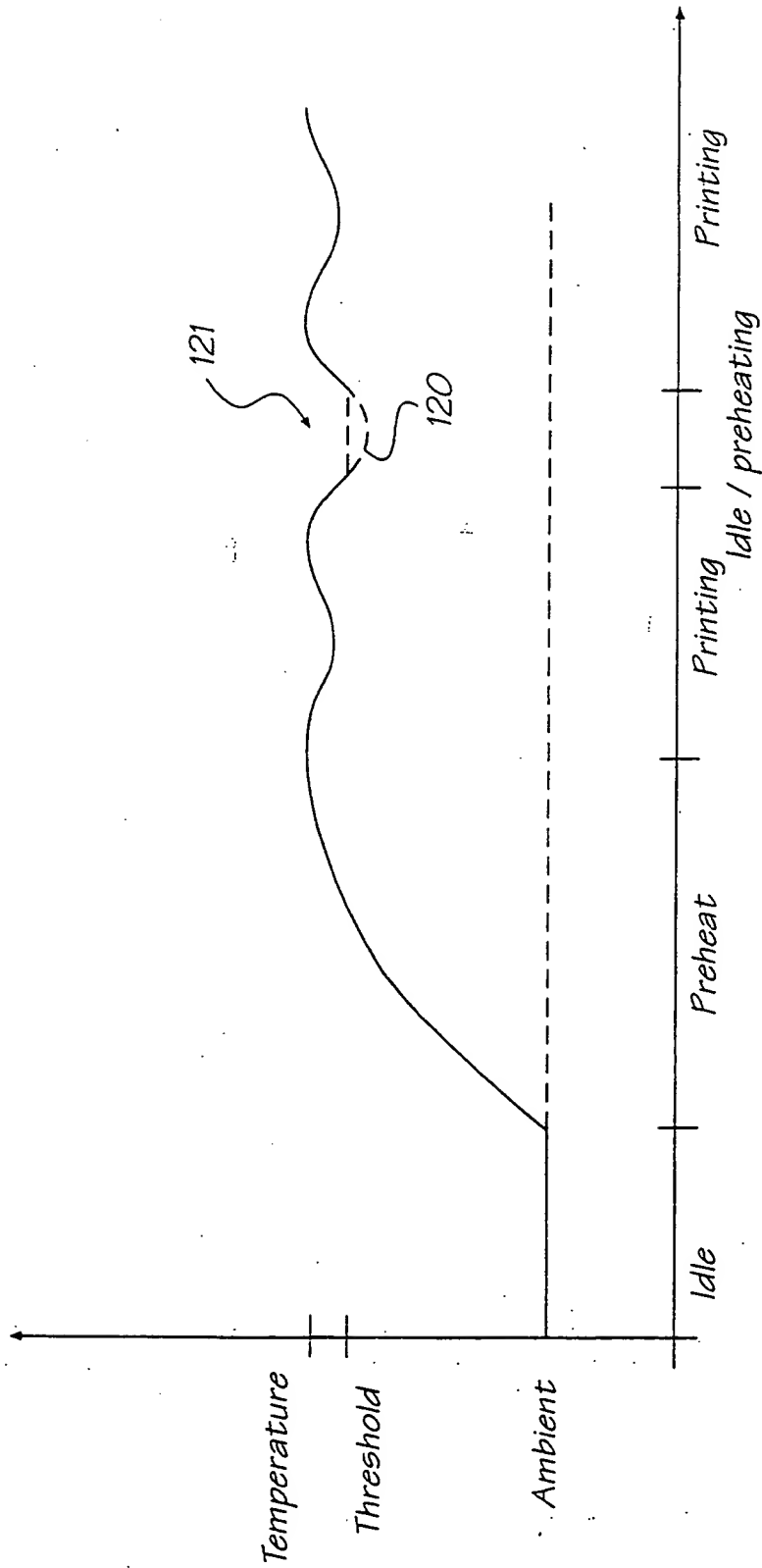


FIG. 16

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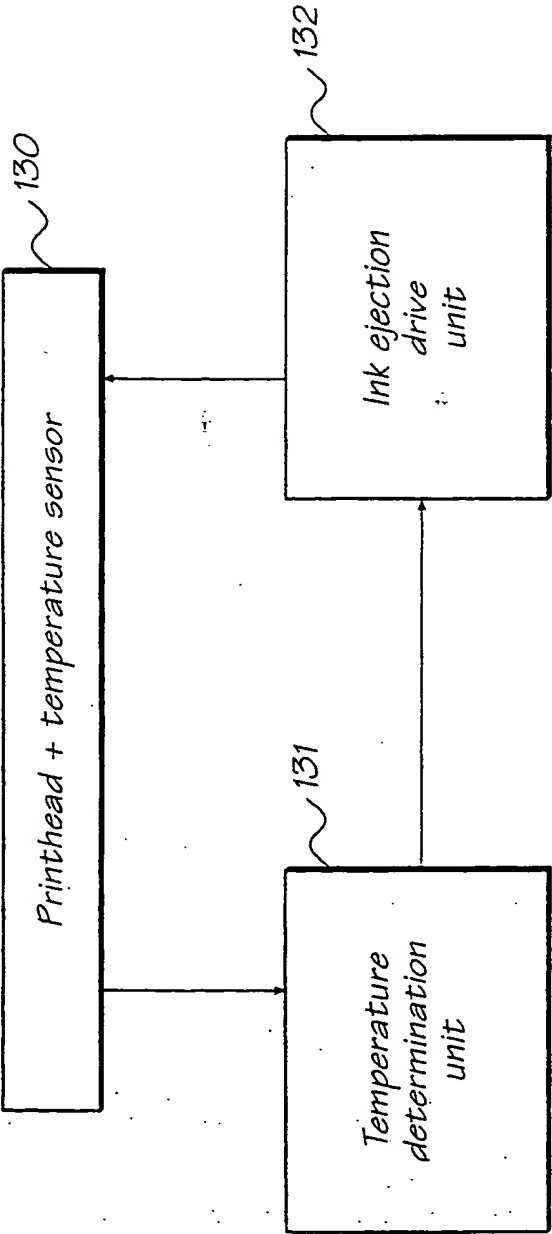


FIG. 17

FIG. 17

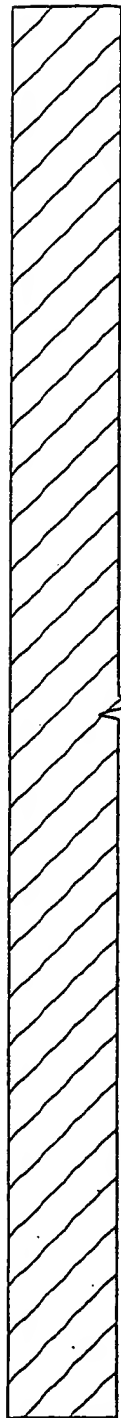
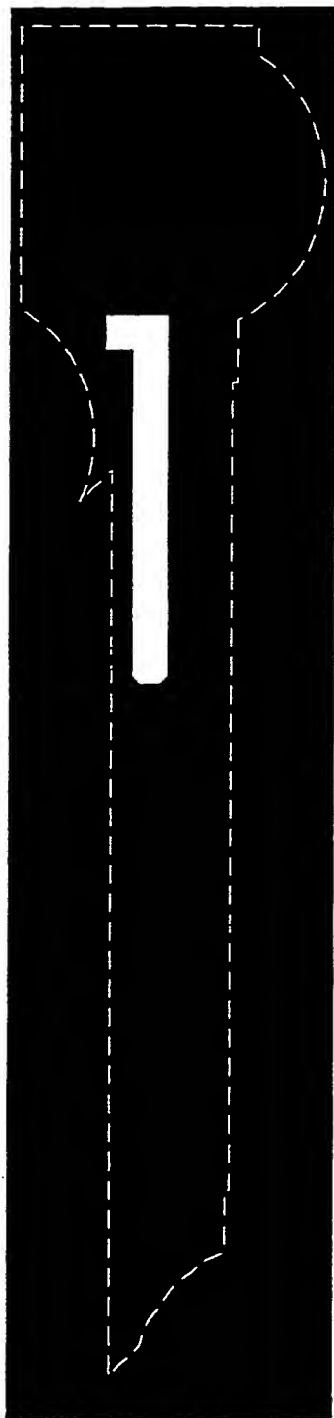


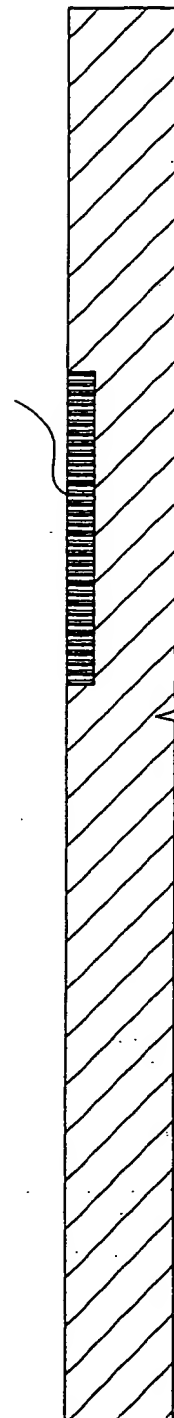
FIG. 18



N-Well mask

FIG. 19

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Implant N-Well

FIG. 20

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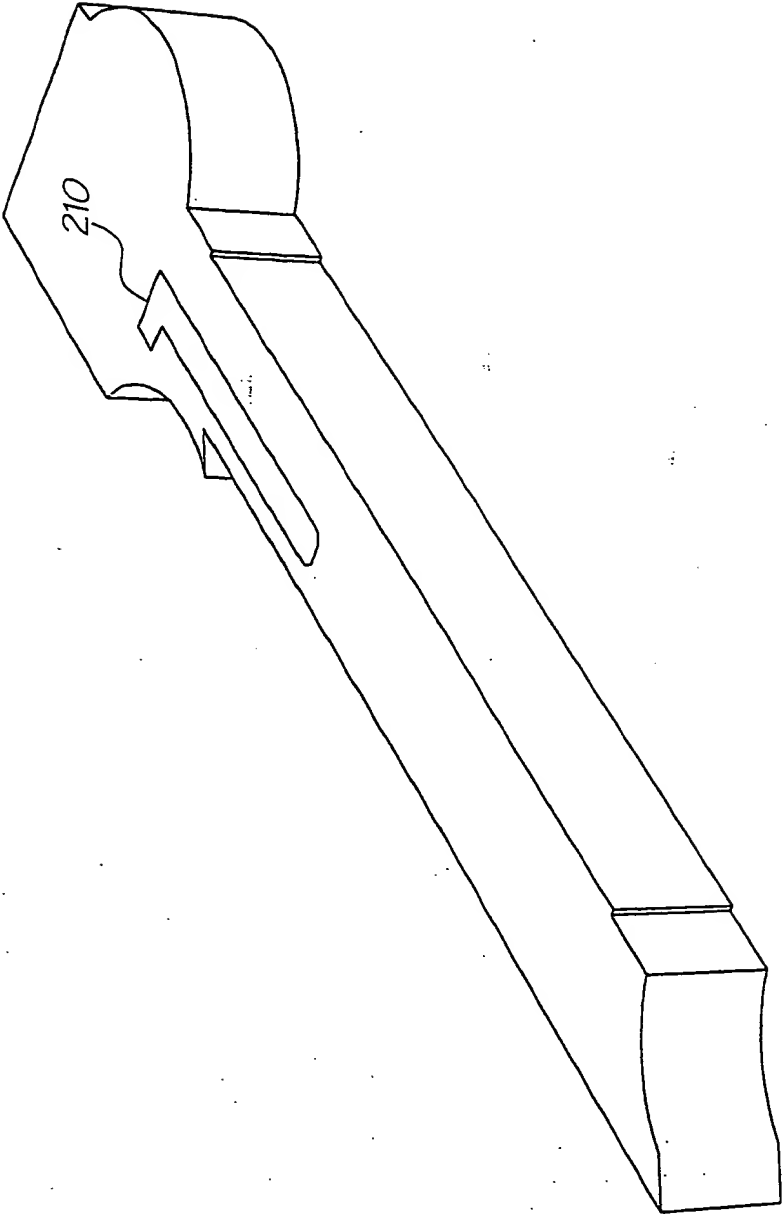
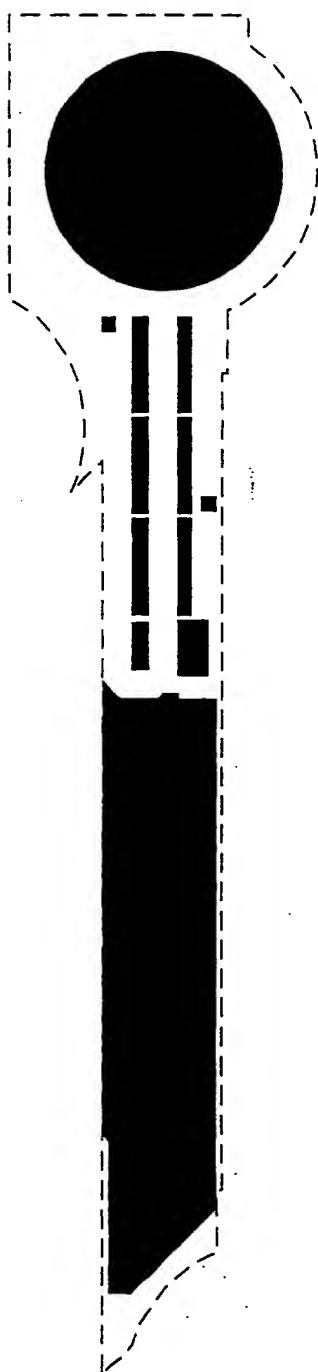


FIG. 21

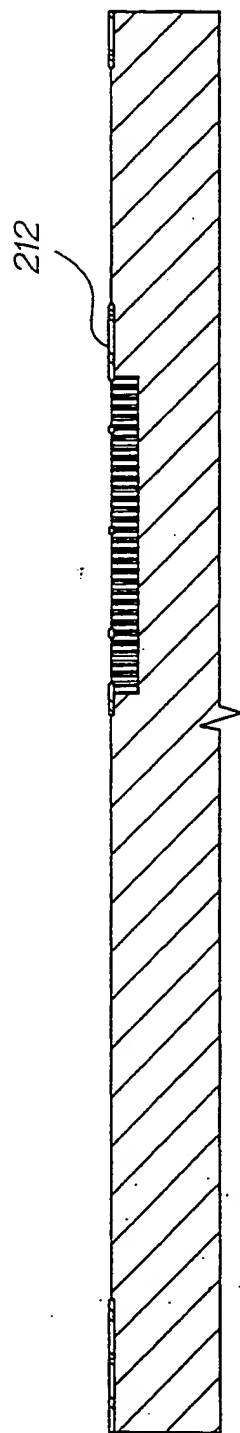
FIG. 21

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Active mask

FIG. 22



Grow field oxide

FIG. 23

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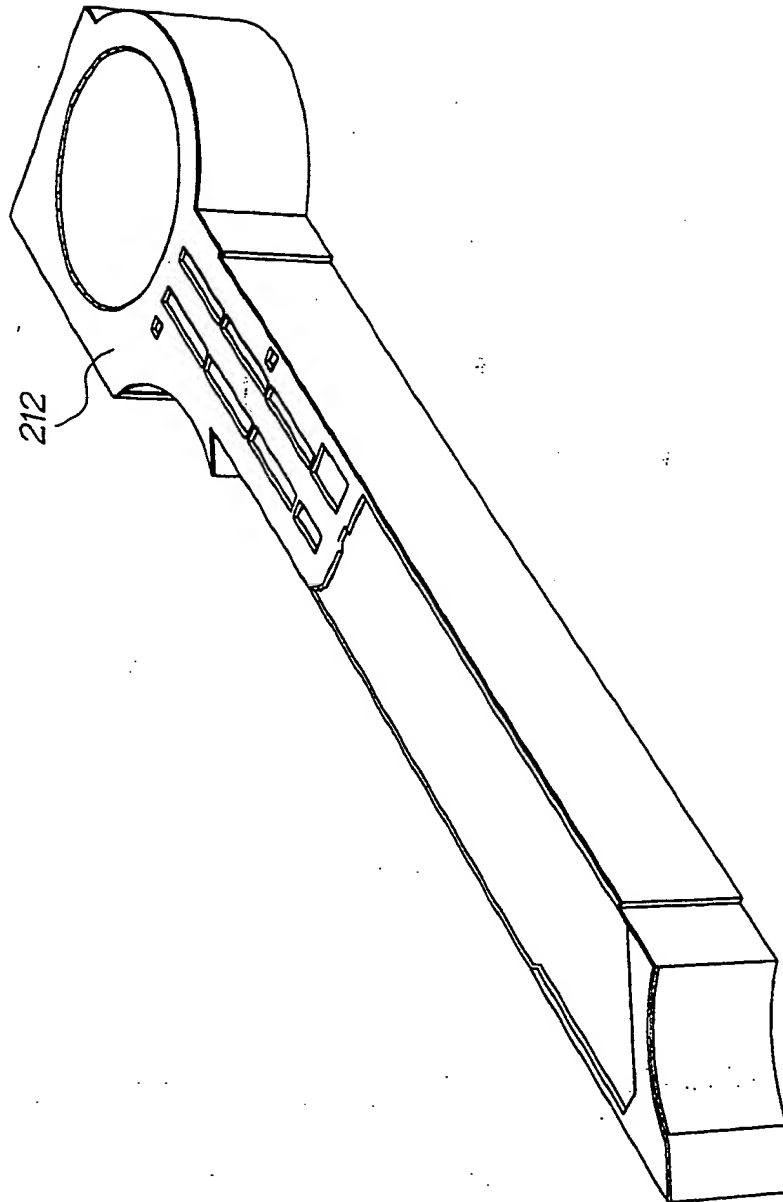
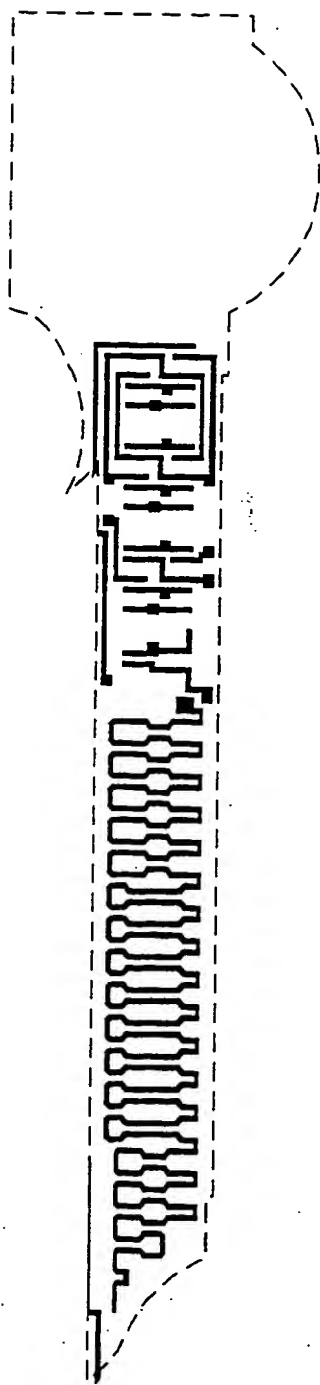


FIG. 24

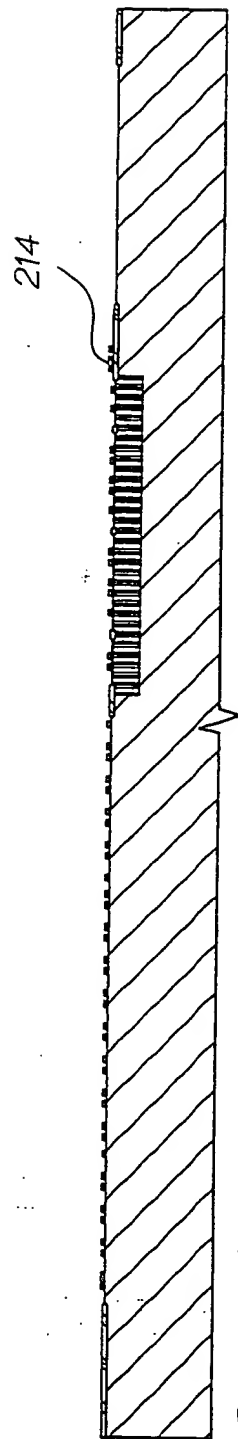
FIG. 24

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*Poly mask*

FIG. 25



*Deposit poly*

FIG. 26

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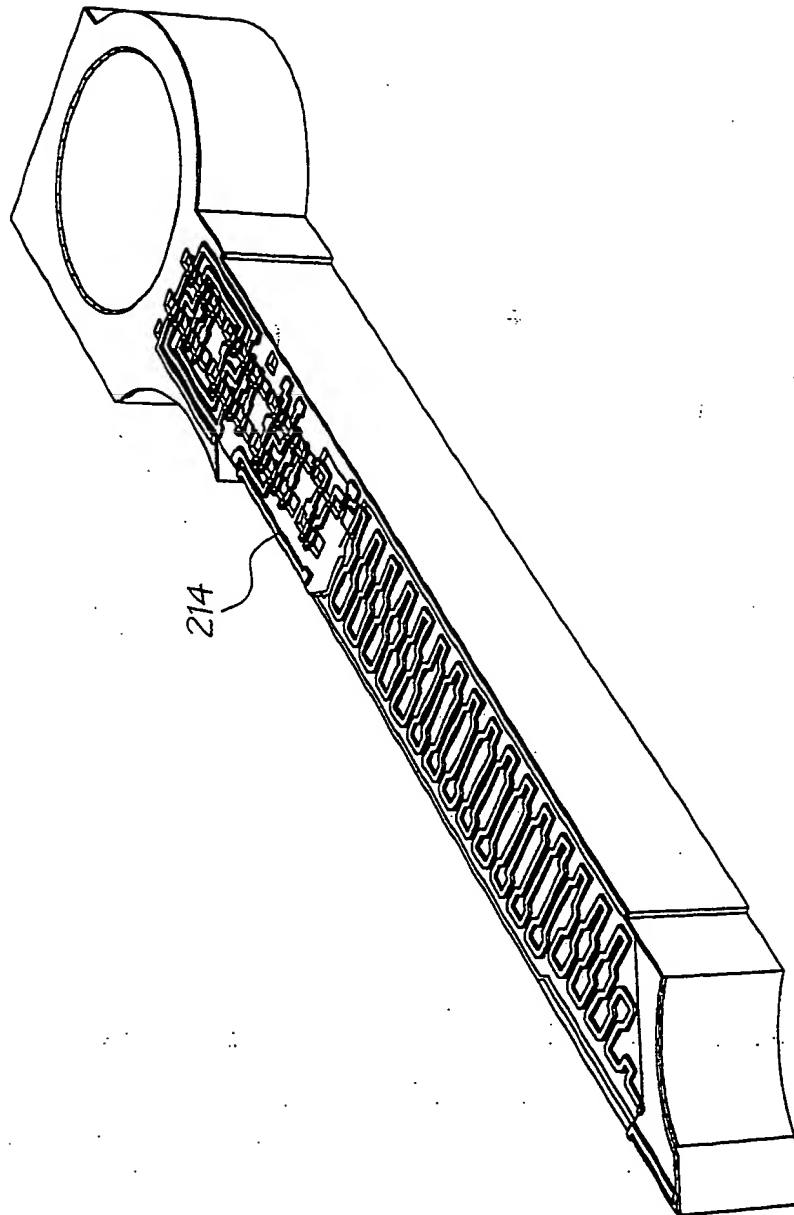


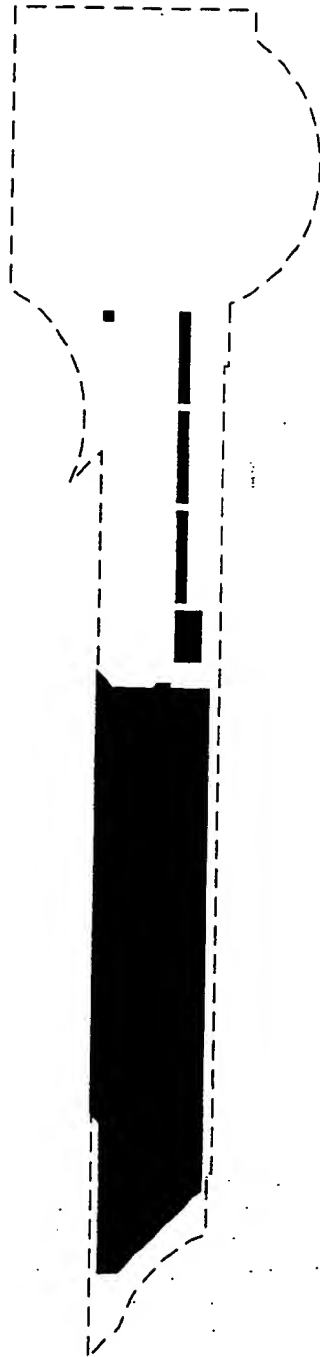
FIG. 27

FIG. 27



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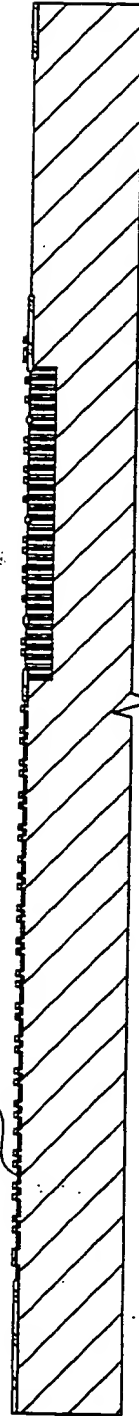
FIG. 28



*n+ mask*

FIG. 28

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*n+ implant*

FIG. 29

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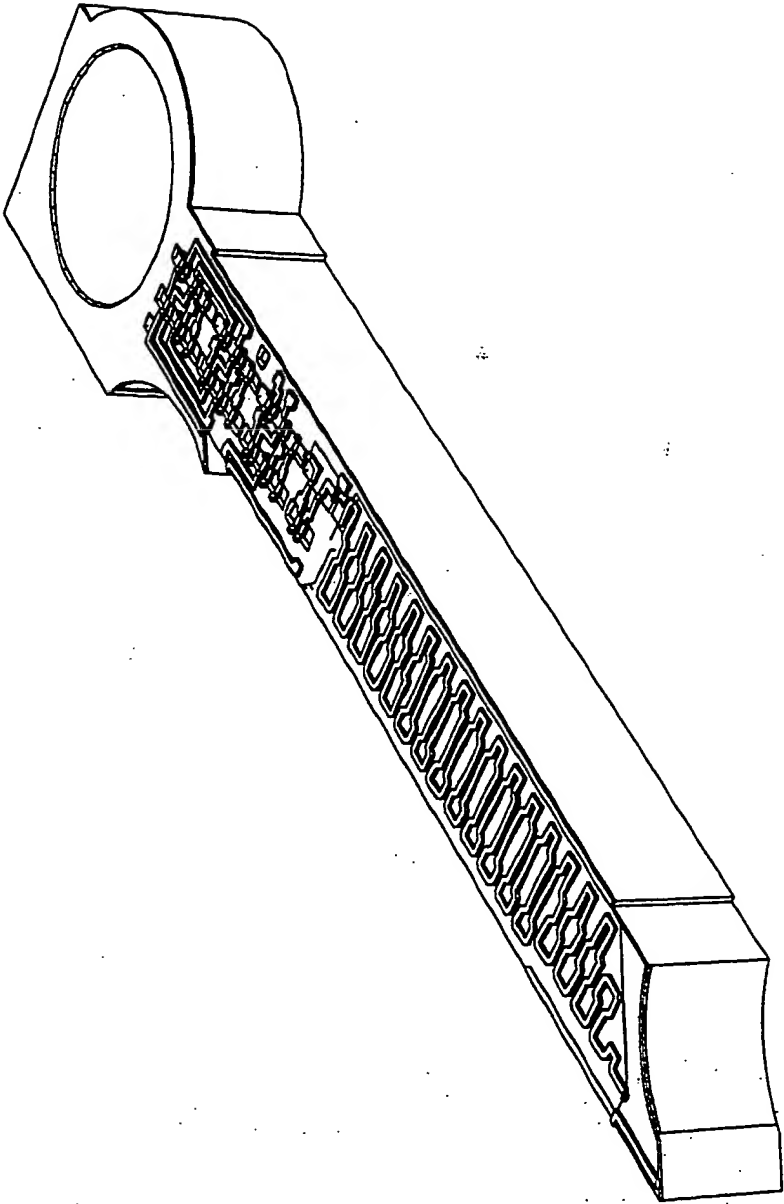


FIG. 30

FIG. 30

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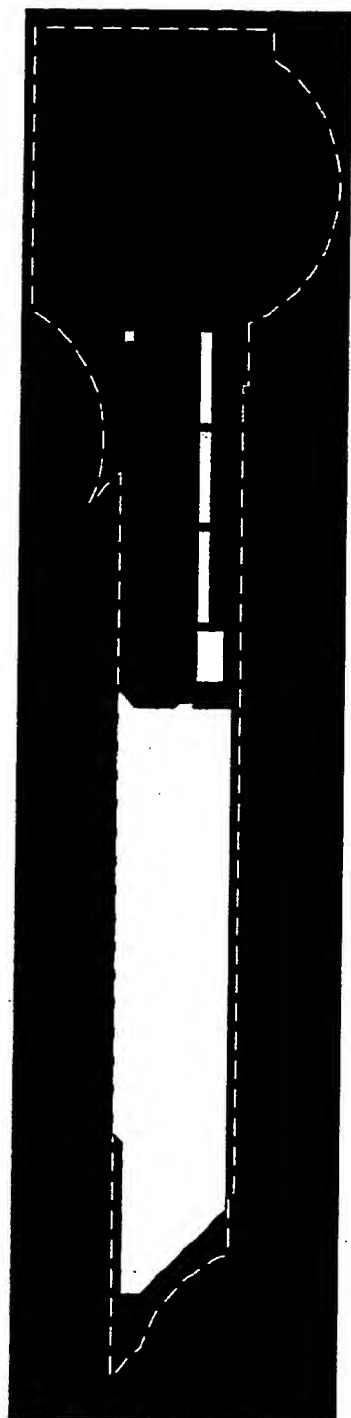


FIG. 31

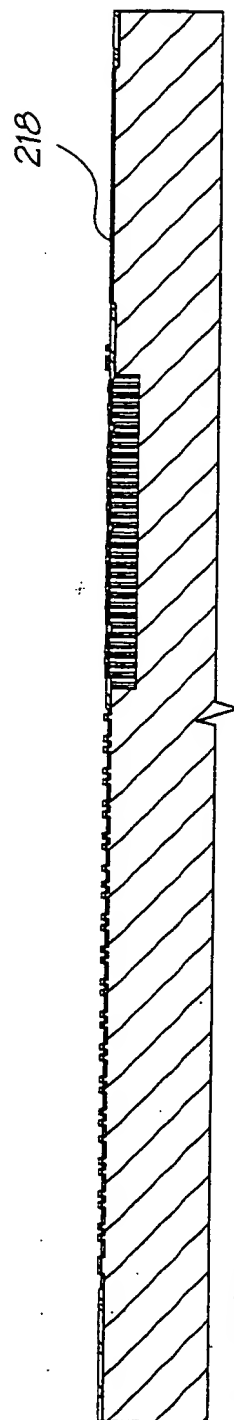


FIG. 32

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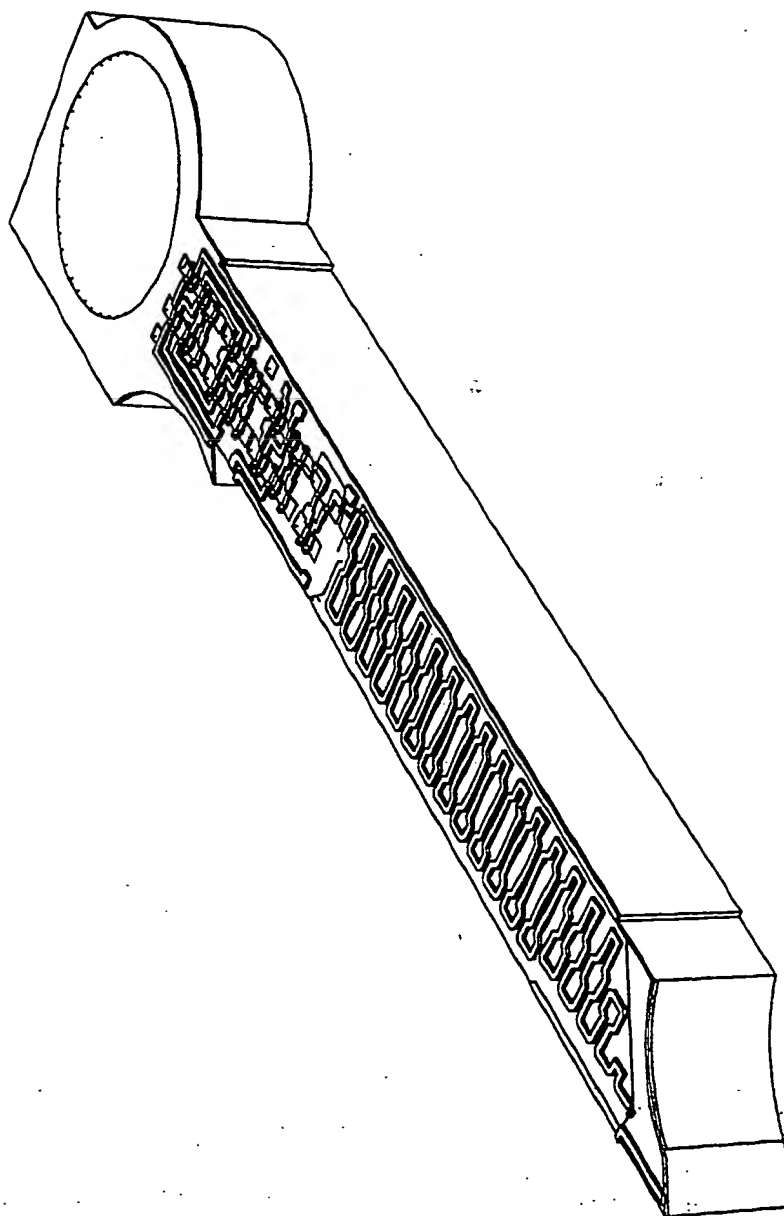


FIG. 33

FIG. 33

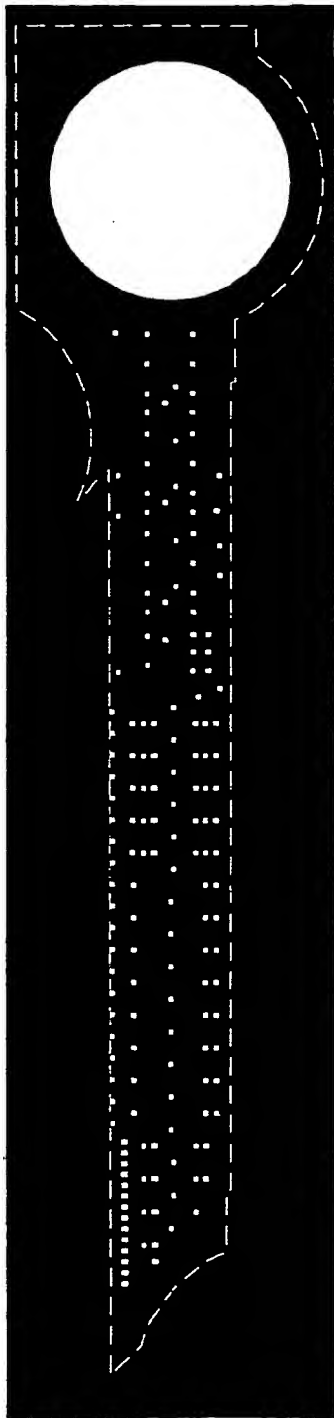


FIG. 34

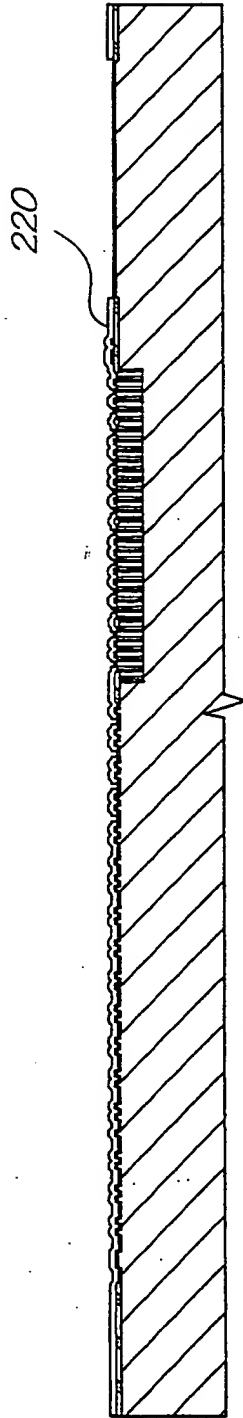


FIG. 35

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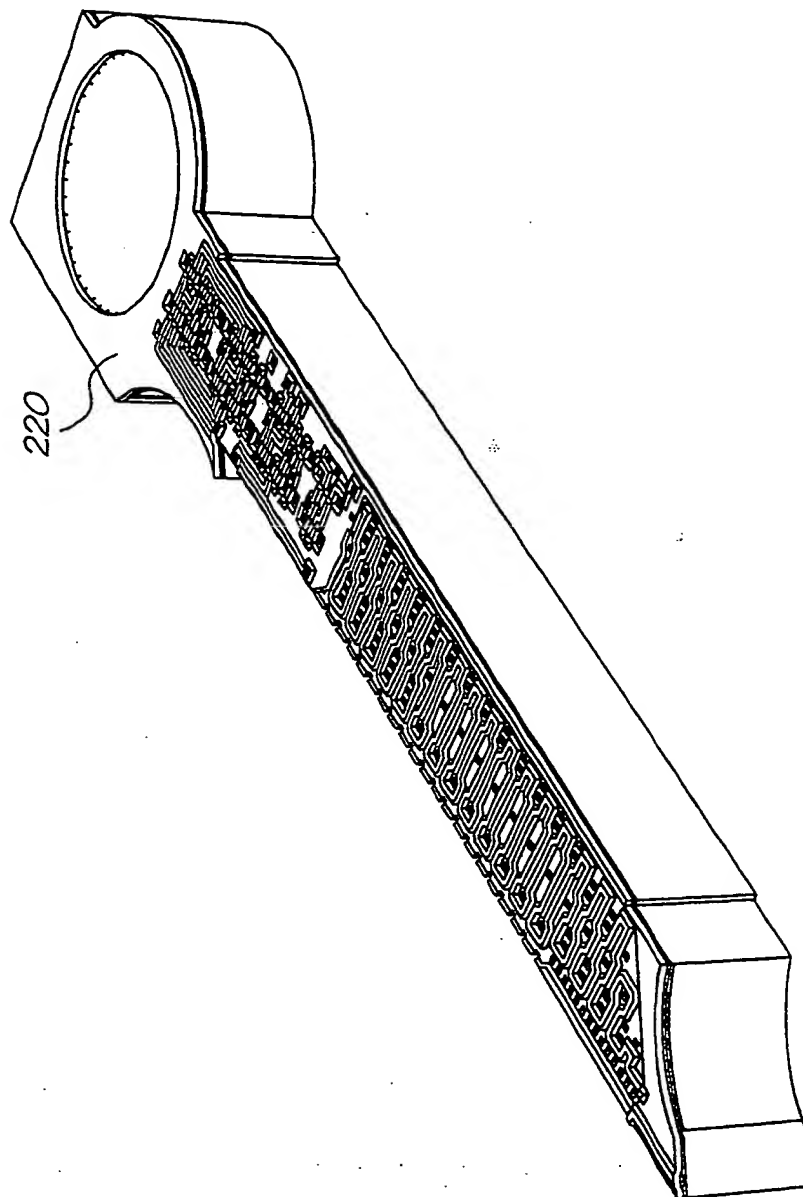
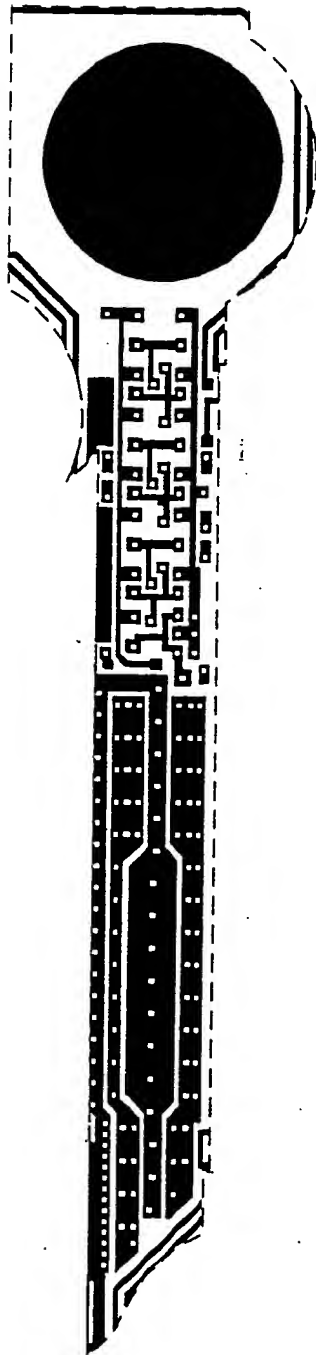


FIG. 36

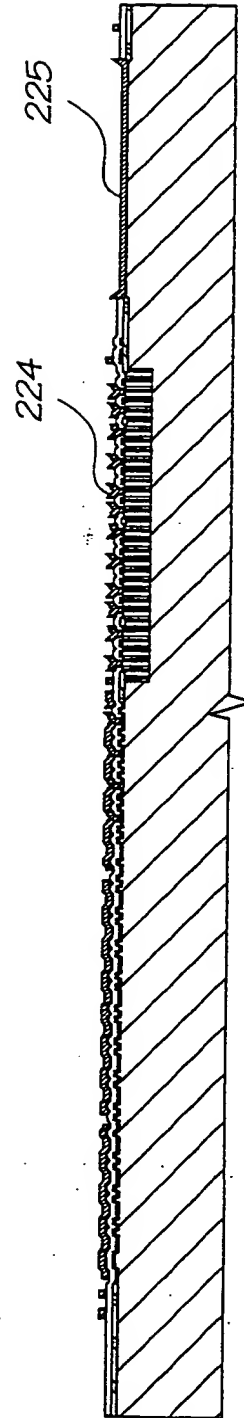
FIG. 36

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Metal 1 mask

FIG. 37



Deposit Metal 1

FIG. 38

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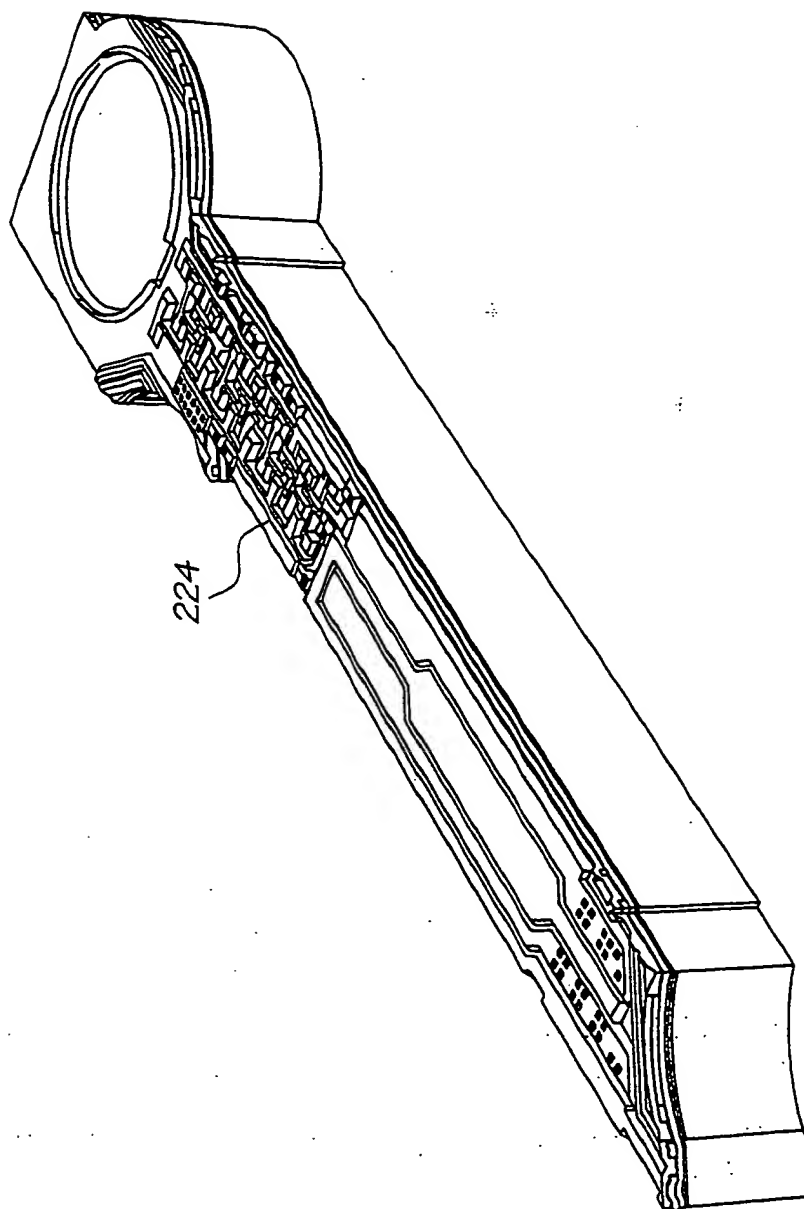
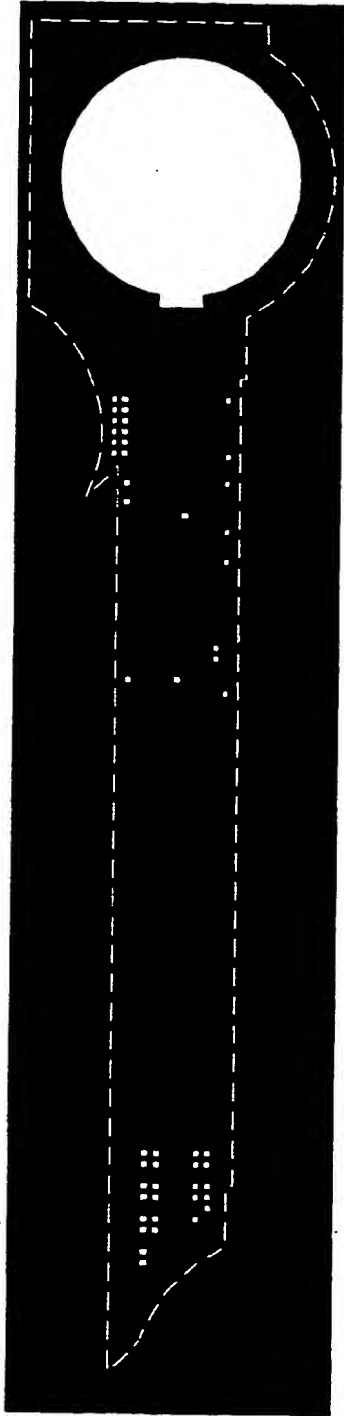


FIG. 39

FIG. 39



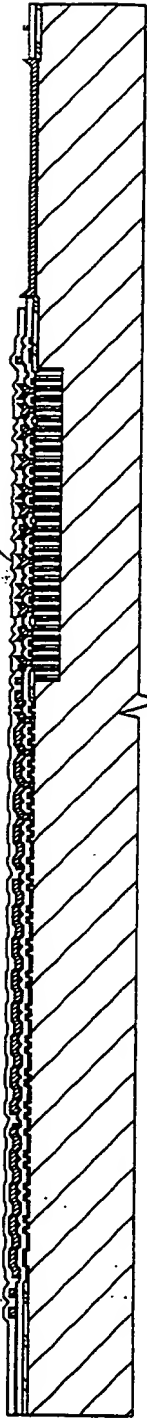
FIG. 40



Via 1 mask

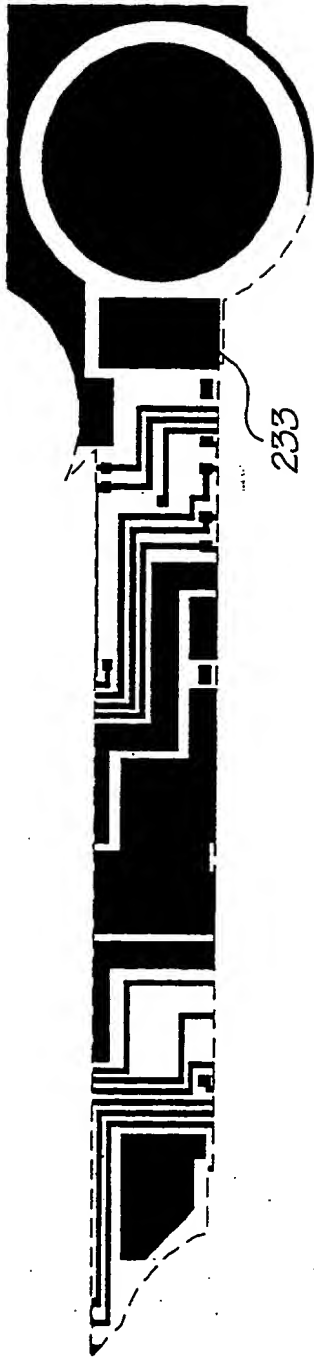
FIG. 40

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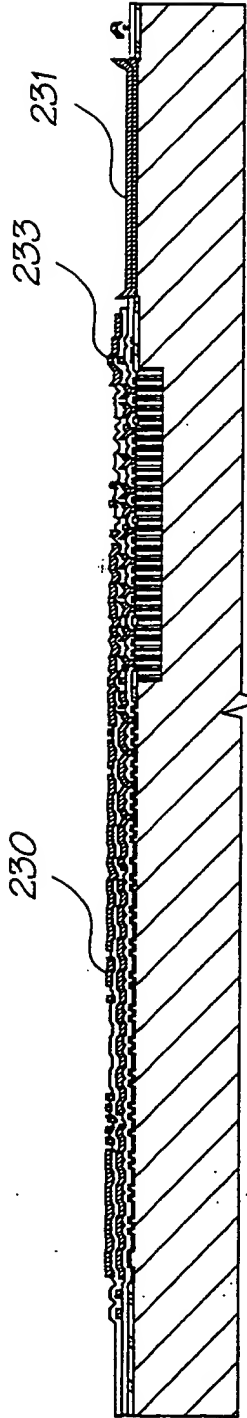
Deposit ILD 2, etch vias

FIG. 41



Metal 2 mask

FIG. 42



Deposit metal 2

FIG. 43

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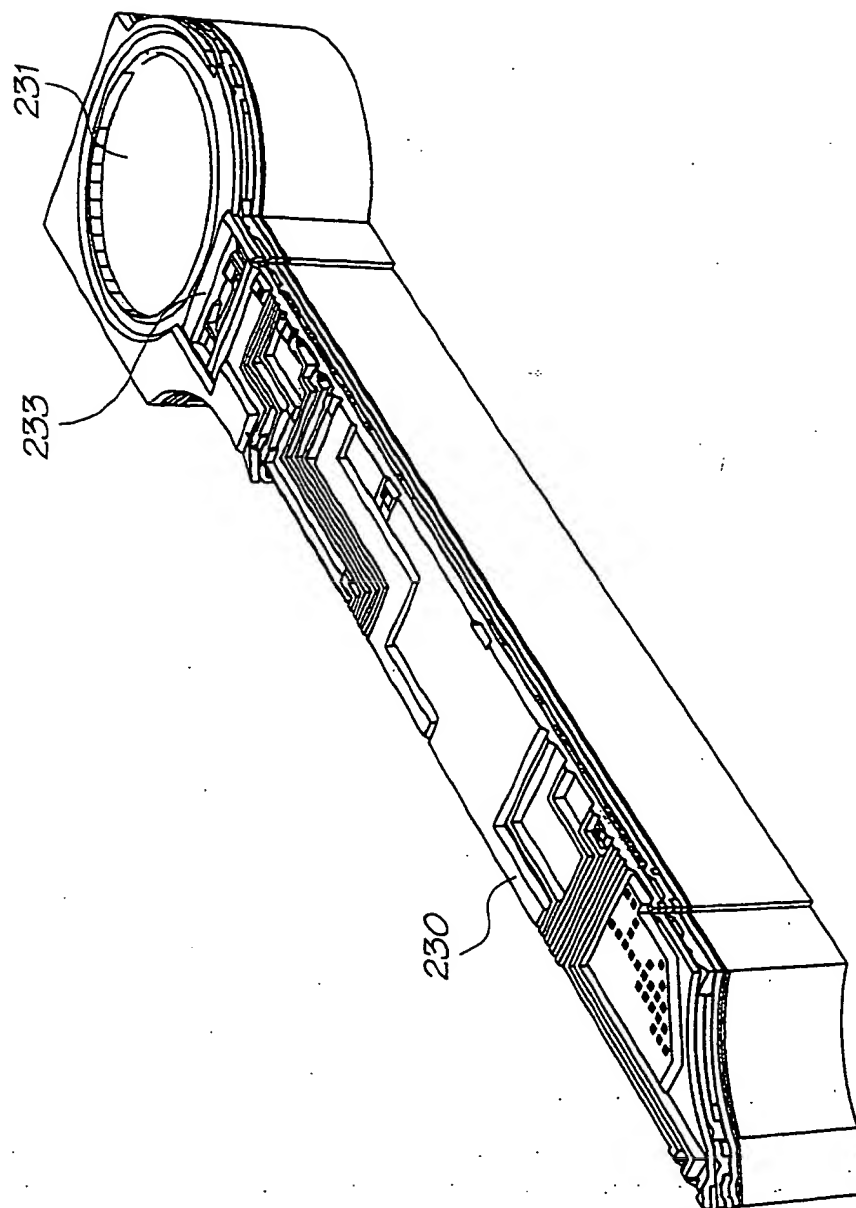
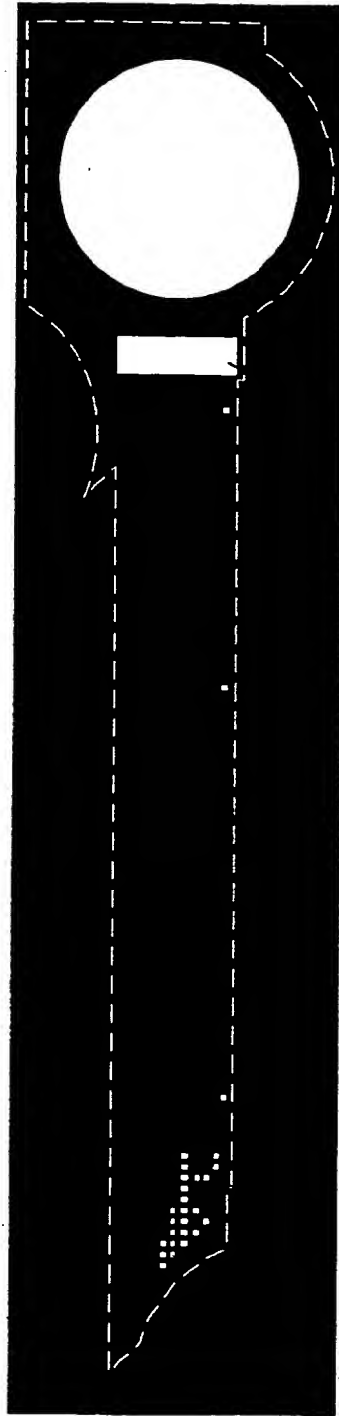


FIG. 44

FIG. 44

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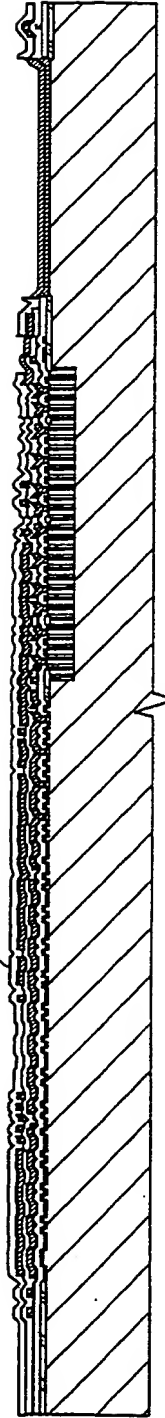
FIG. 45



Via 2 mask

FIG. 45

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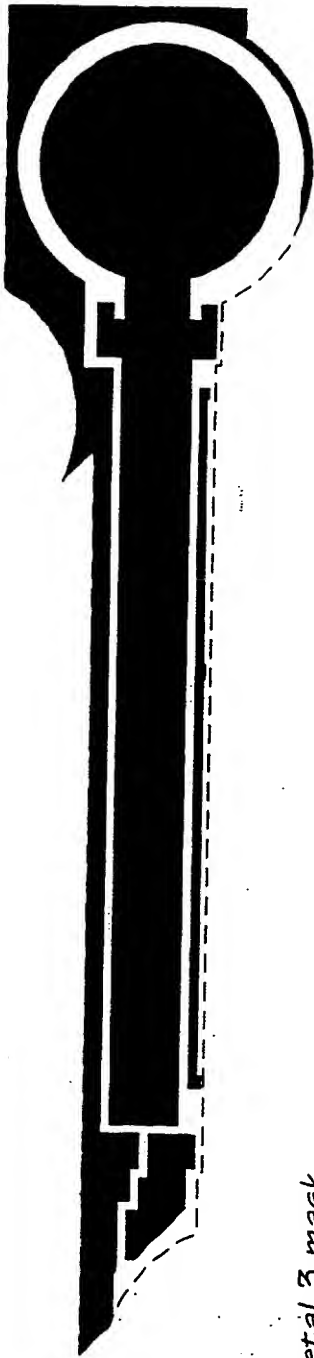


Deposit ILD 3, etch vias

FIG. 46

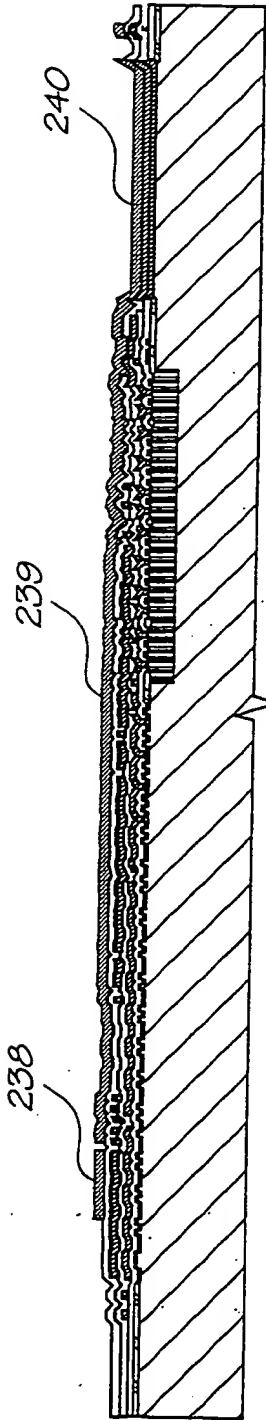
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FIG. 47



Metal 3 mask

FIG. 47



Deposit metal 3

FIG. 48

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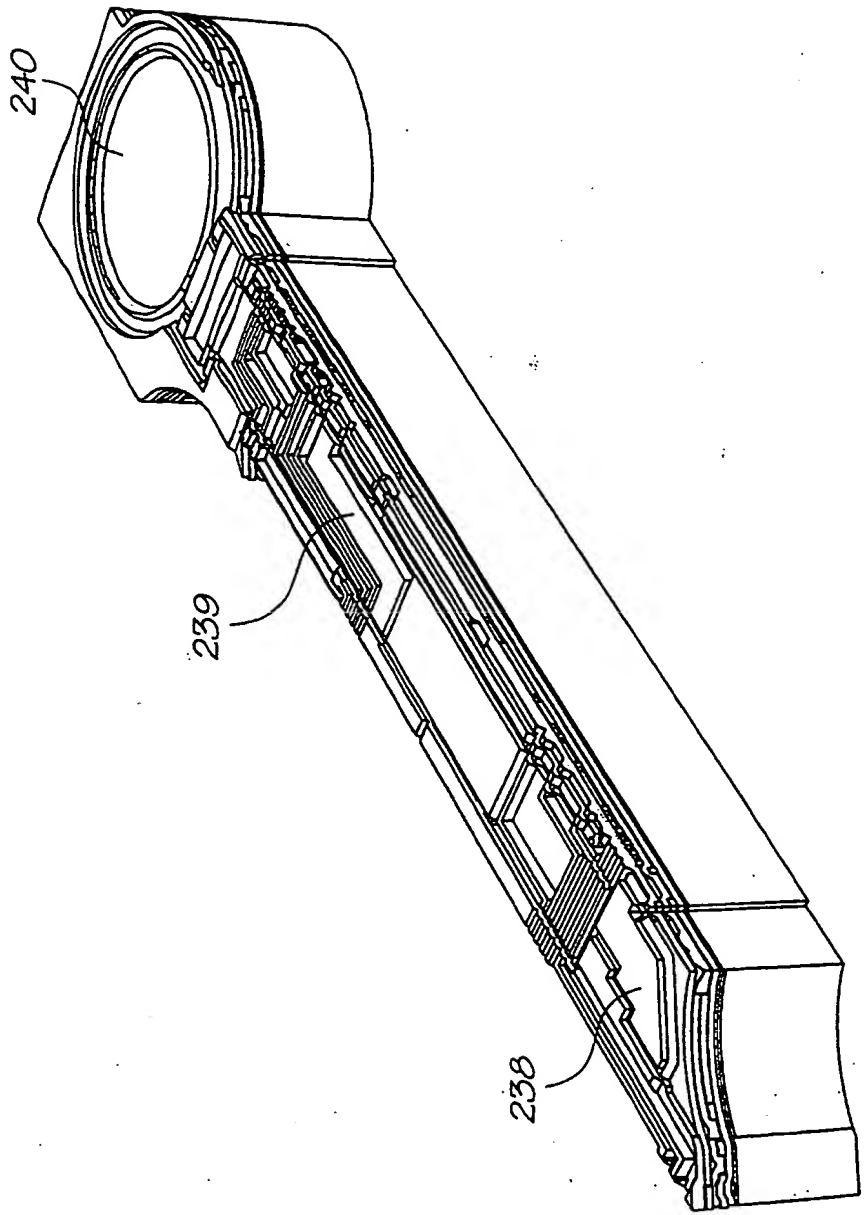
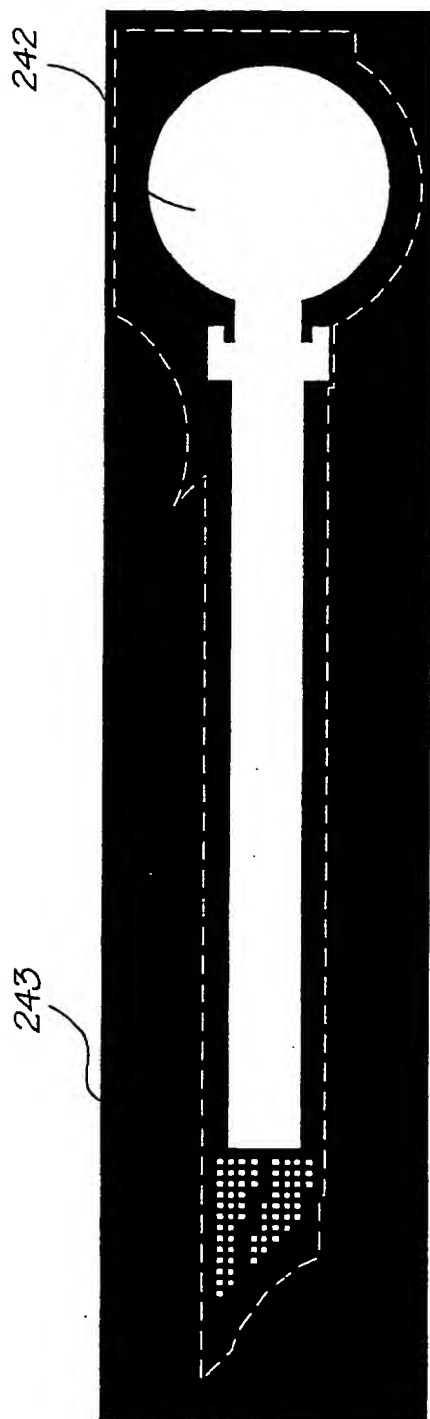


FIG. 49

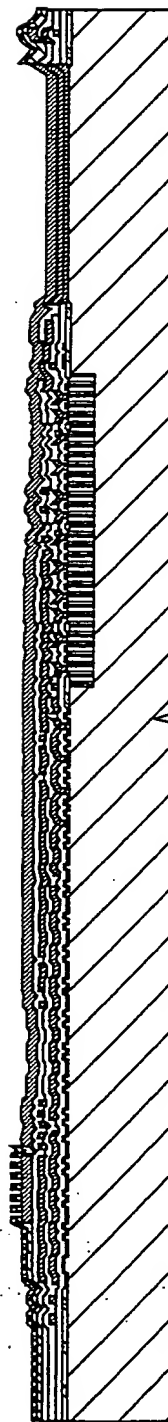
FIG. 49

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Via 3 / Passivation mask

FIG. 50



Deposit passivation oxide & nitride, etch vias

FIG. 51

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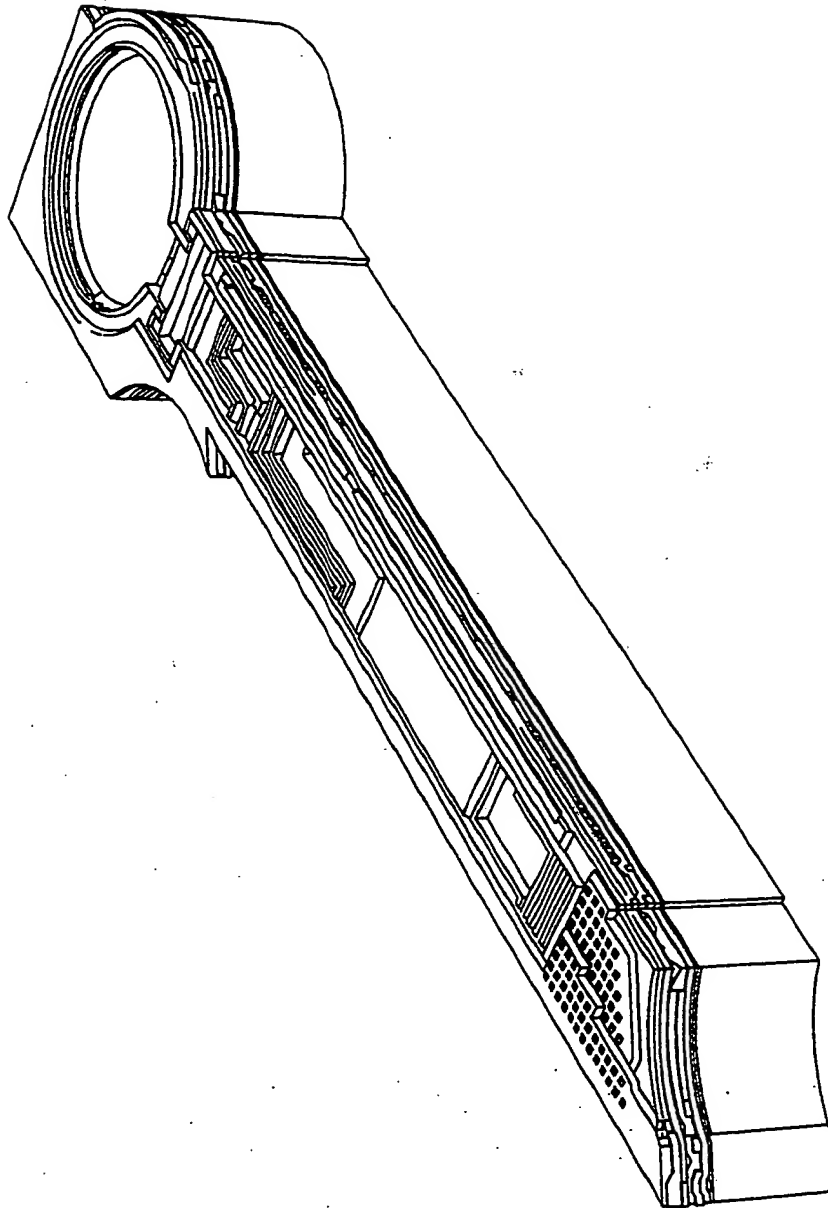
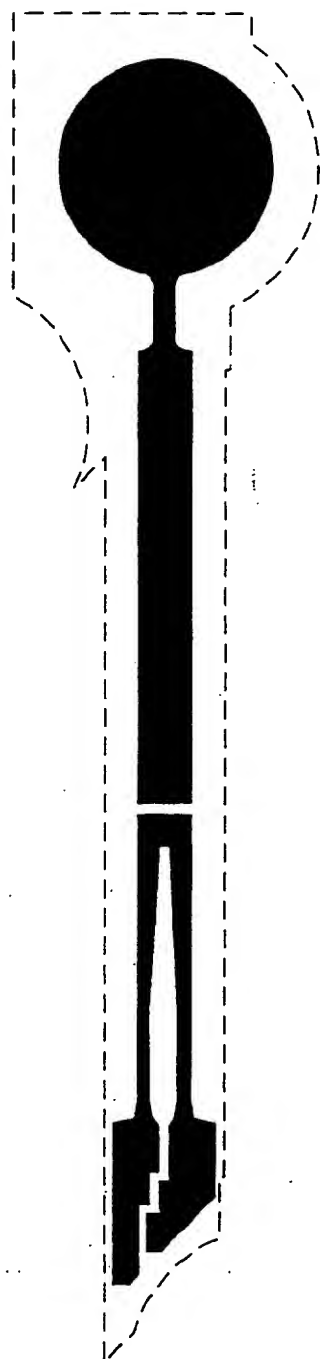


FIG. 52

FIG. 52

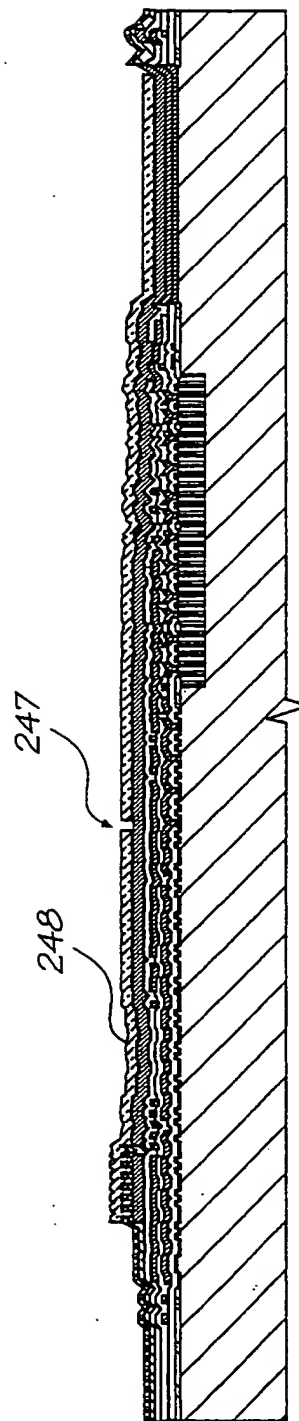


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Heater mask

FIG. 53



Deposit heater TiN

FIG. 54

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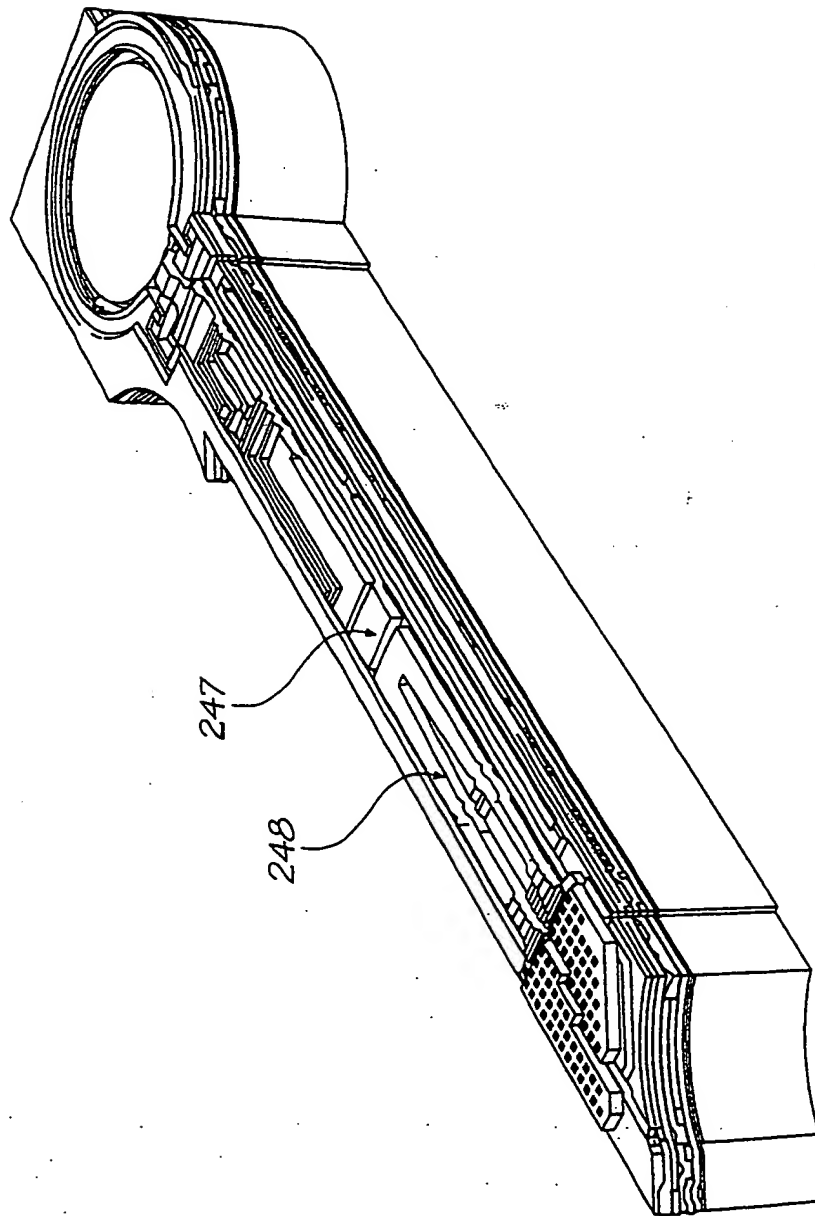
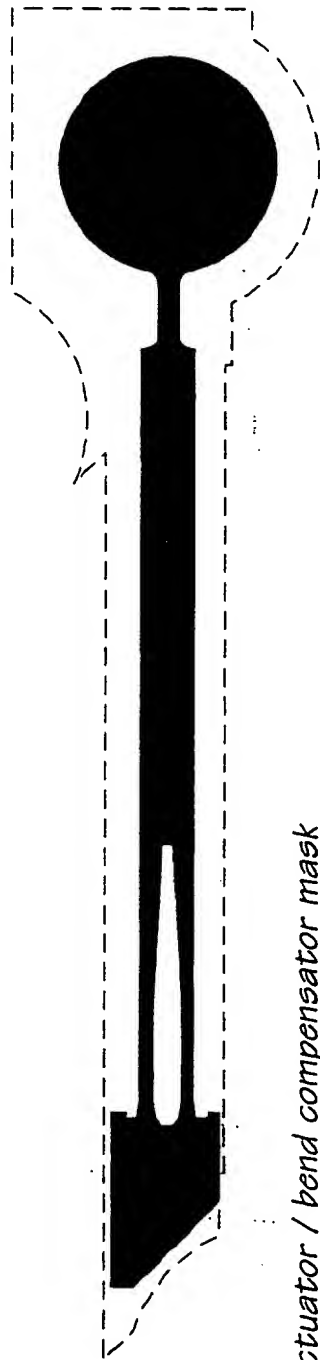
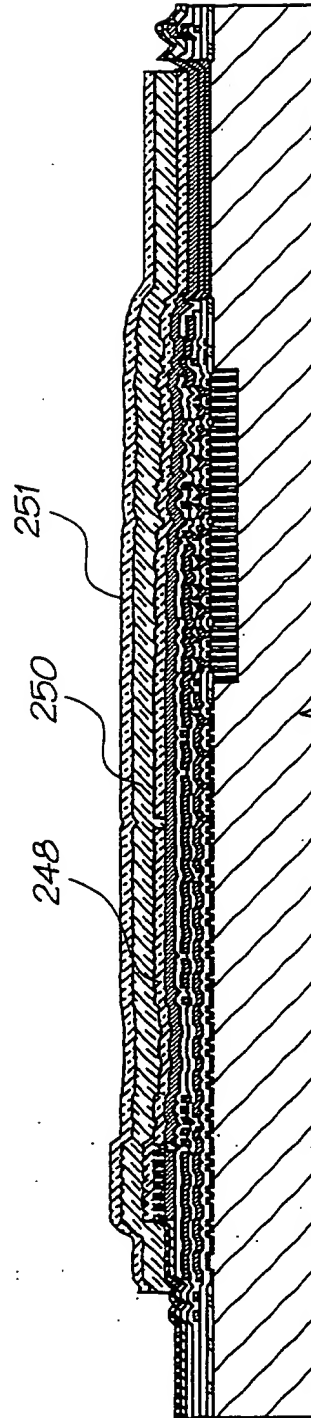


FIG. 55



Actuator / bend compensator mask

FIG. 56



Deposit actuator glass and bend compensator TiN, etch together

FIG. 57

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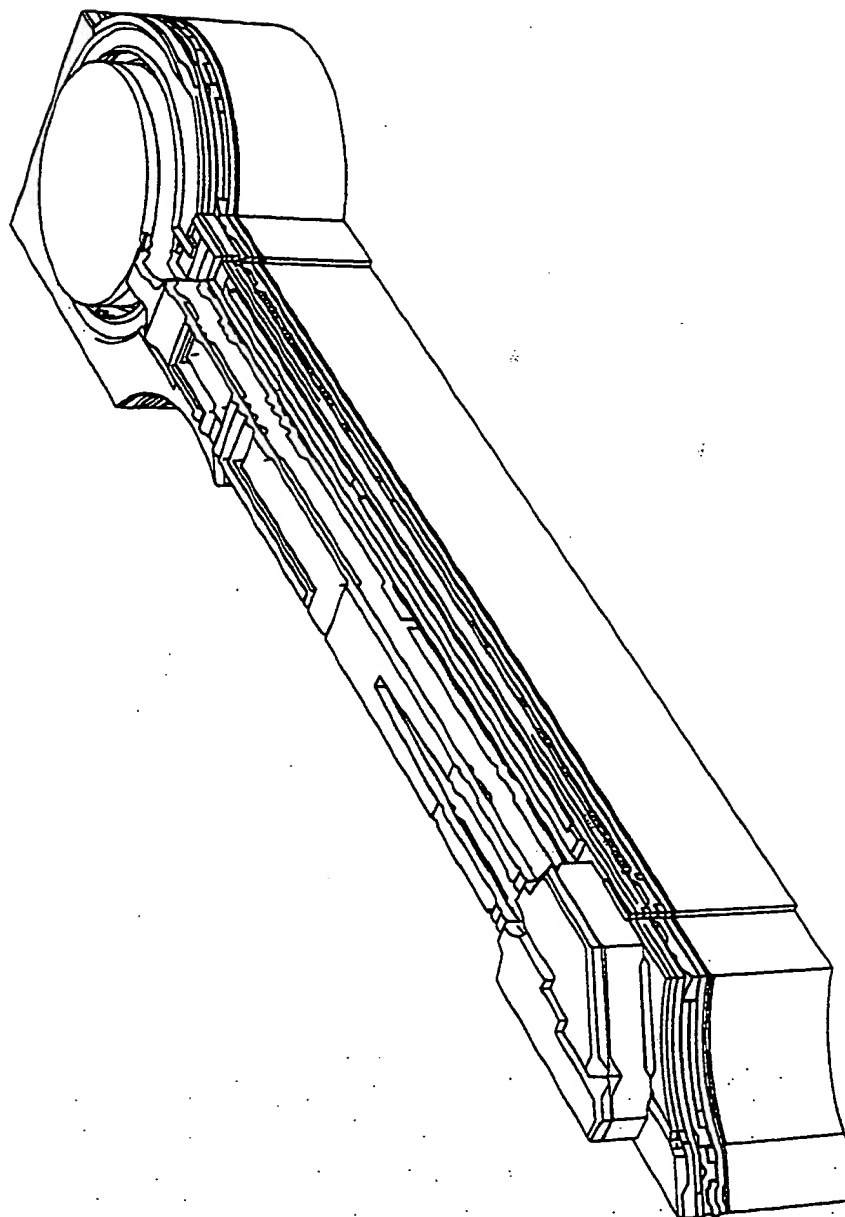


FIG. 58

FIG. 58

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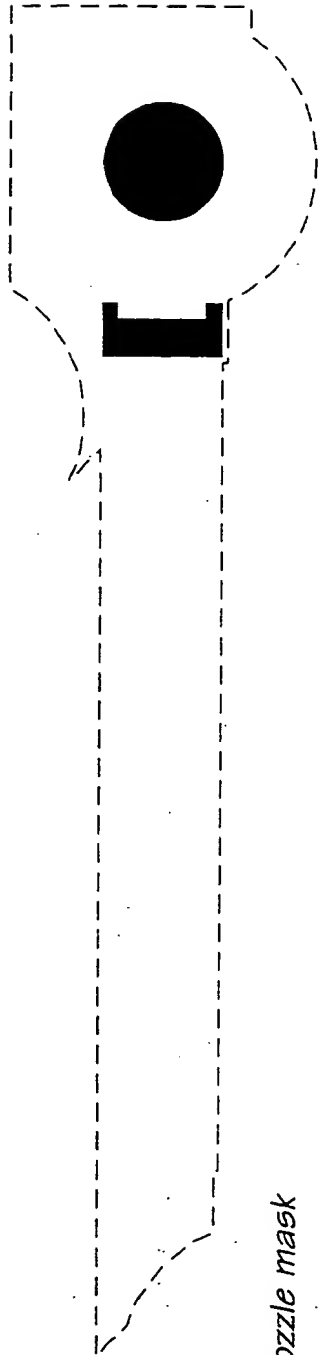


FIG. 59

Nozzle mask

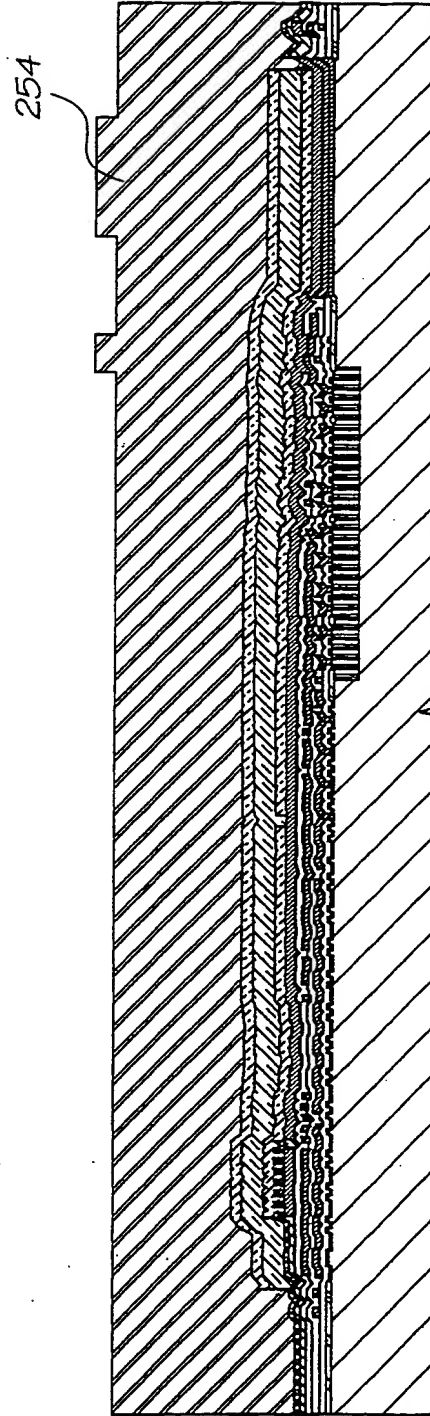


FIG. 60

Deposit sacrificial layer, etch nozzles

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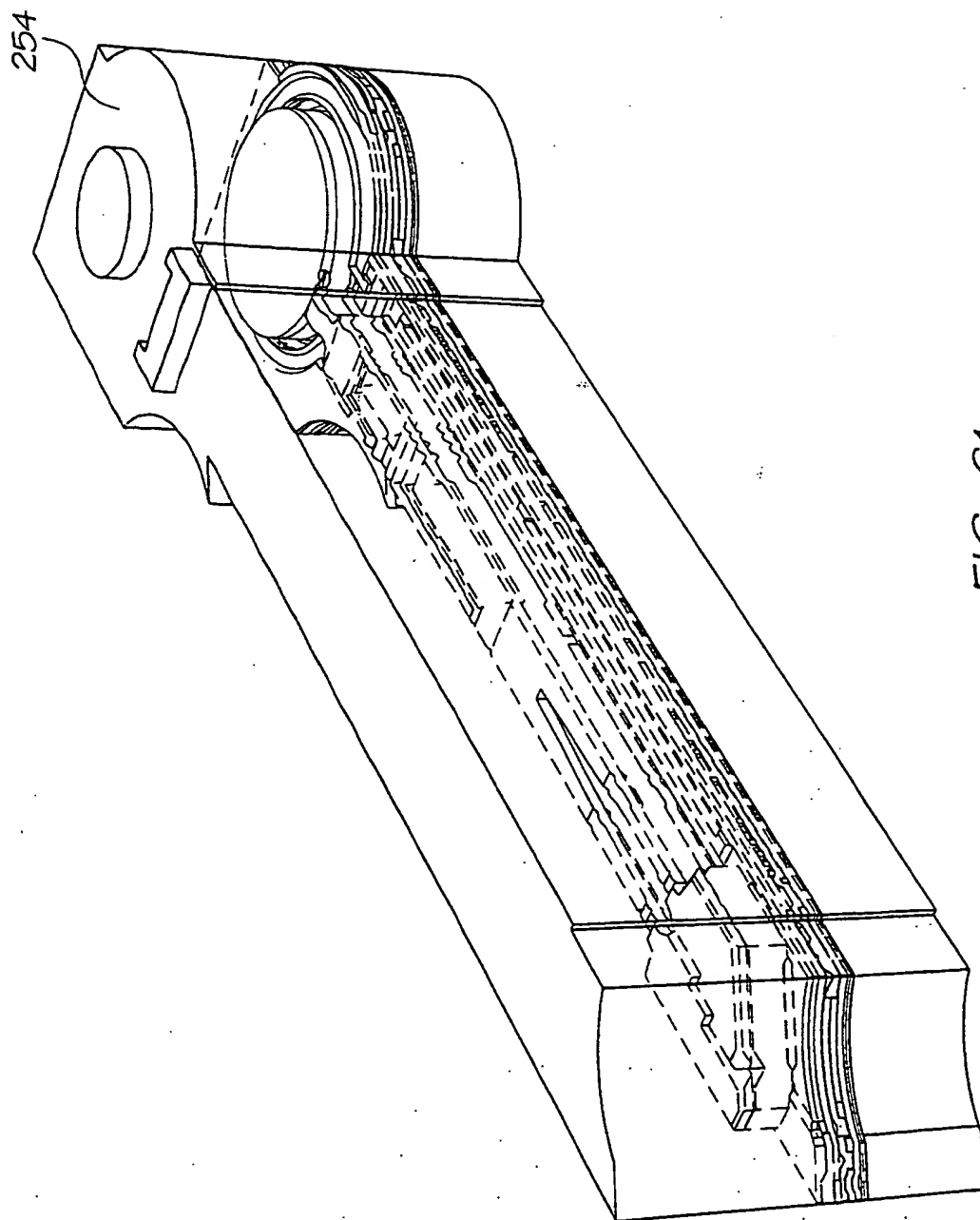
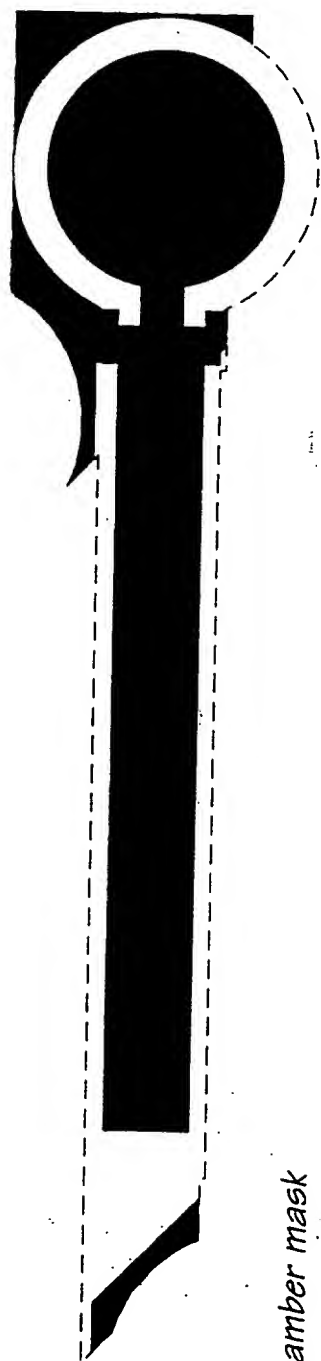


FIG. 61

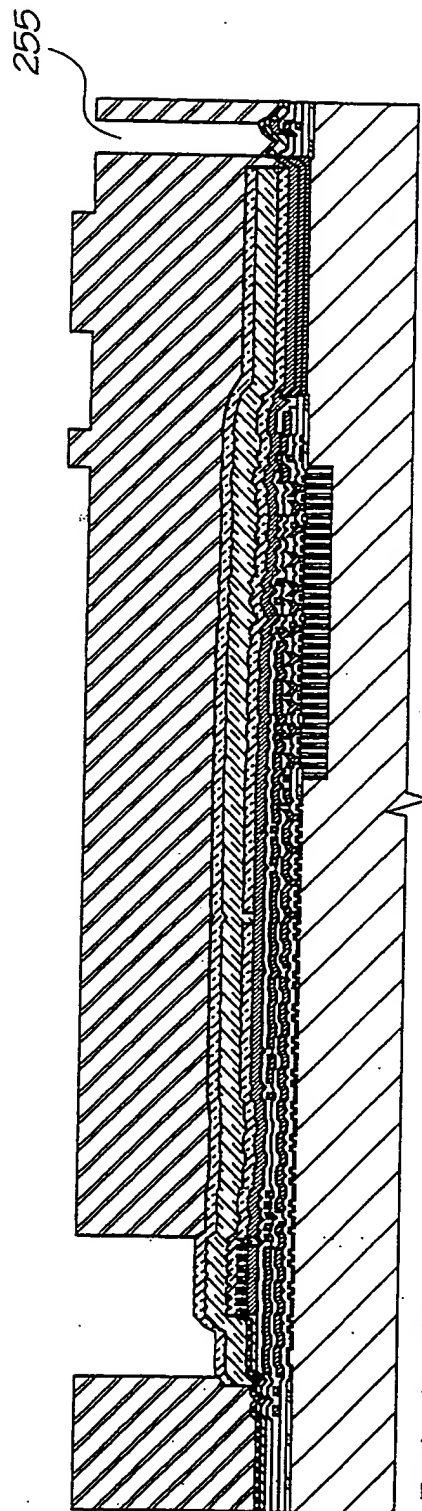
FIG. 61

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Chamber mask

FIG. 62



Etch chambers in sacrificial layer

FIG. 63

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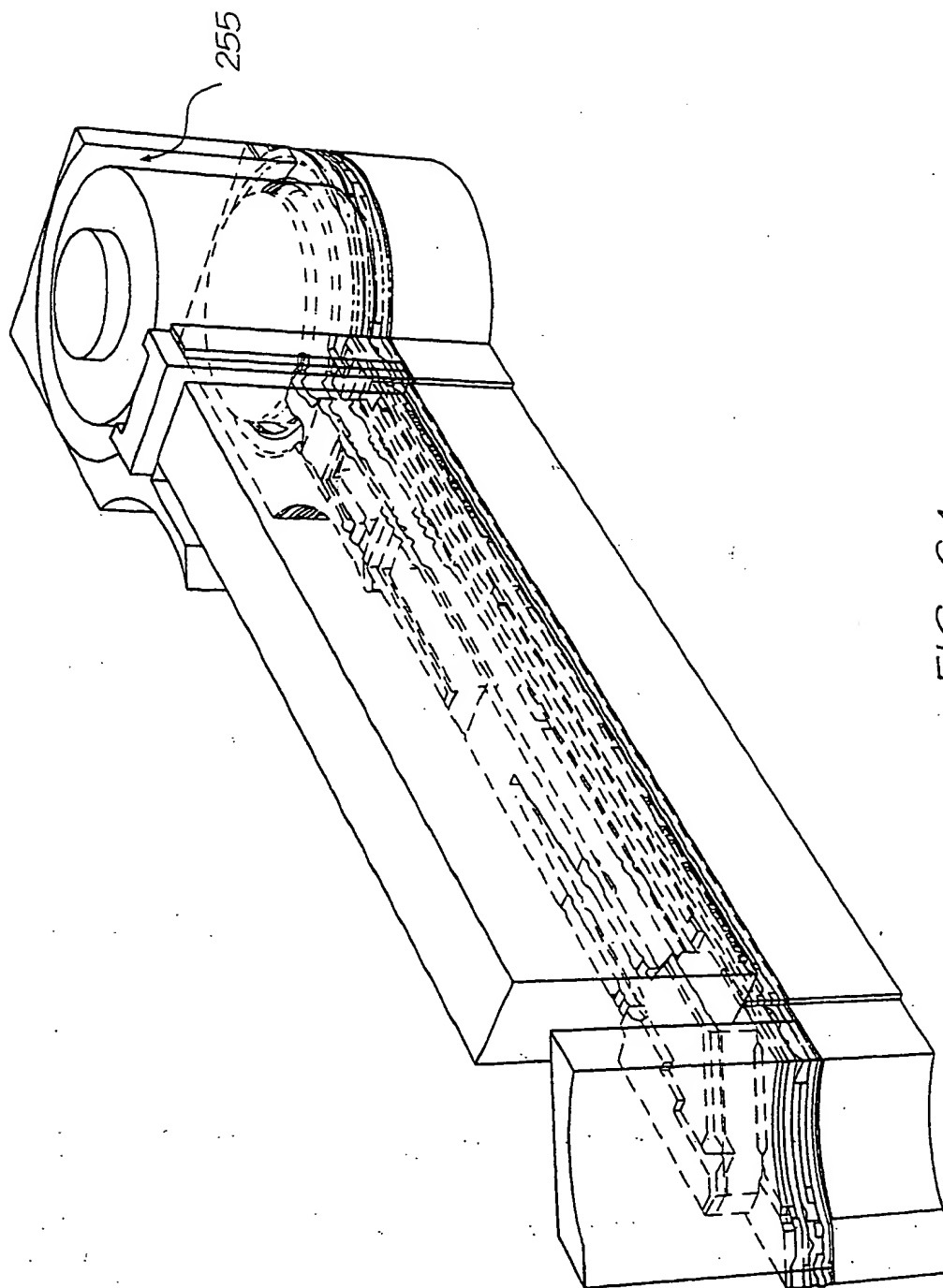
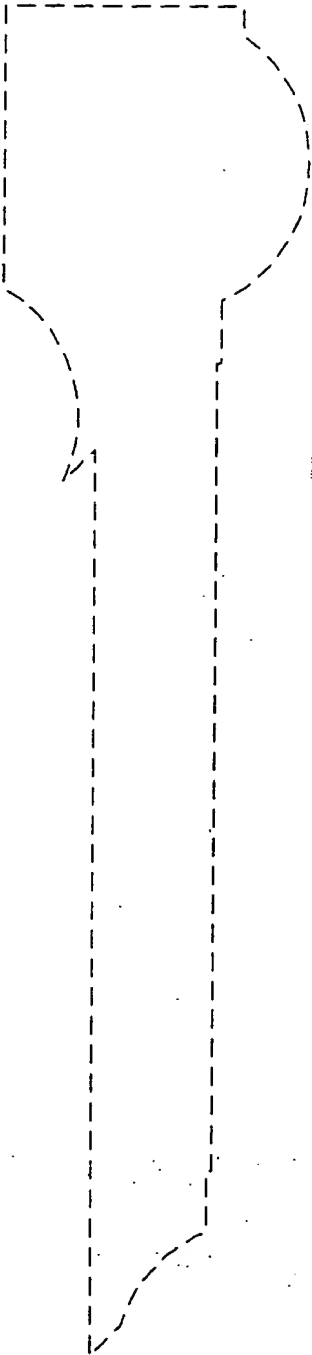


FIG. 64

FIG. 64

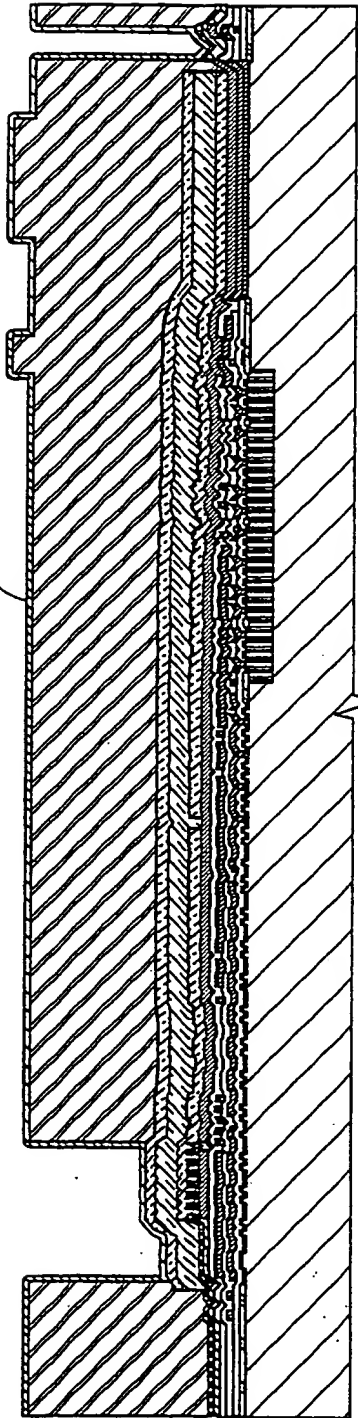


FIG. 65



No mask

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Deposit chamber walls

FIG. 65

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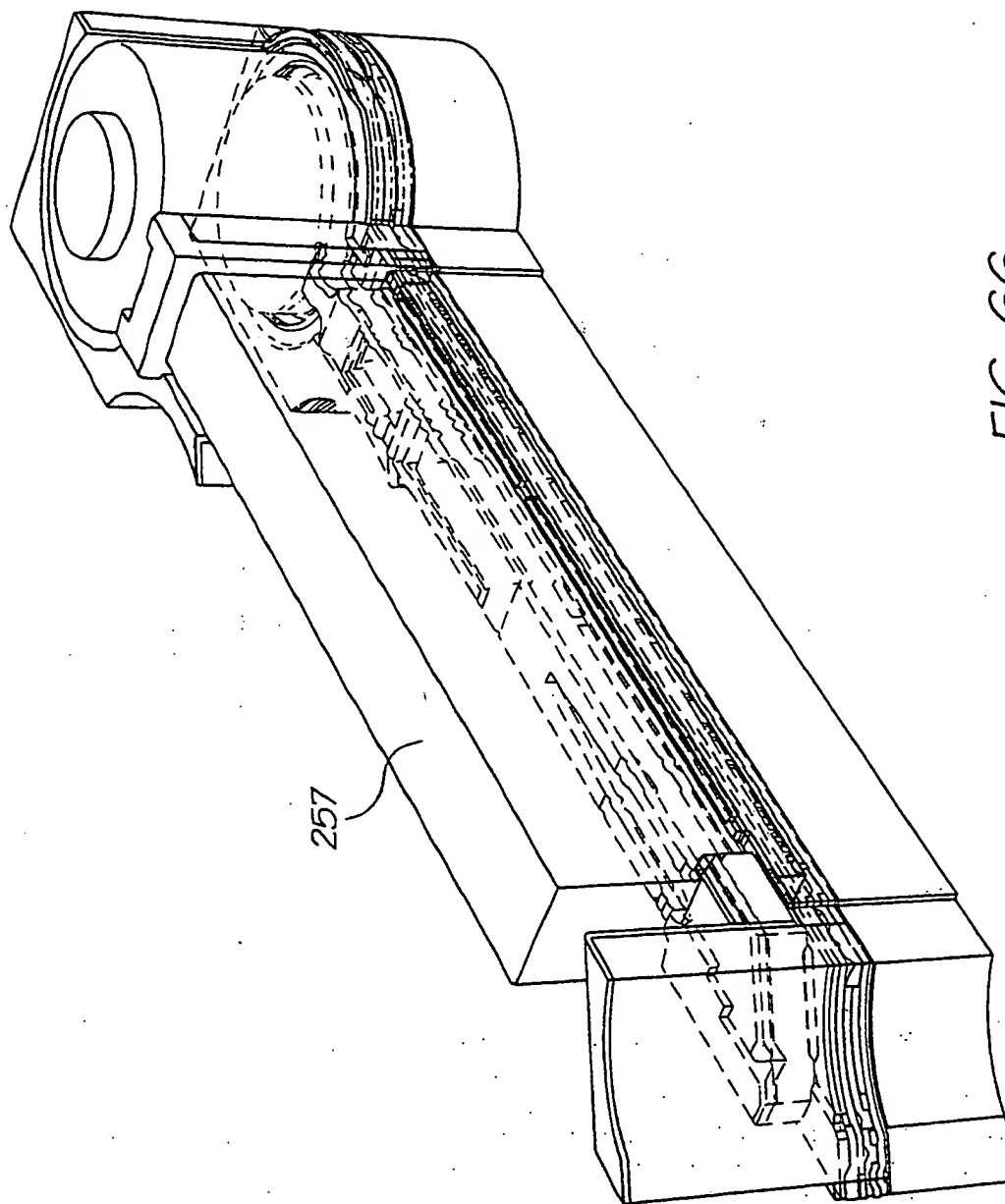
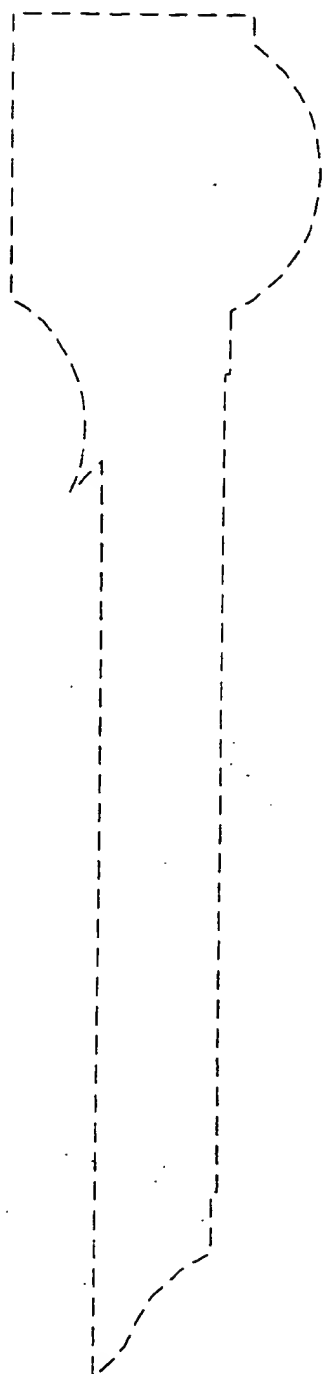


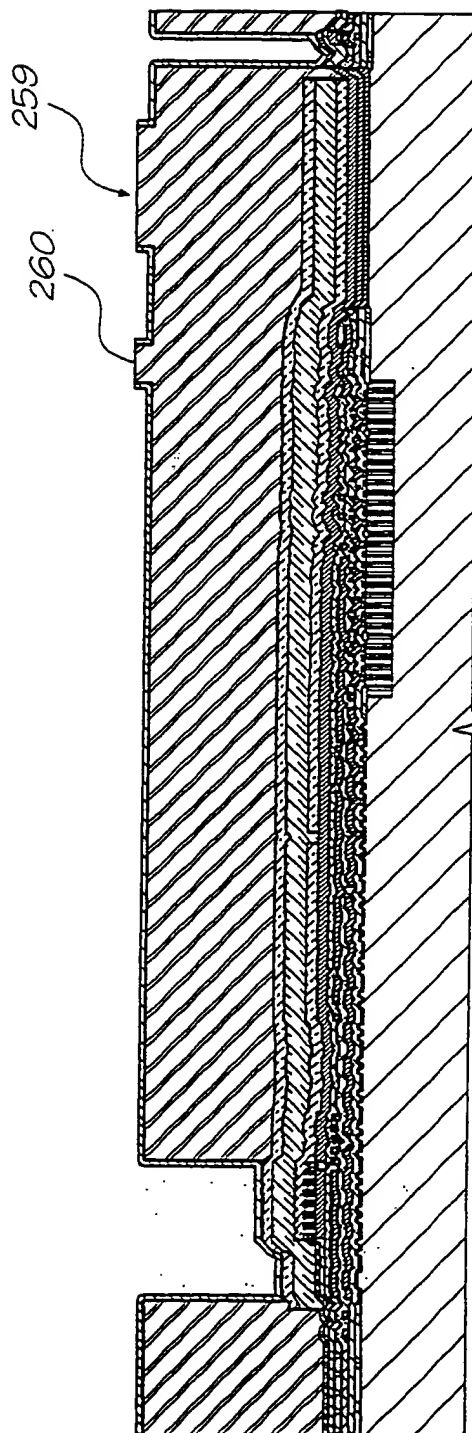
FIG. 66

FIG. 66

FIG. 67



No mask



Form self-aligned nozzles using CMP

FIG. 67

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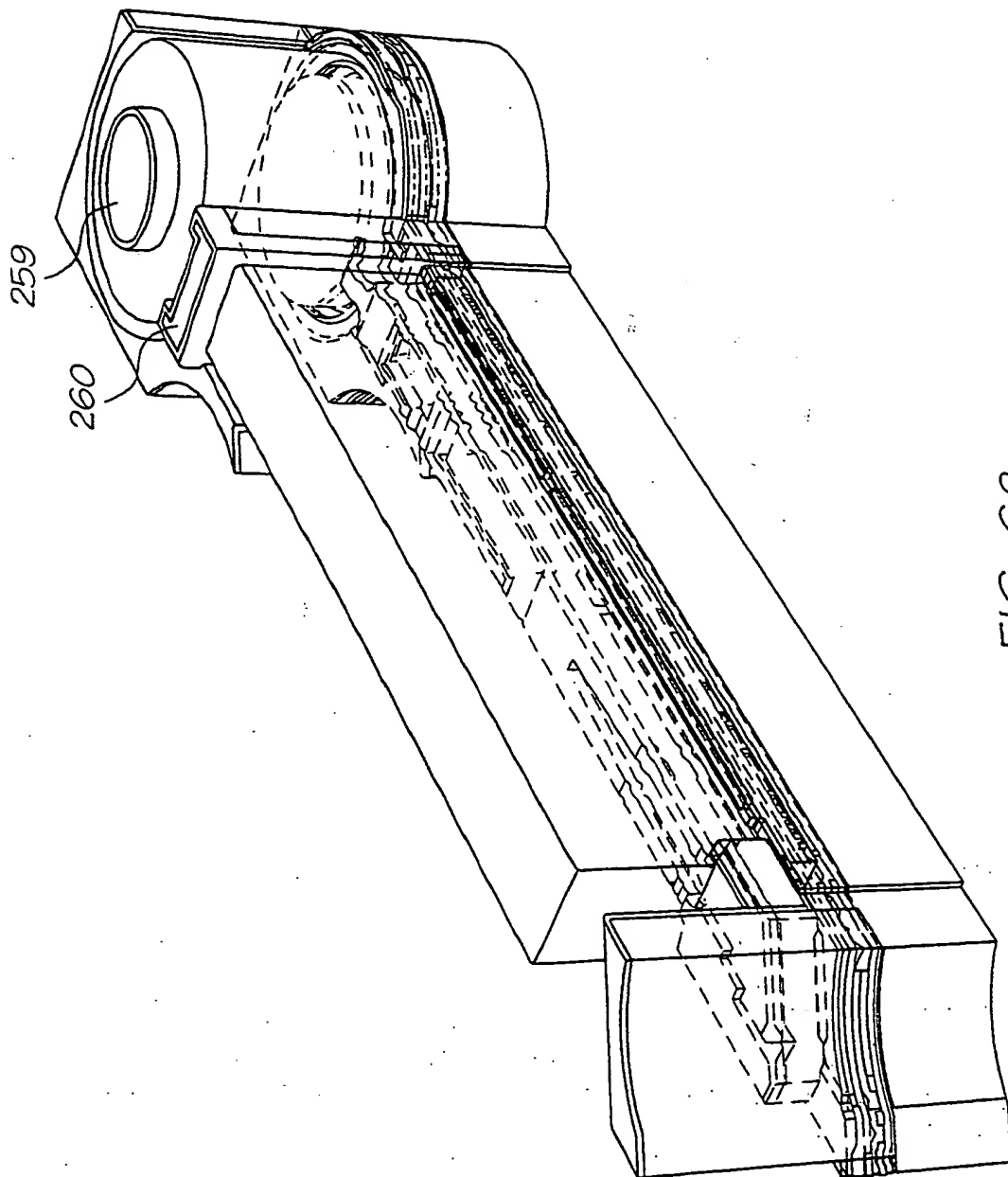
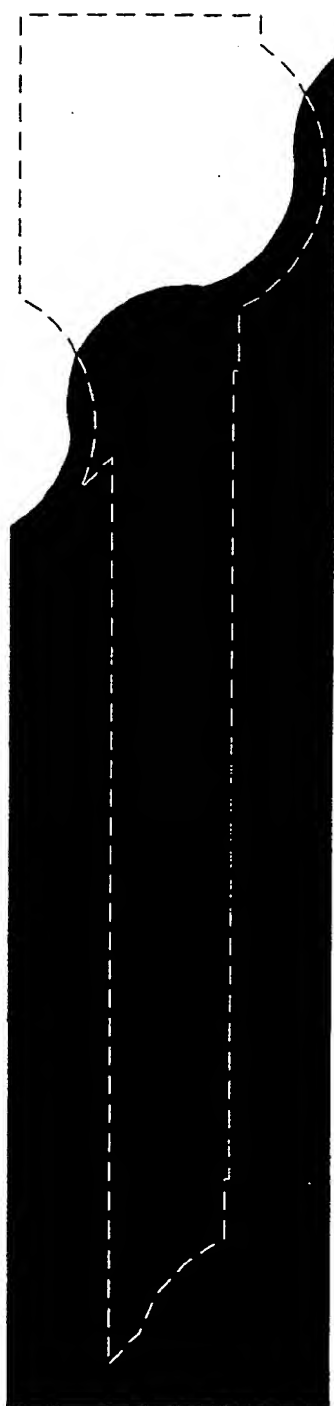


FIG. 68

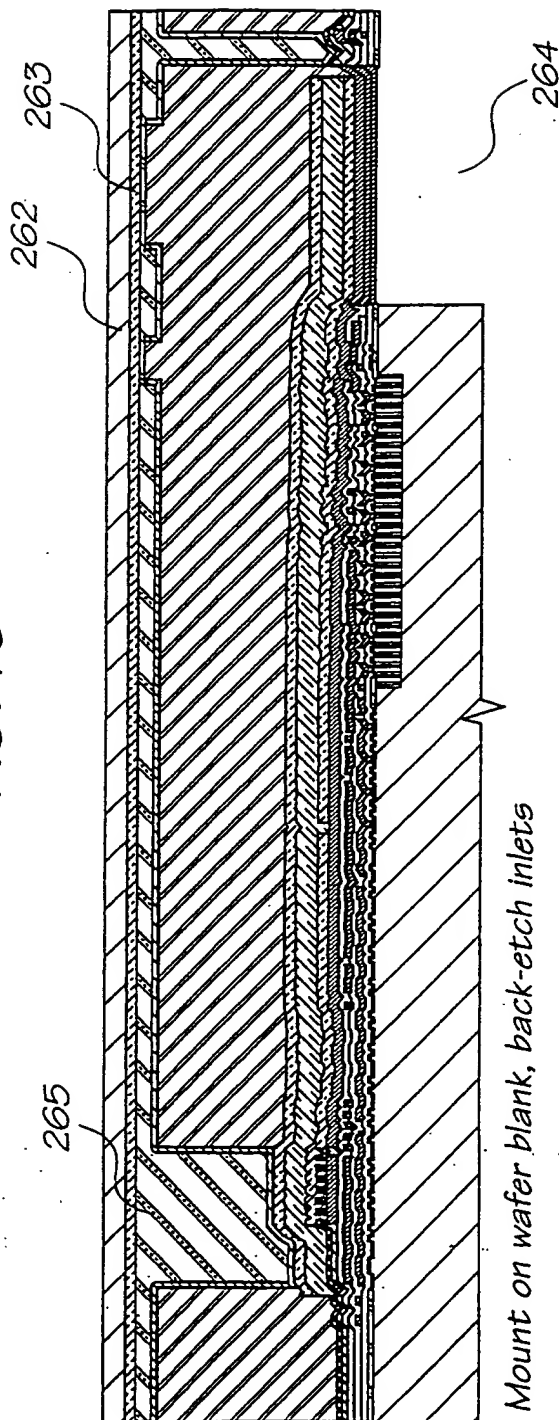
FIG. 68

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Back-etch inlet mask

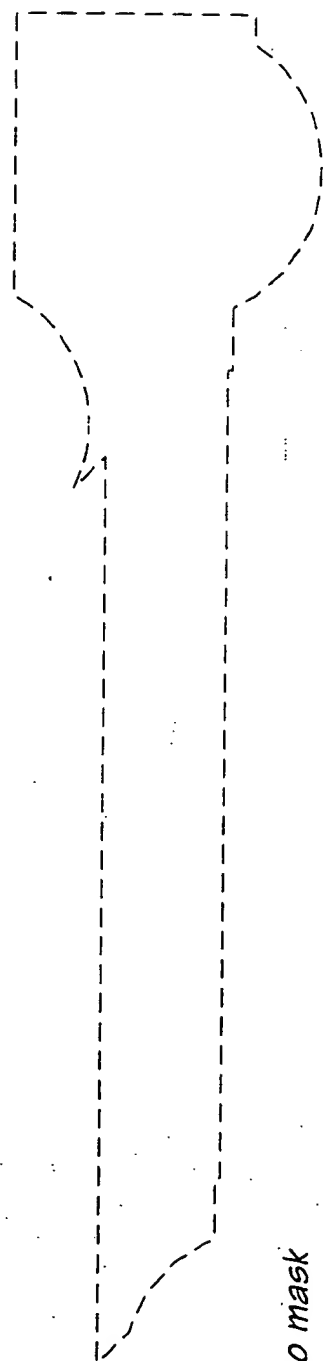
FIG. 70



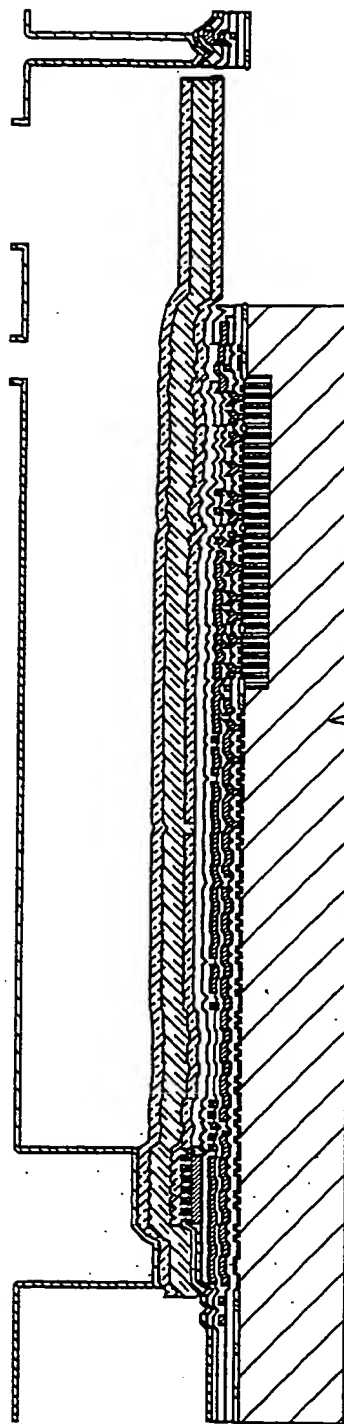
Mount on wafer blank, back-etch inlets

FIG. 69

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No mask



Detach from wafer blank, etch sacrificial material

FIG. 71

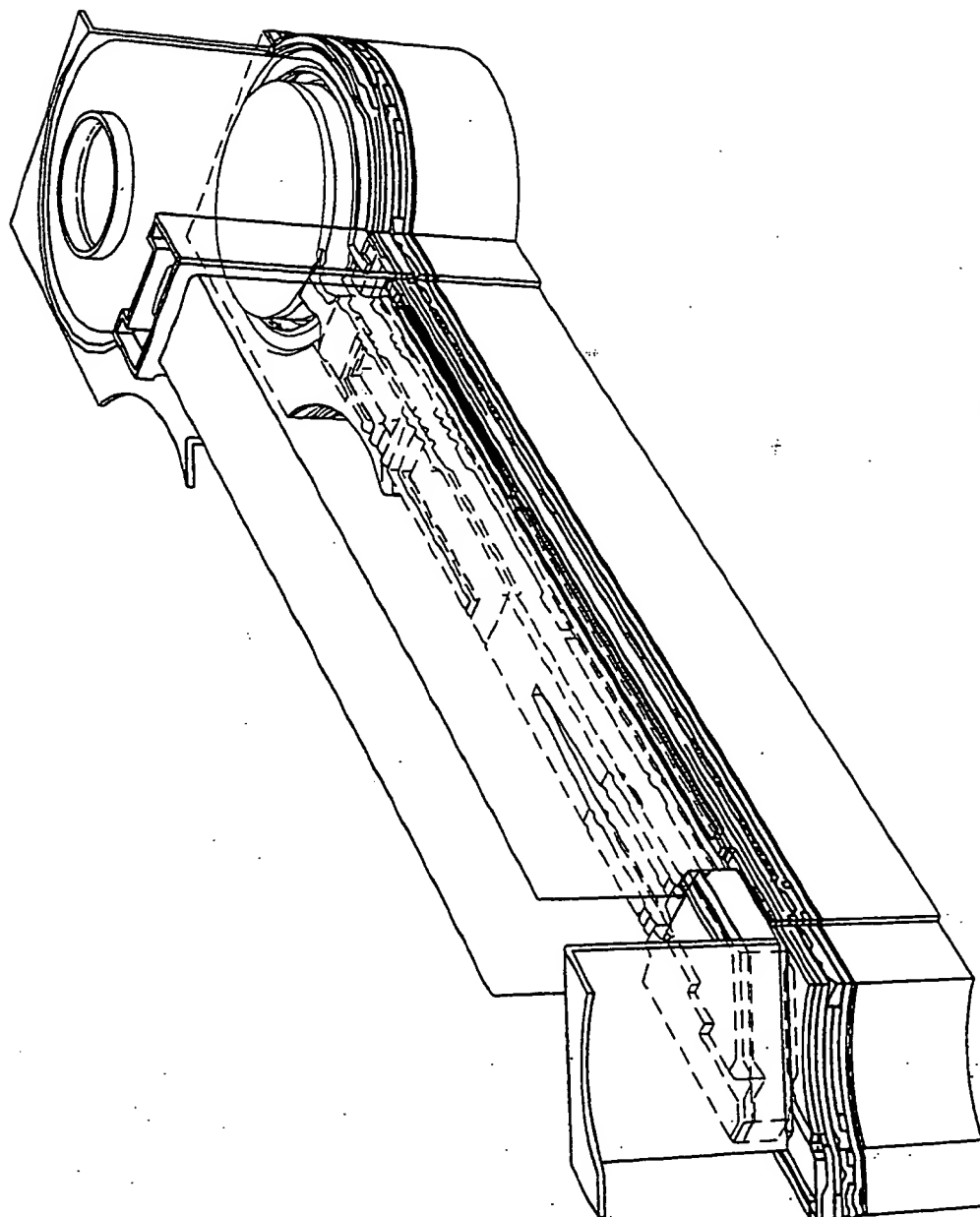


FIG. 72

FIG. 72

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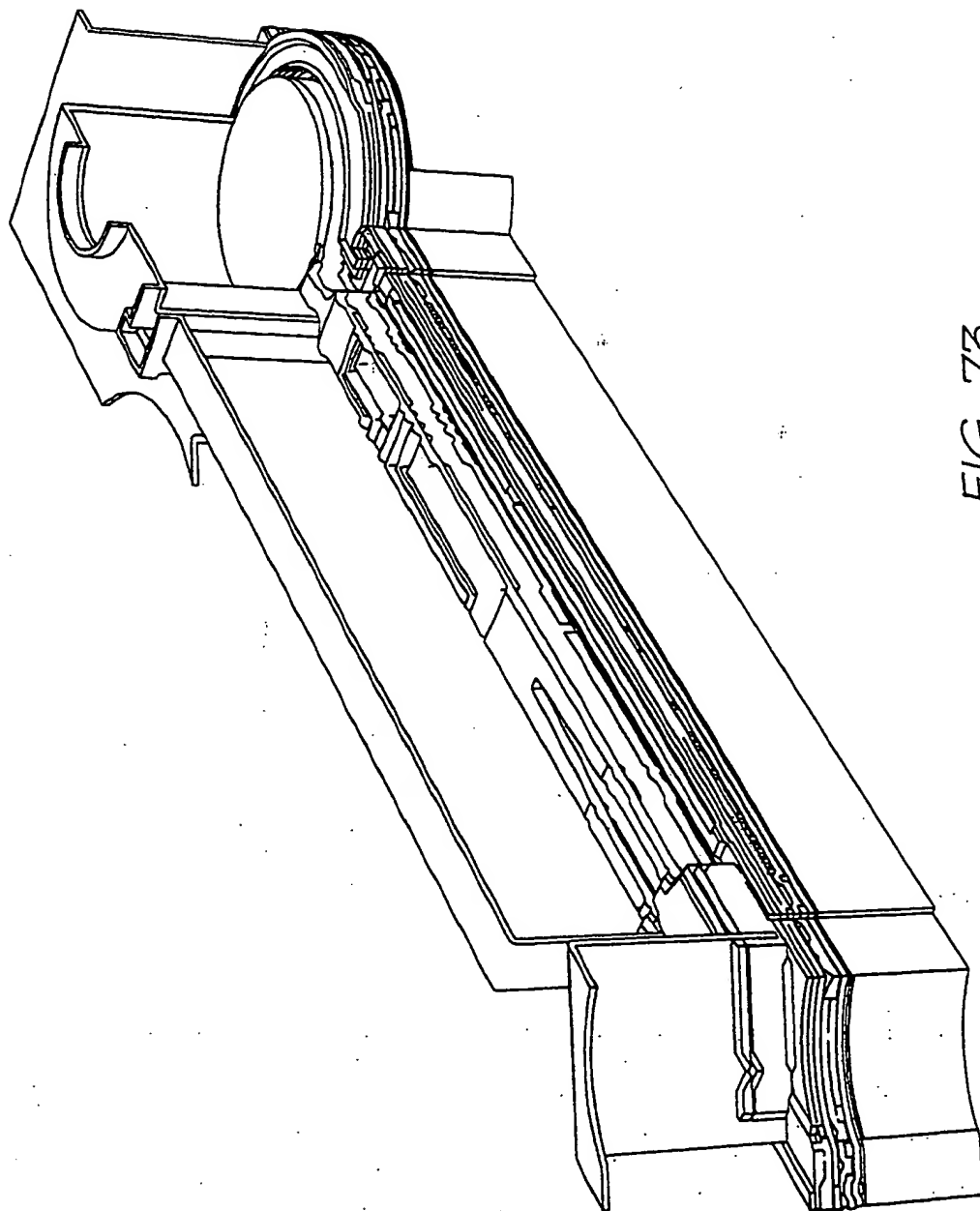


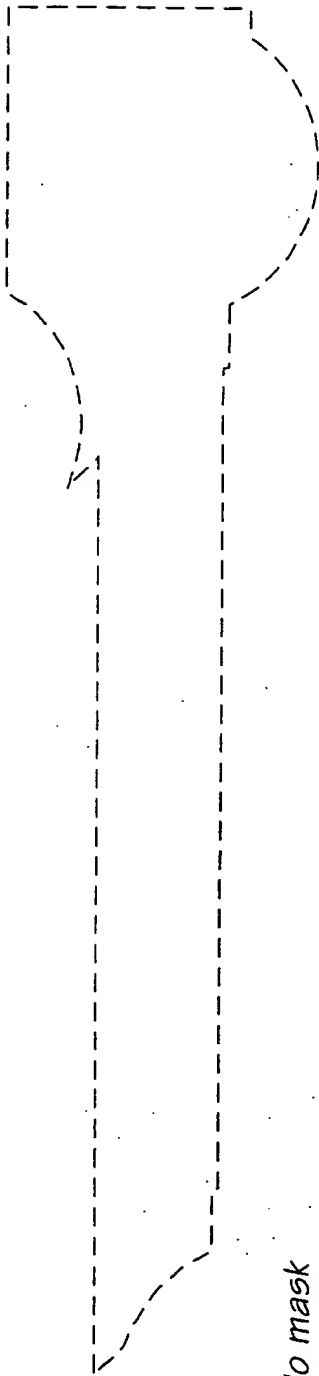
FIG. 73

FIG. 73



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FIG. 73



No mask

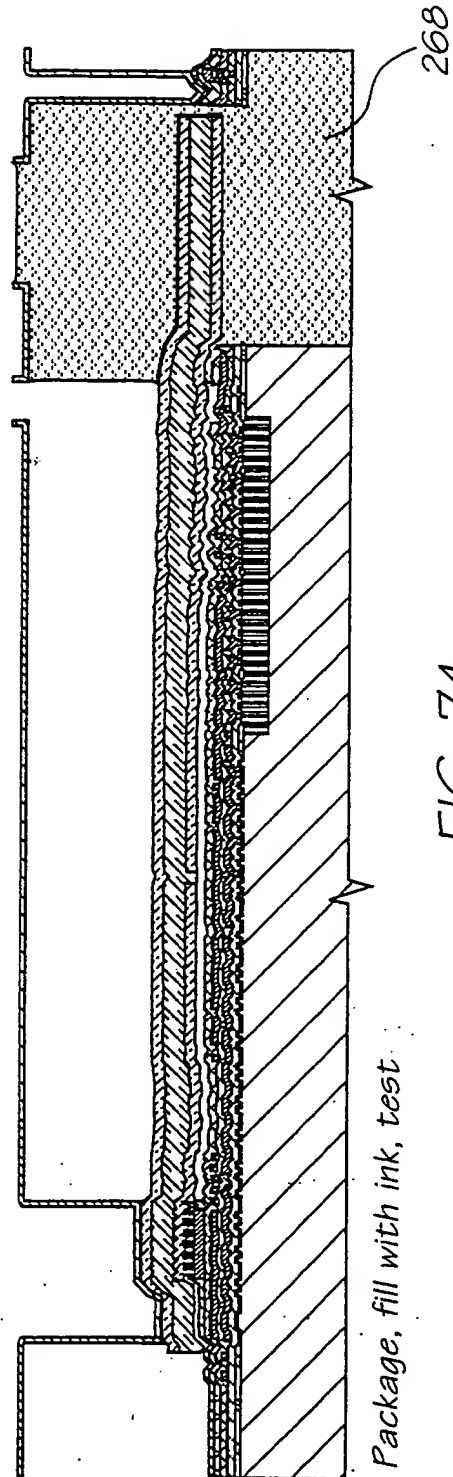


FIG. 74

Package, fill with ink, test

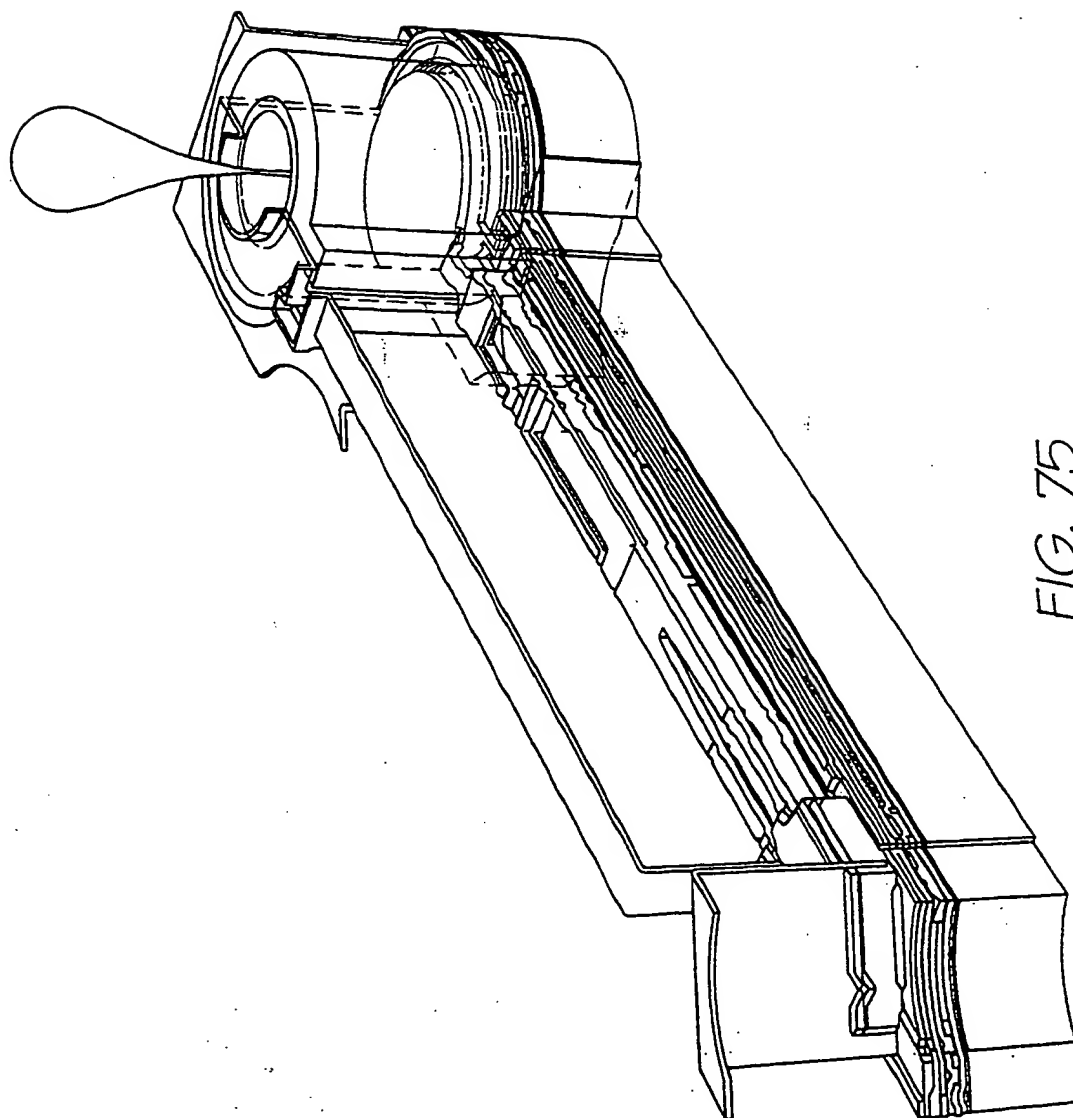


FIG. 75

FIG. 75

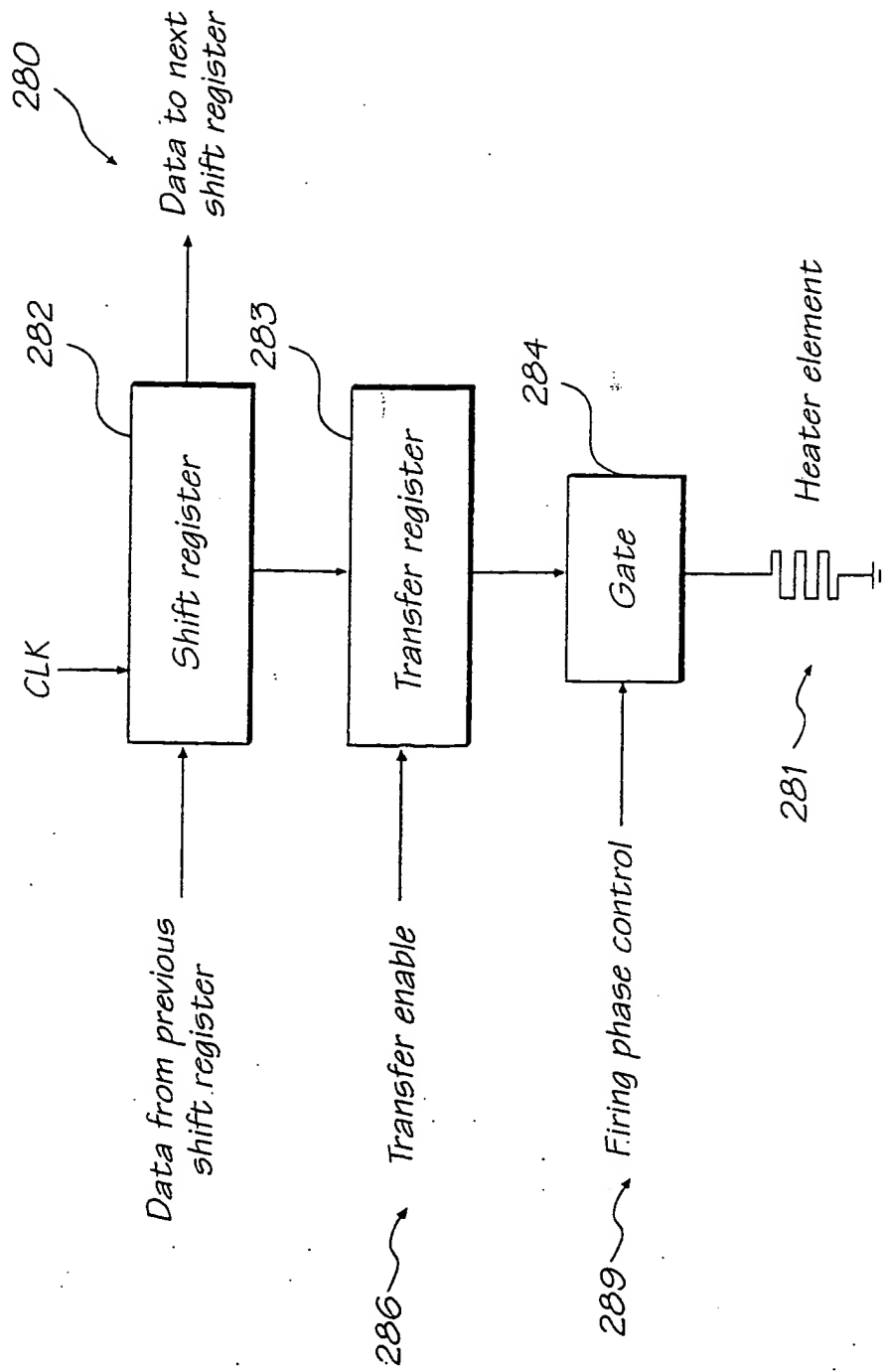


FIG. 76

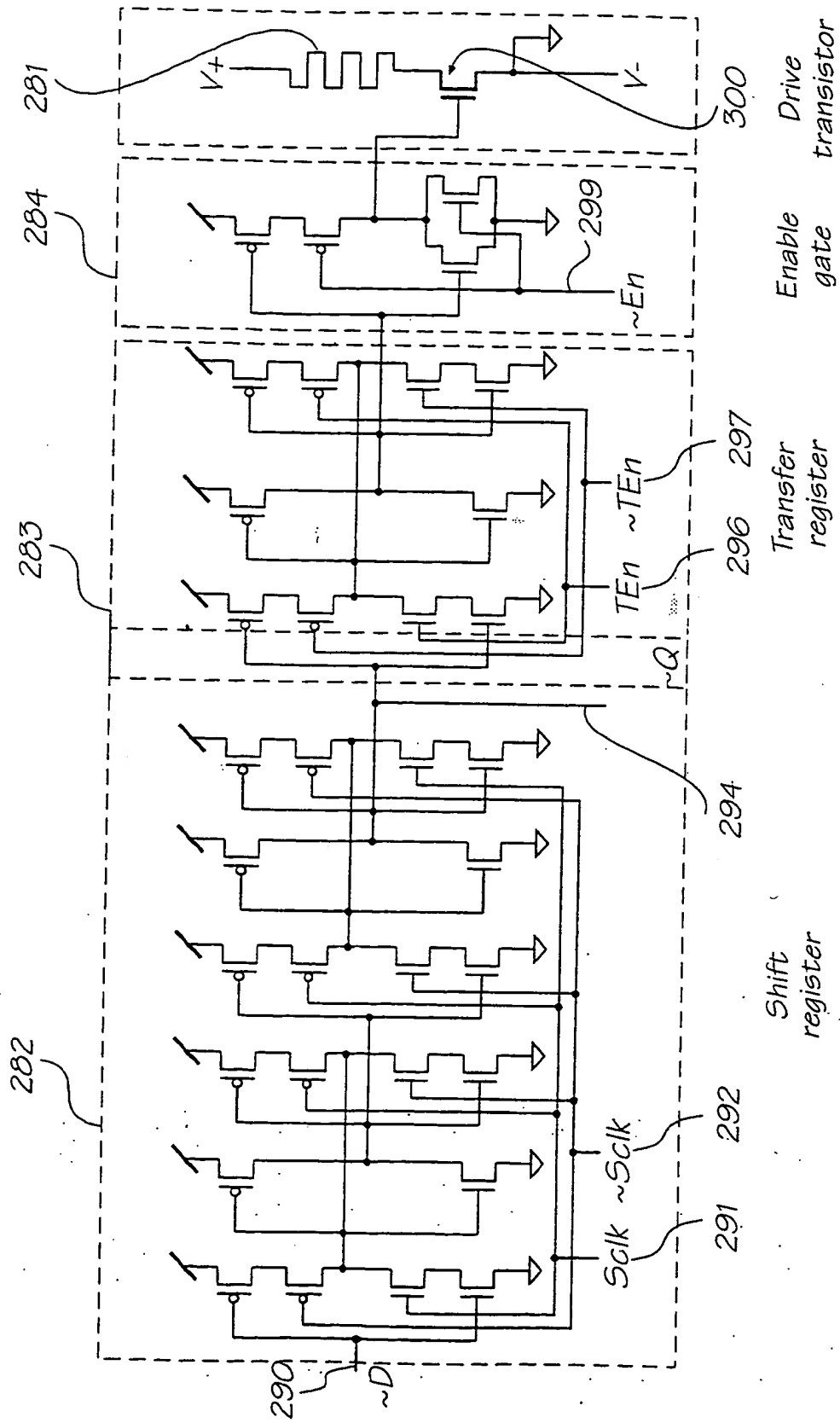


FIG. 77

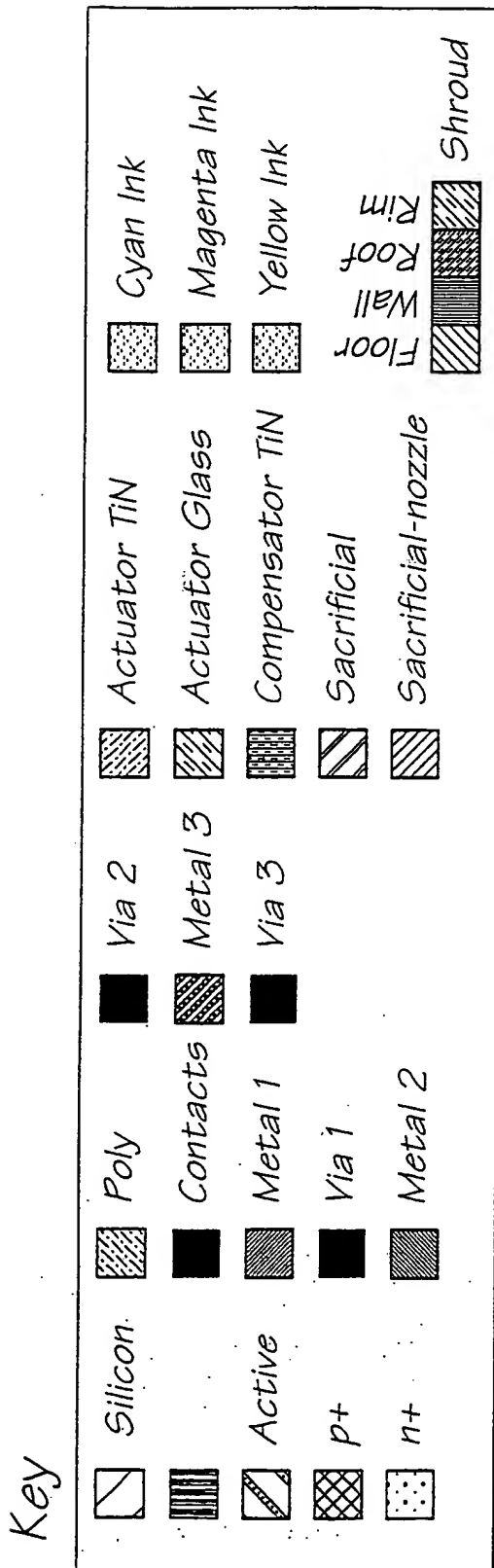


FIG. 78

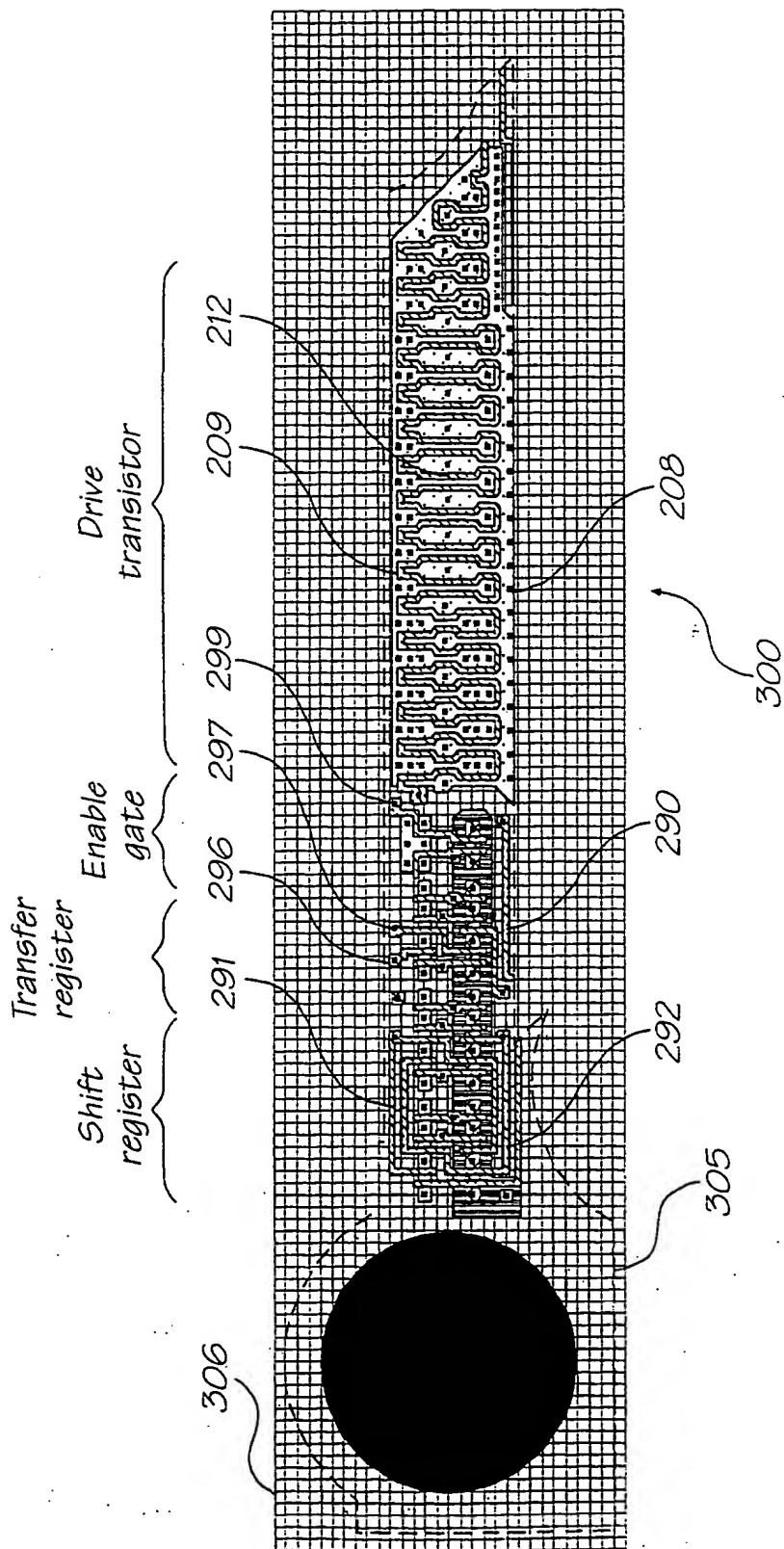


FIG. 79

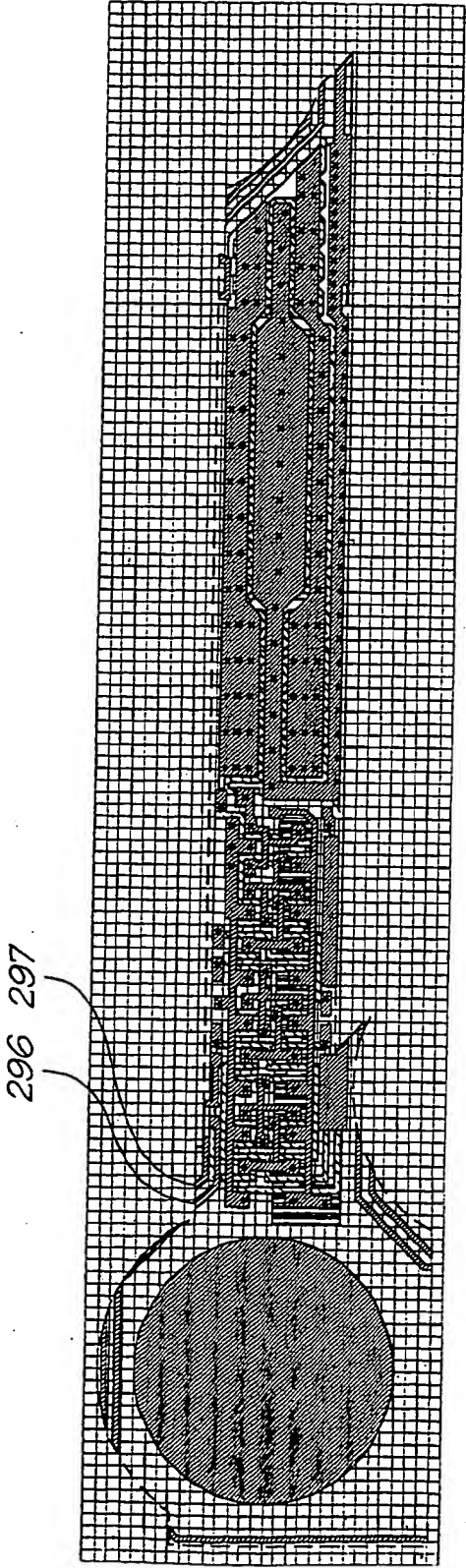


FIG. 80

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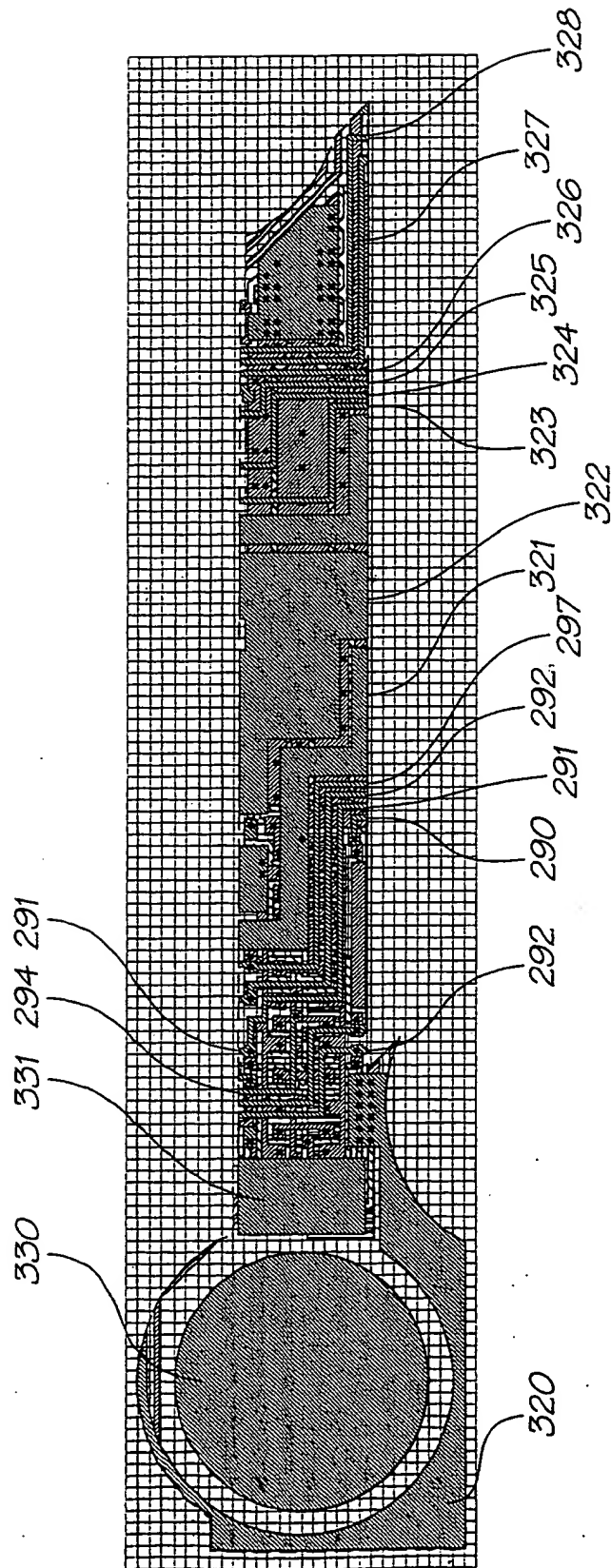


FIG. 81



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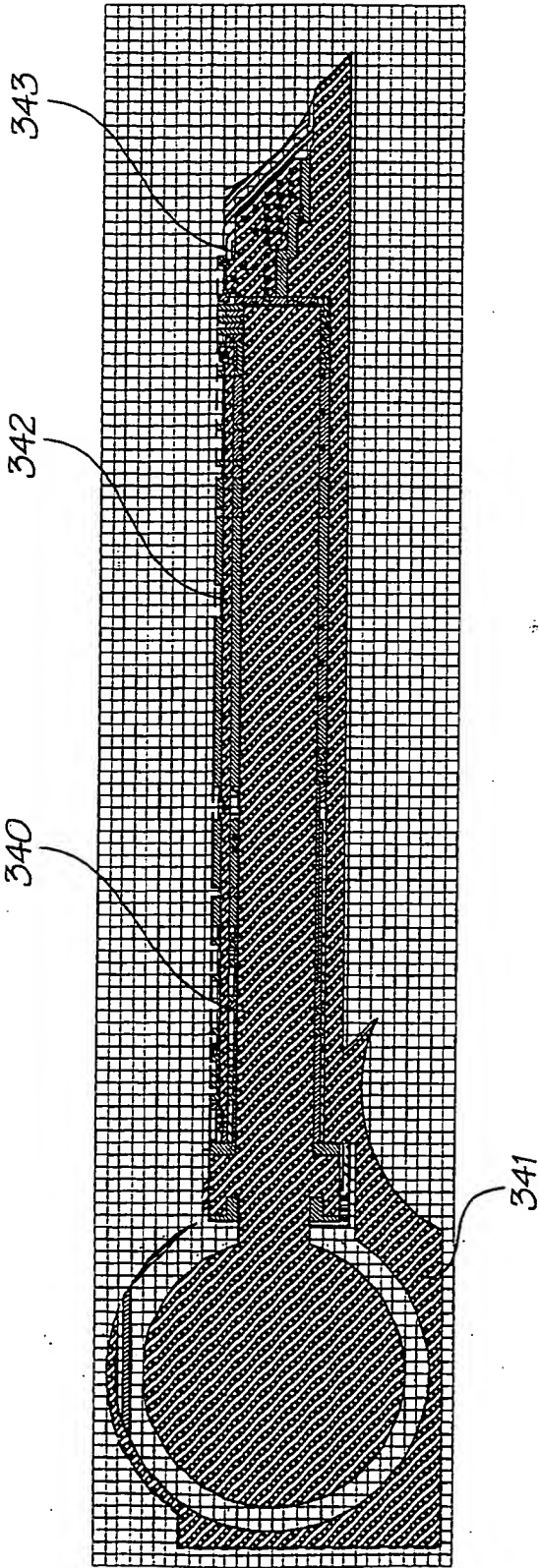


FIG. 82

FIG. 82

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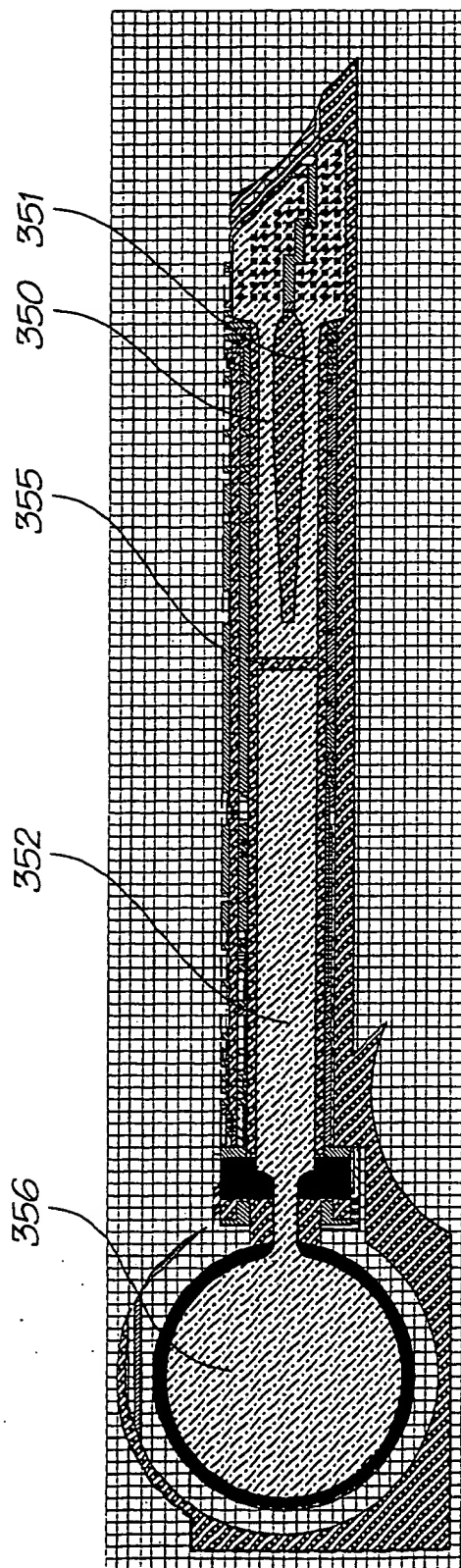


FIG. 83

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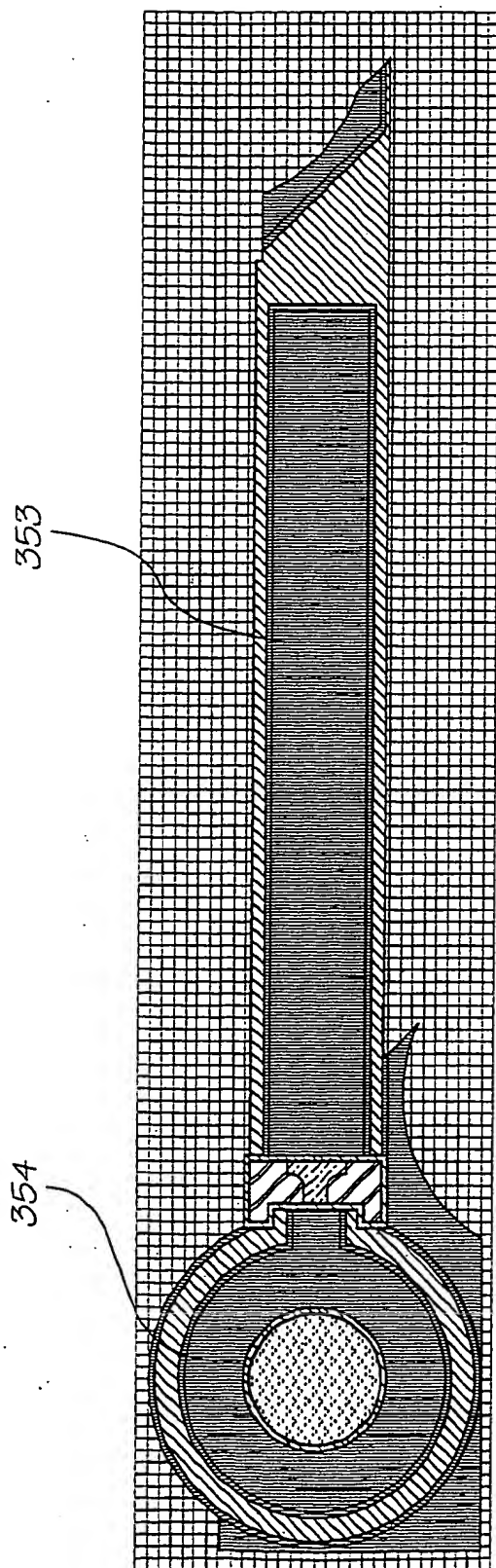


FIG. 84

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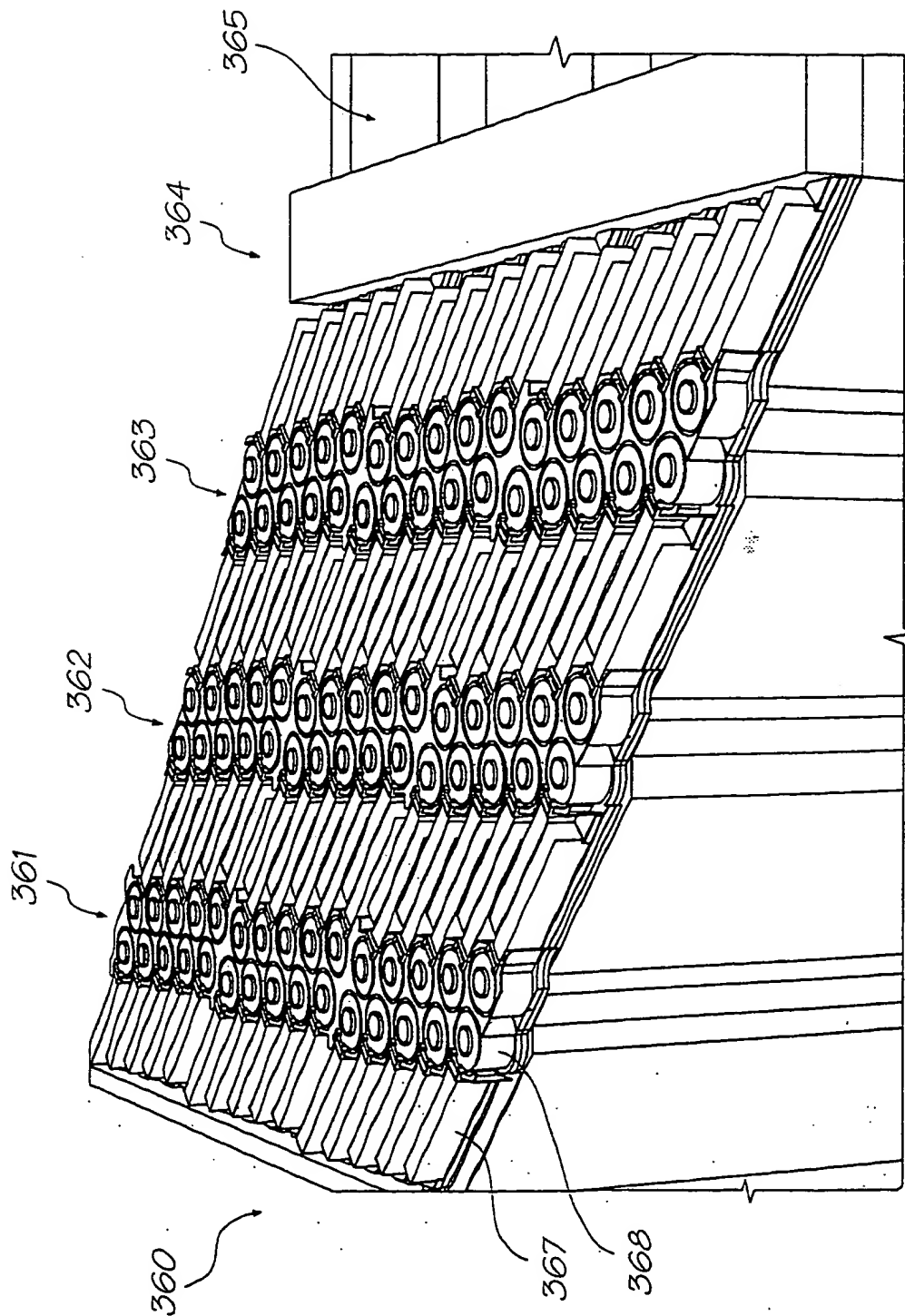


FIG. 85

FIG. 85

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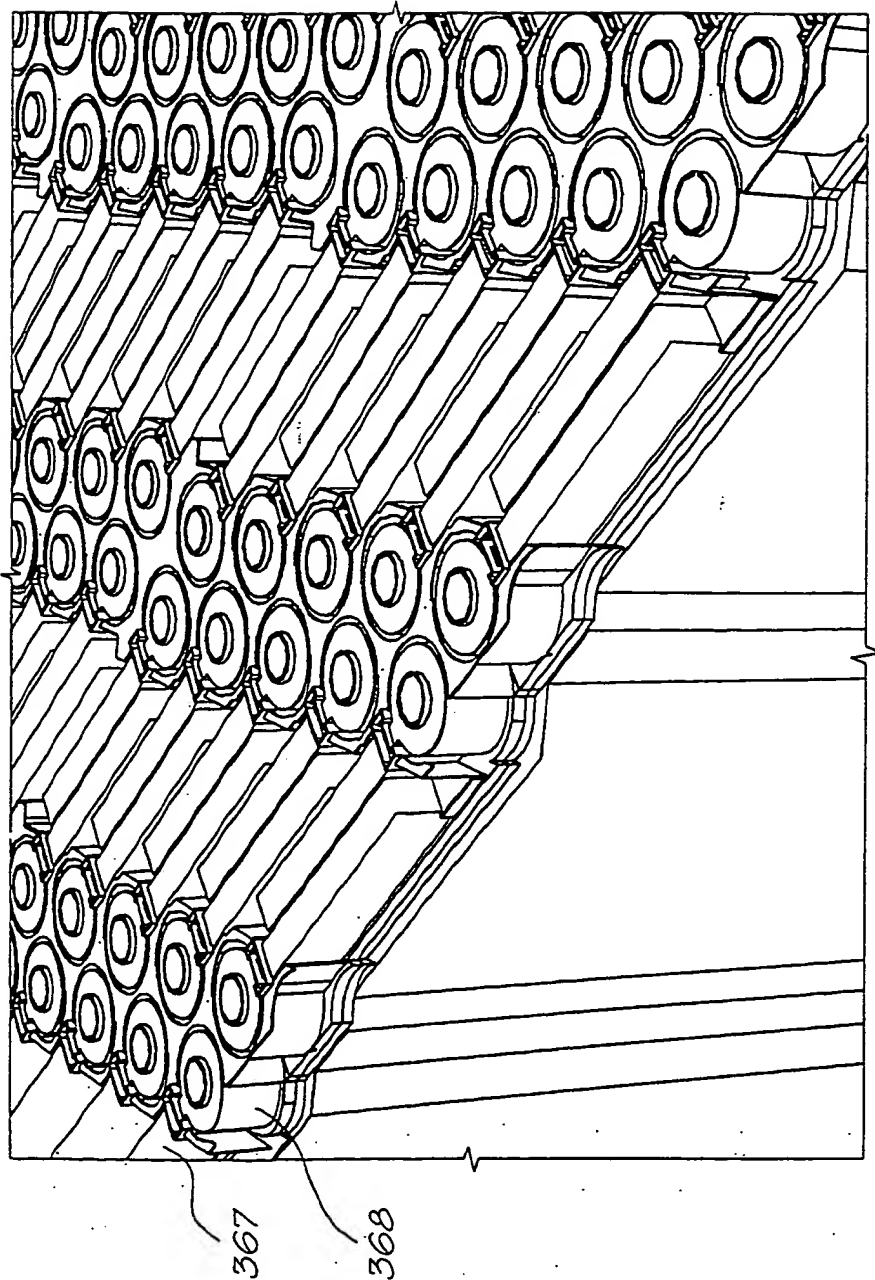


FIG. 86

FIG. 86

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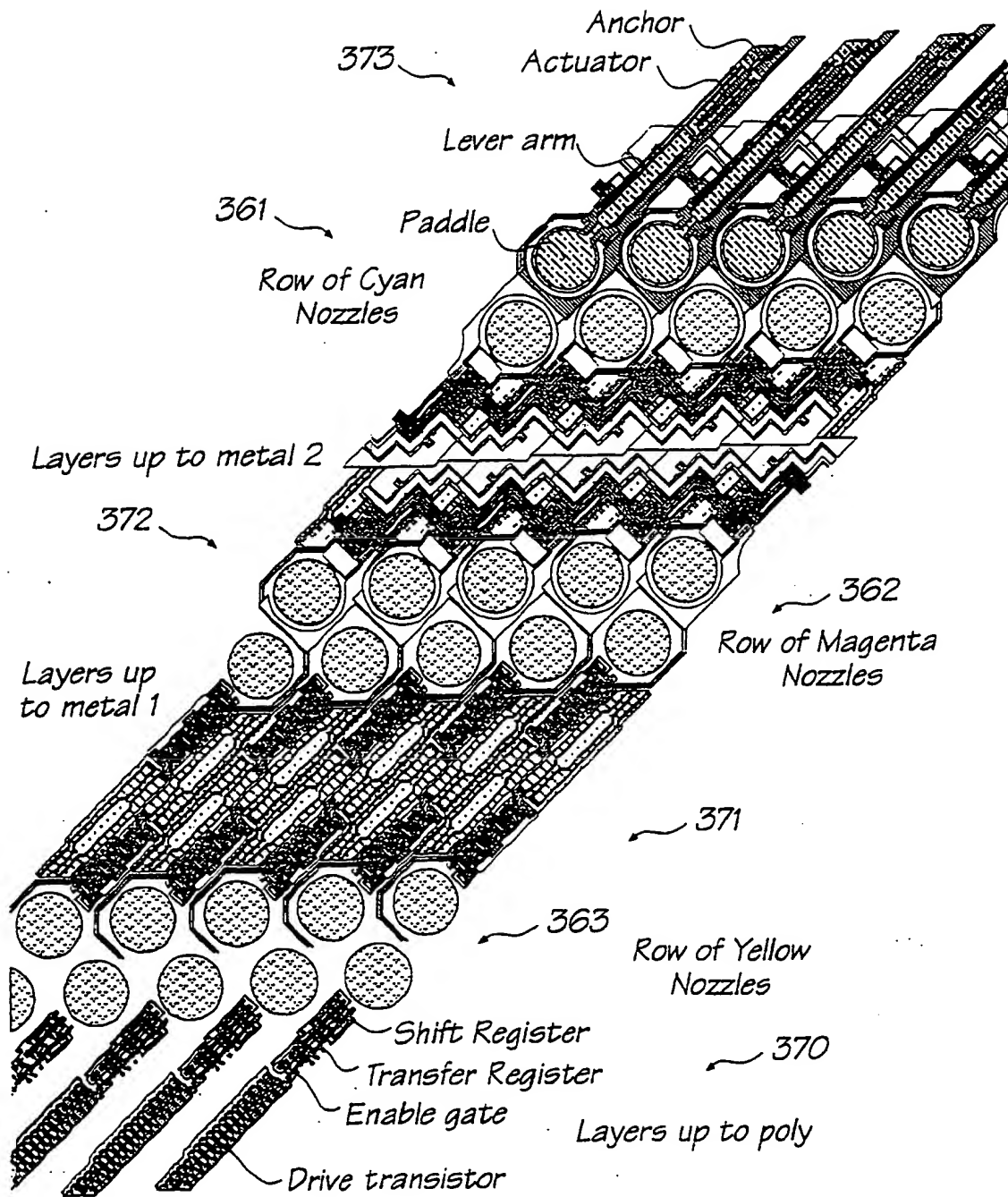


FIG. 87

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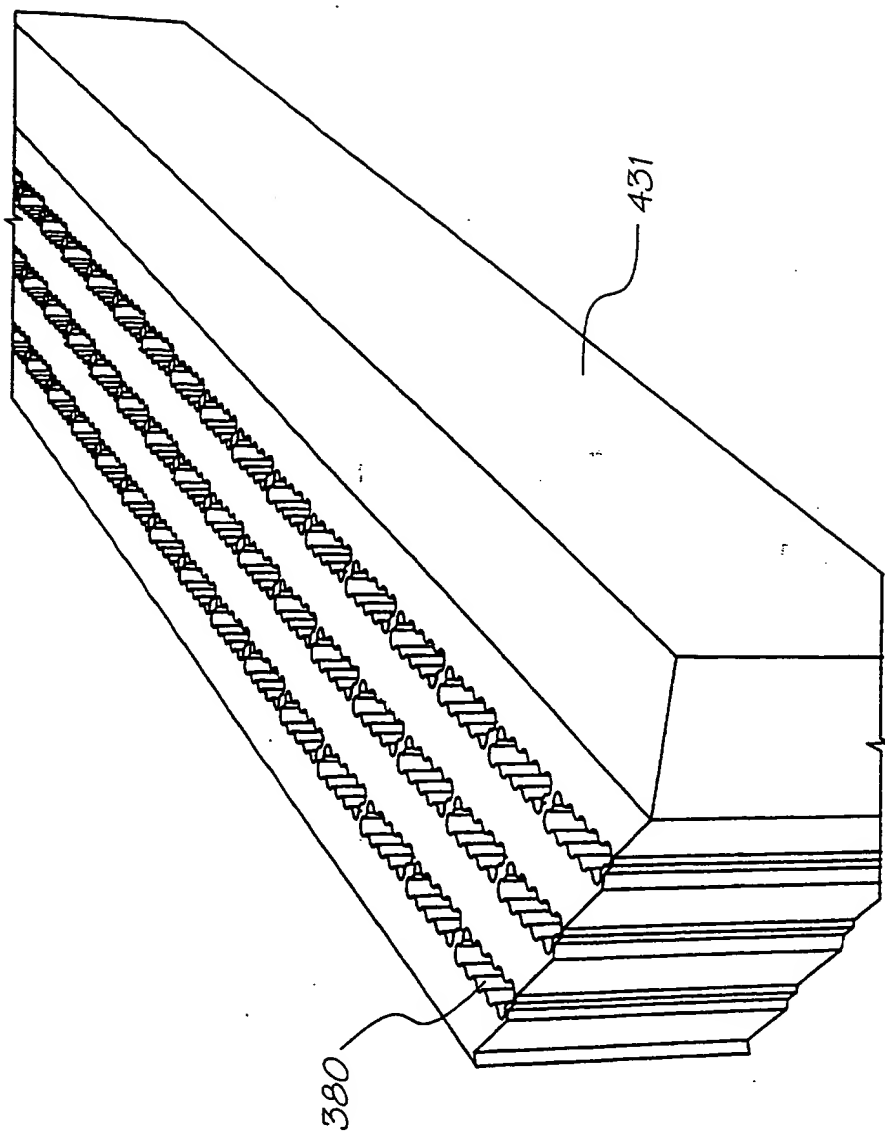


FIG. 88

FIG. 88

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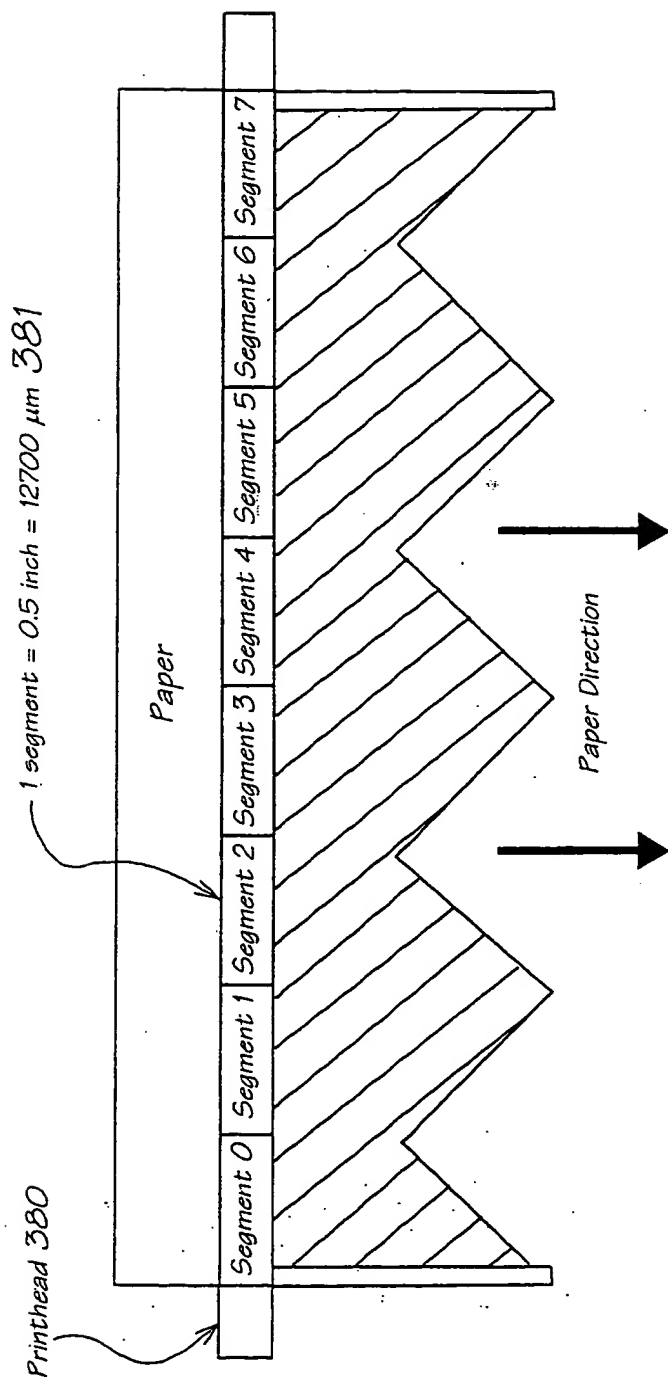
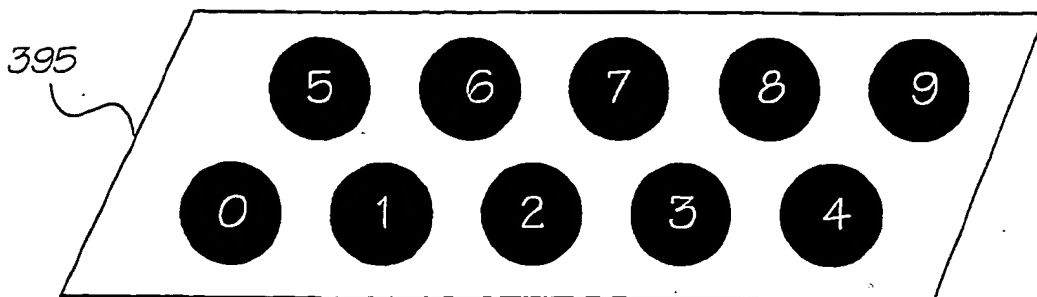


FIG. 89



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A single pod, numbered by firing order

Fig. 90

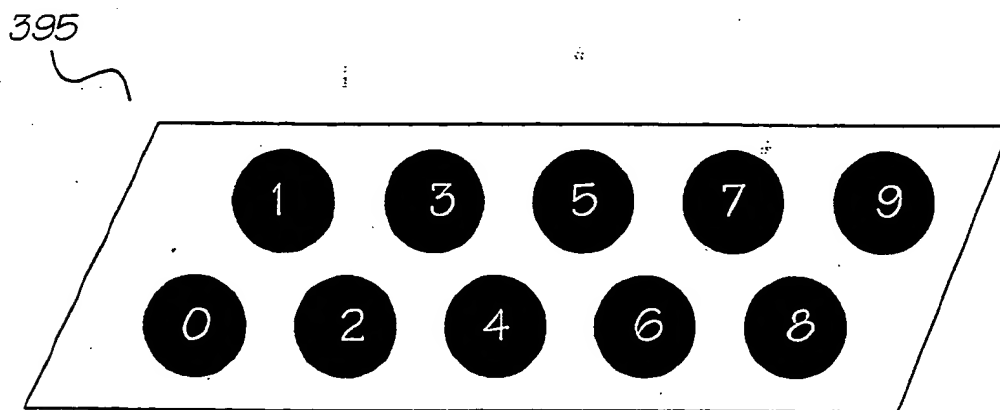


Fig. 91

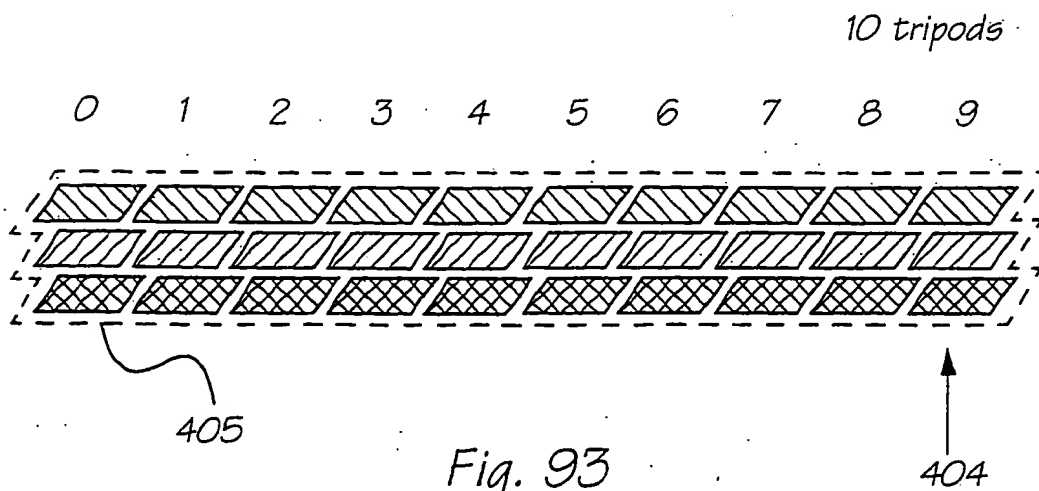


Fig. 93

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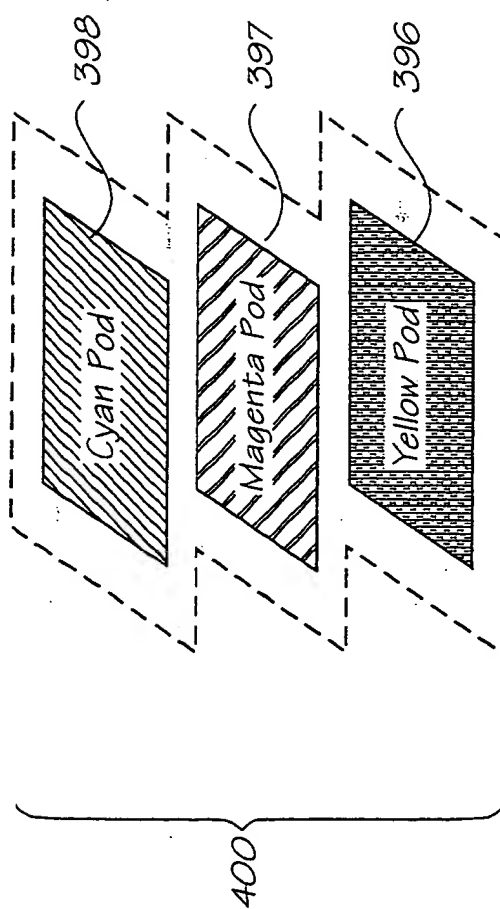
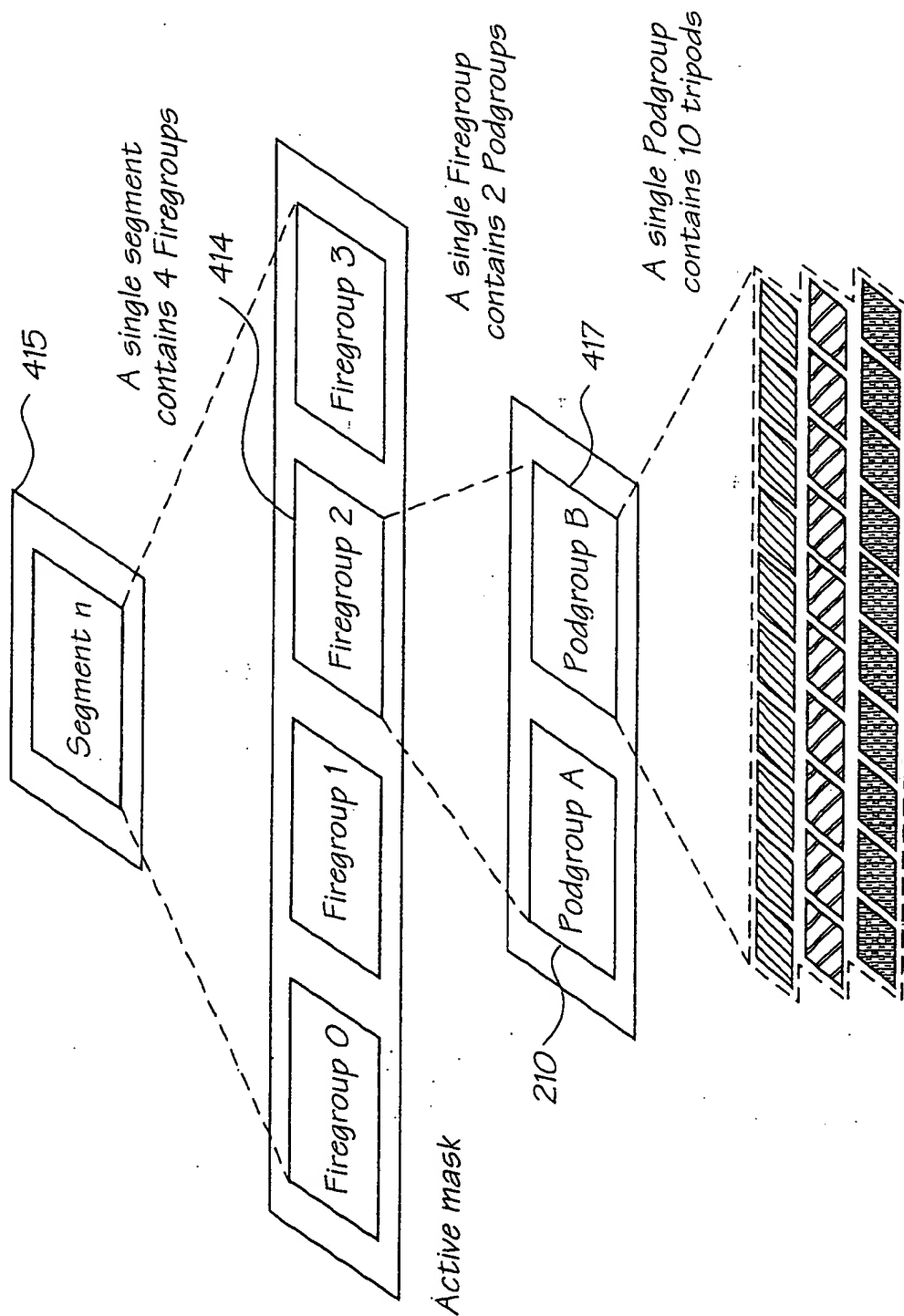


FIG. 92

FIG. 92

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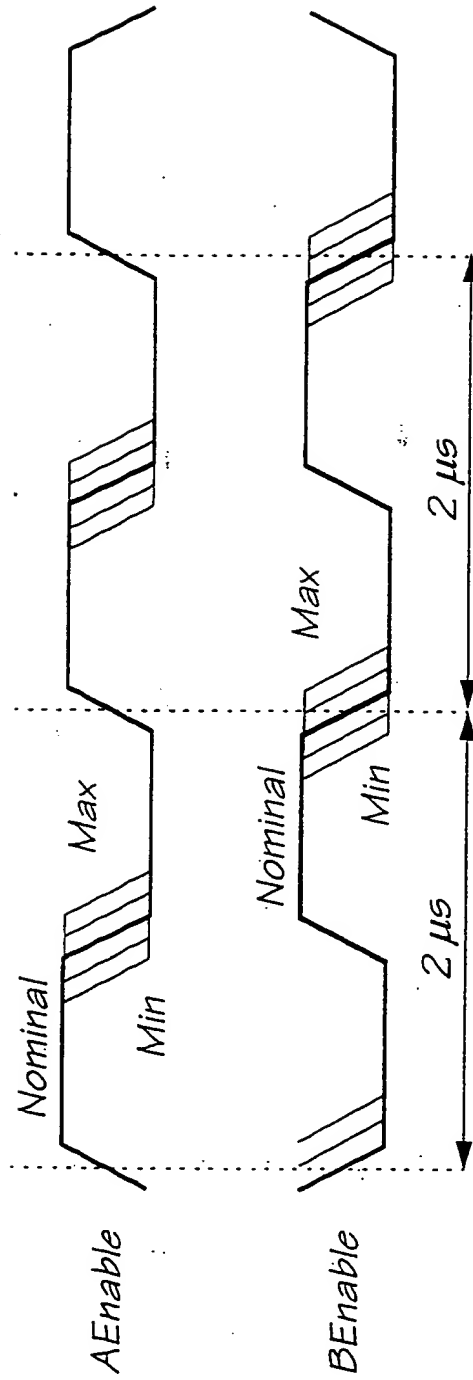


FIG. 95

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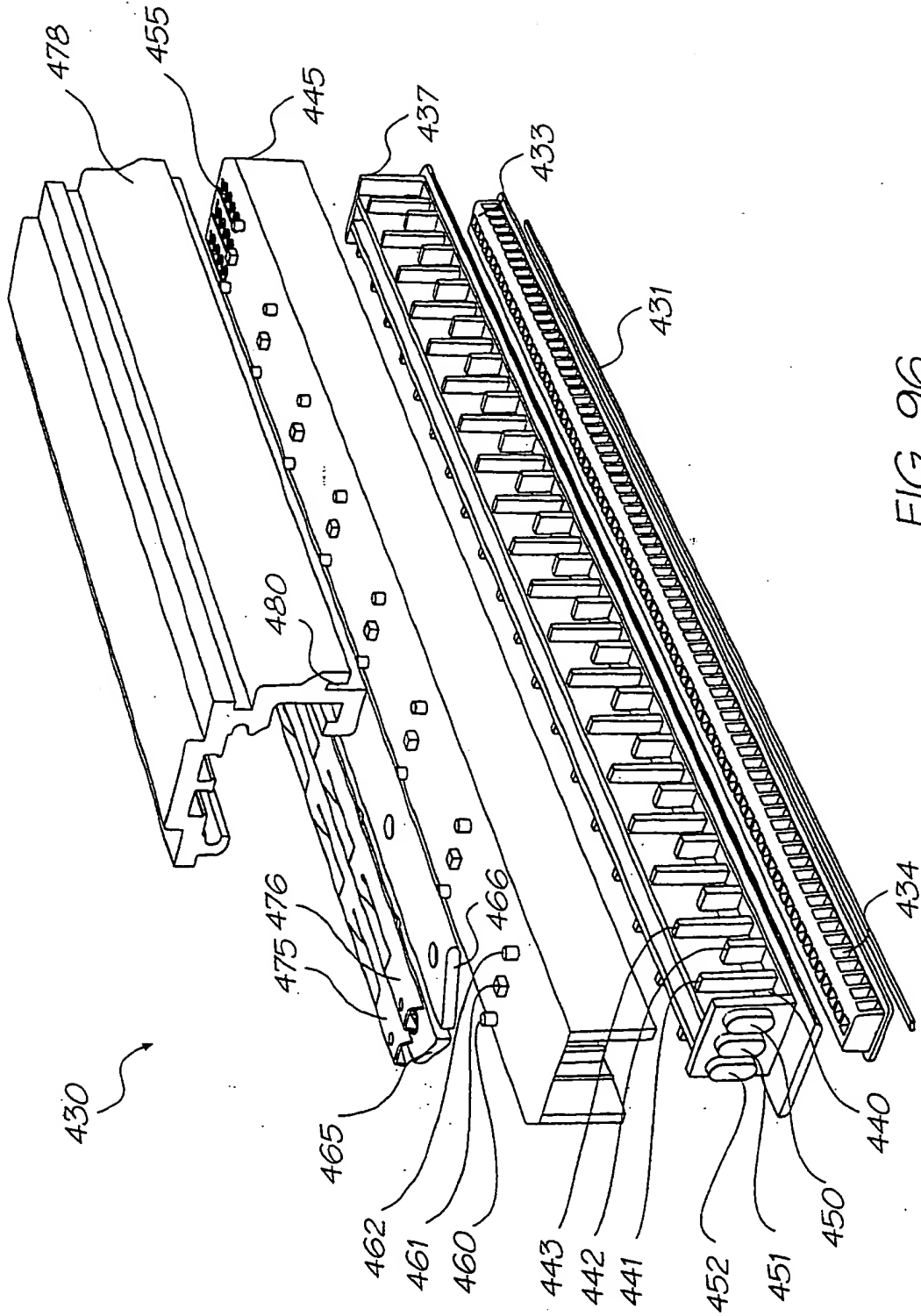


FIG. 96

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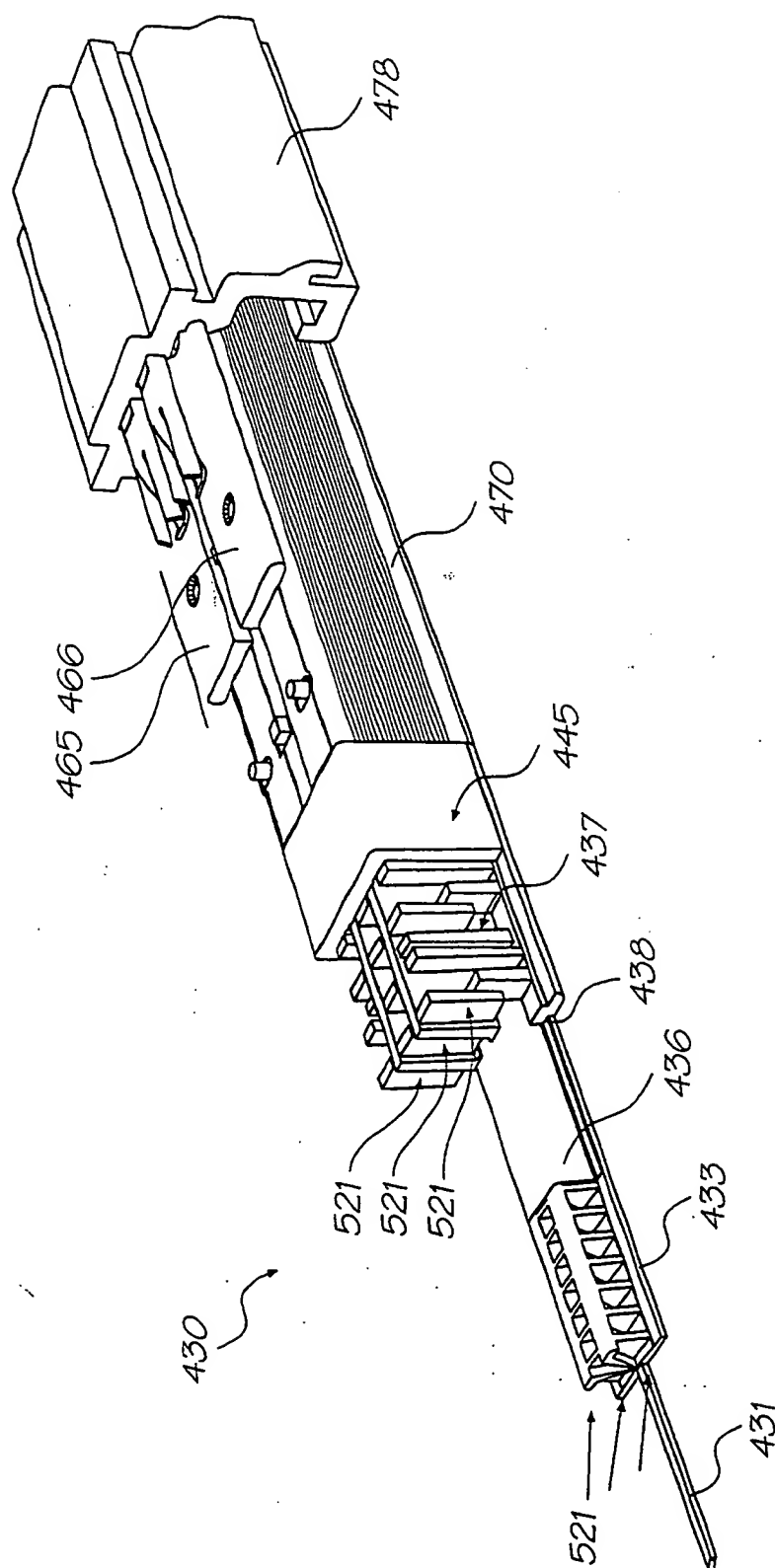


FIG. 97

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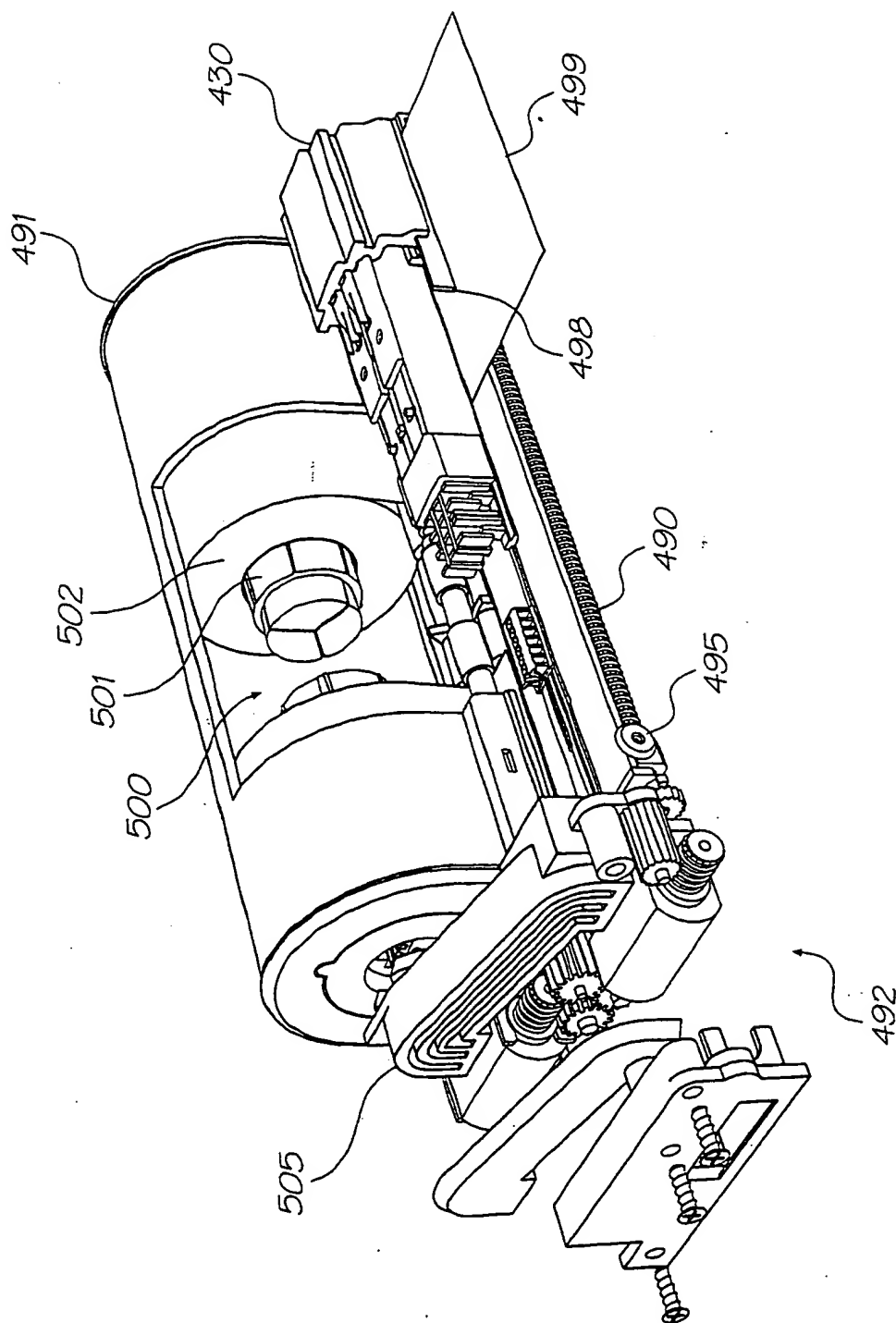


FIG. 98

FIG. 98

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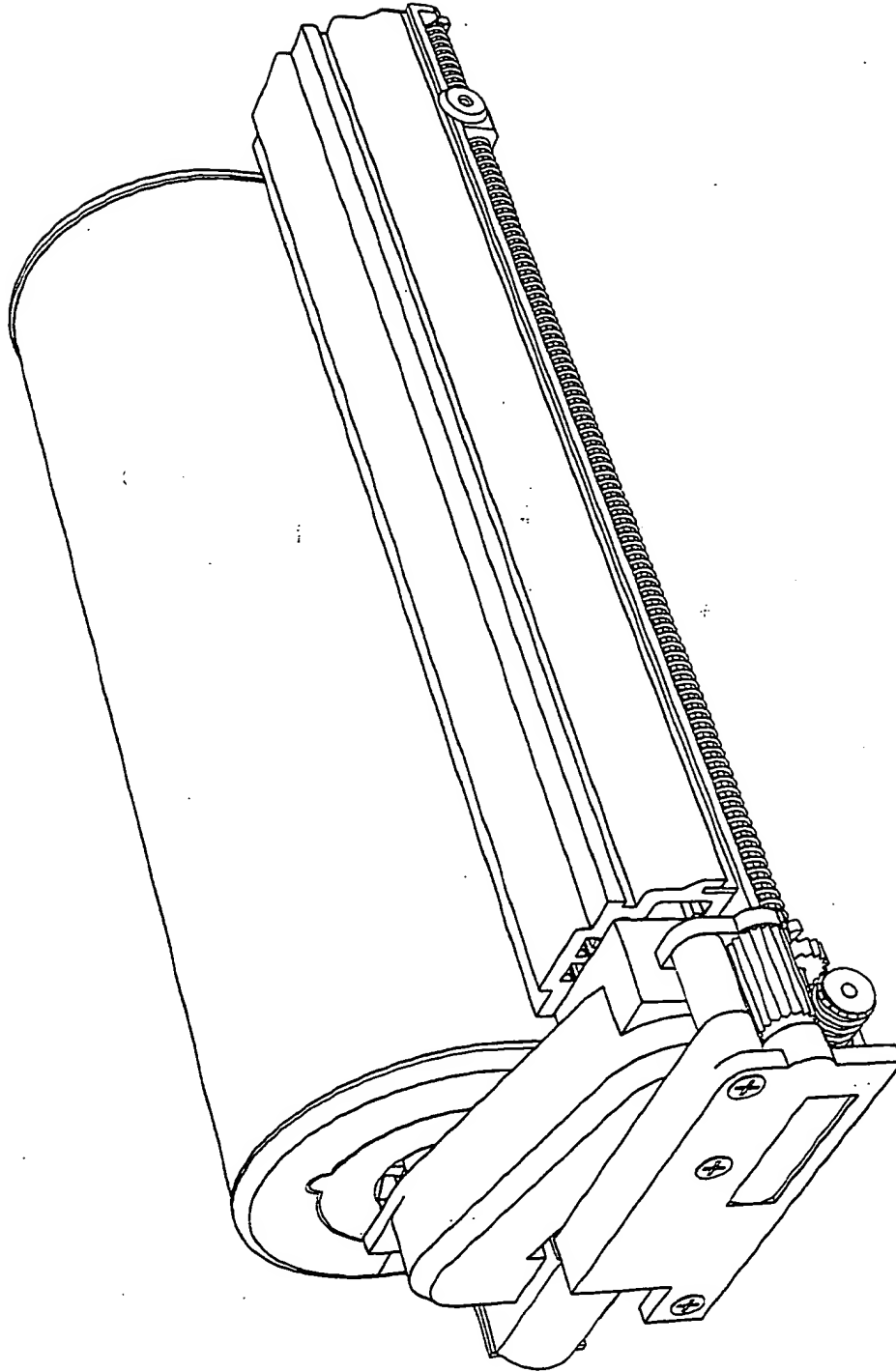


FIG. 99

FIG. 99



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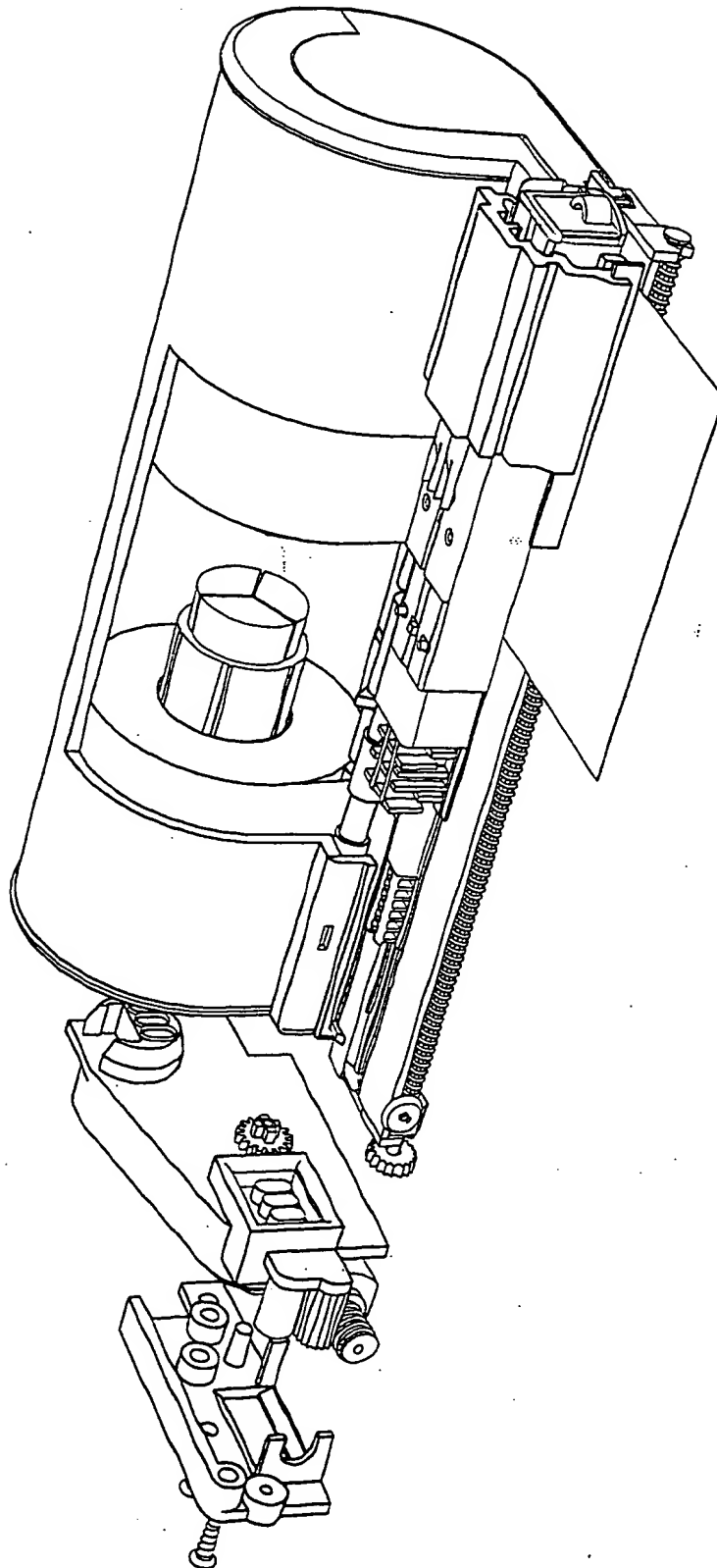


FIG. 100

FIG. 100

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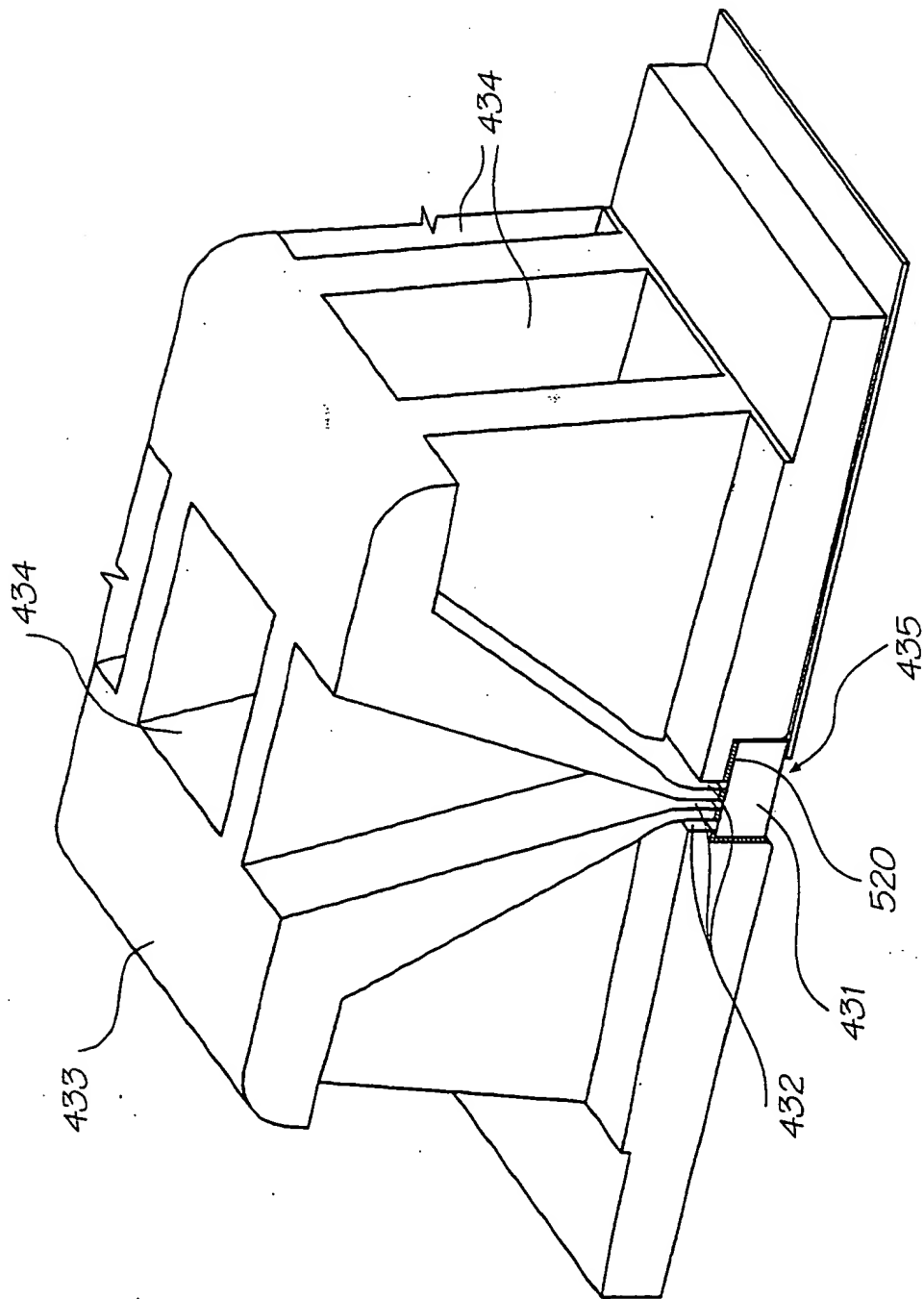


FIG. 101

FIG. 101

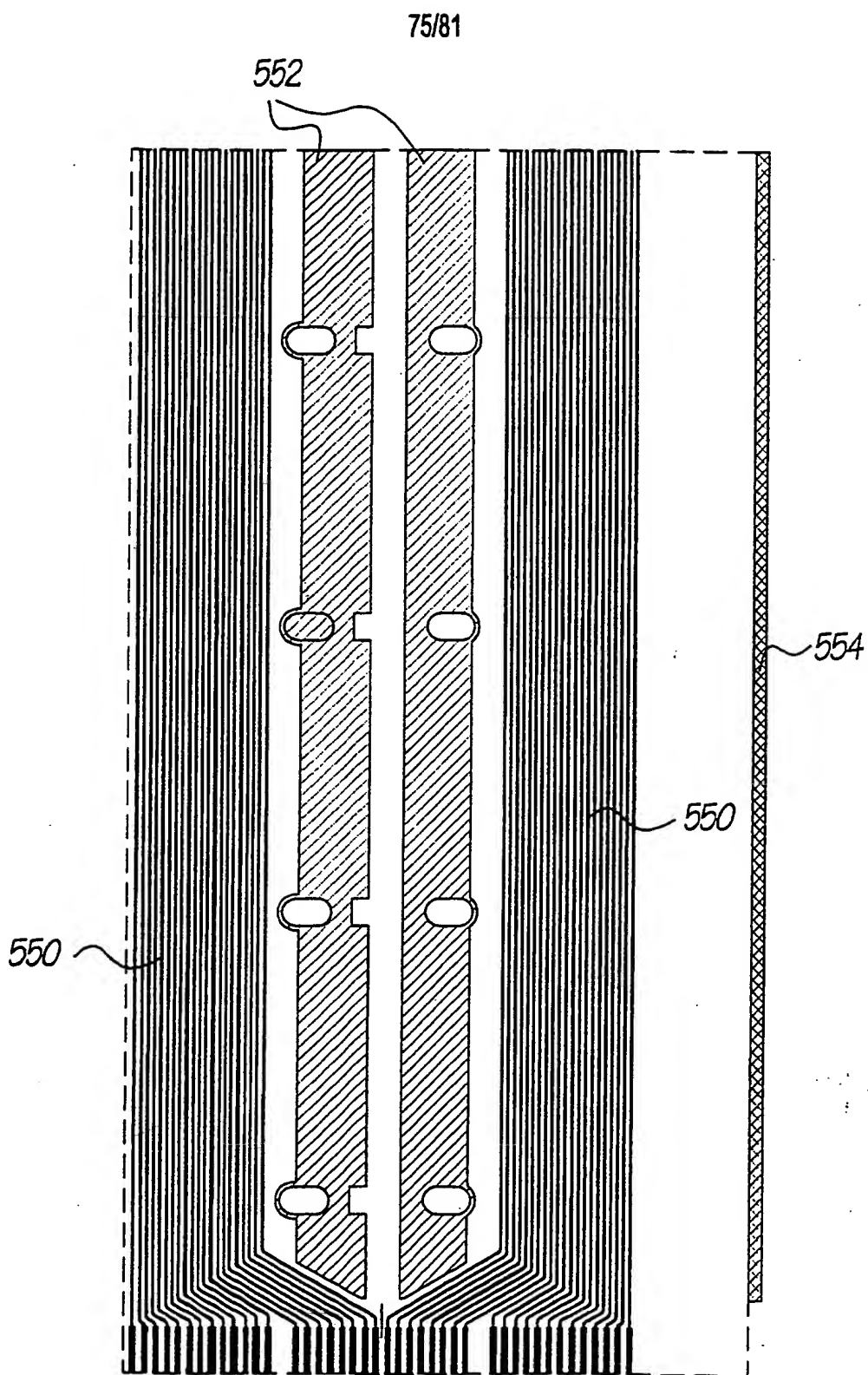


FIG. 102

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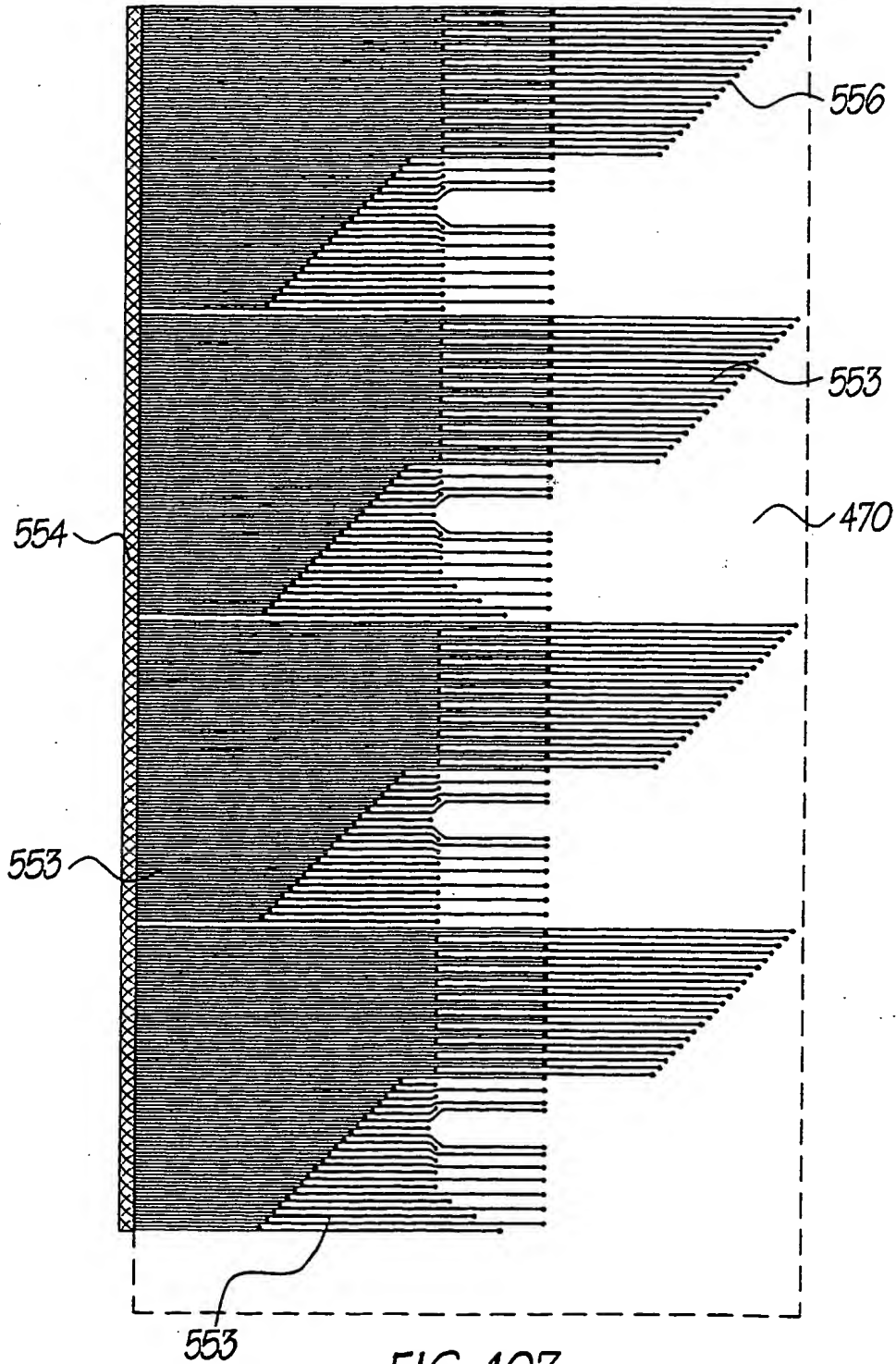


FIG. 103

FIG. 103

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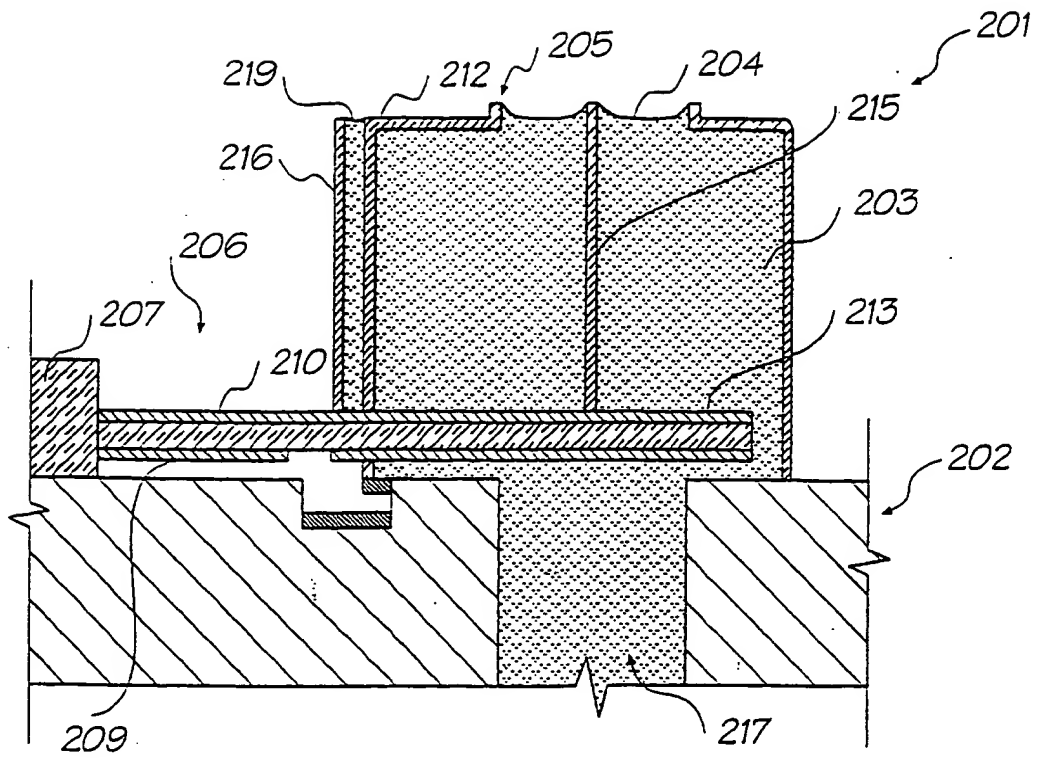


FIG. 104

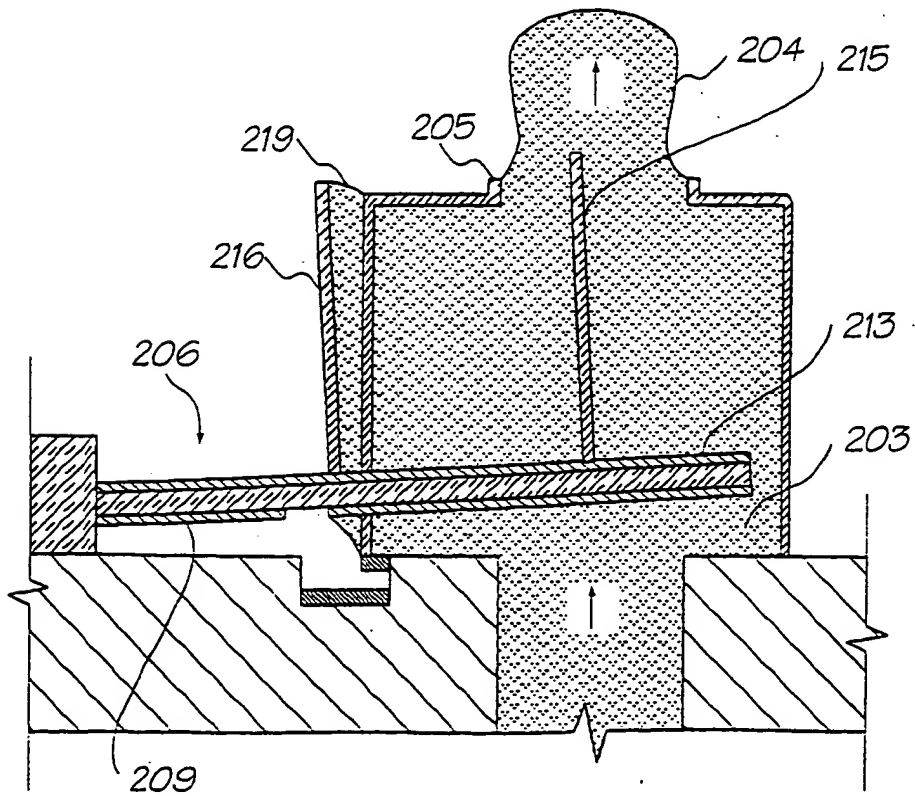


FIG. 105

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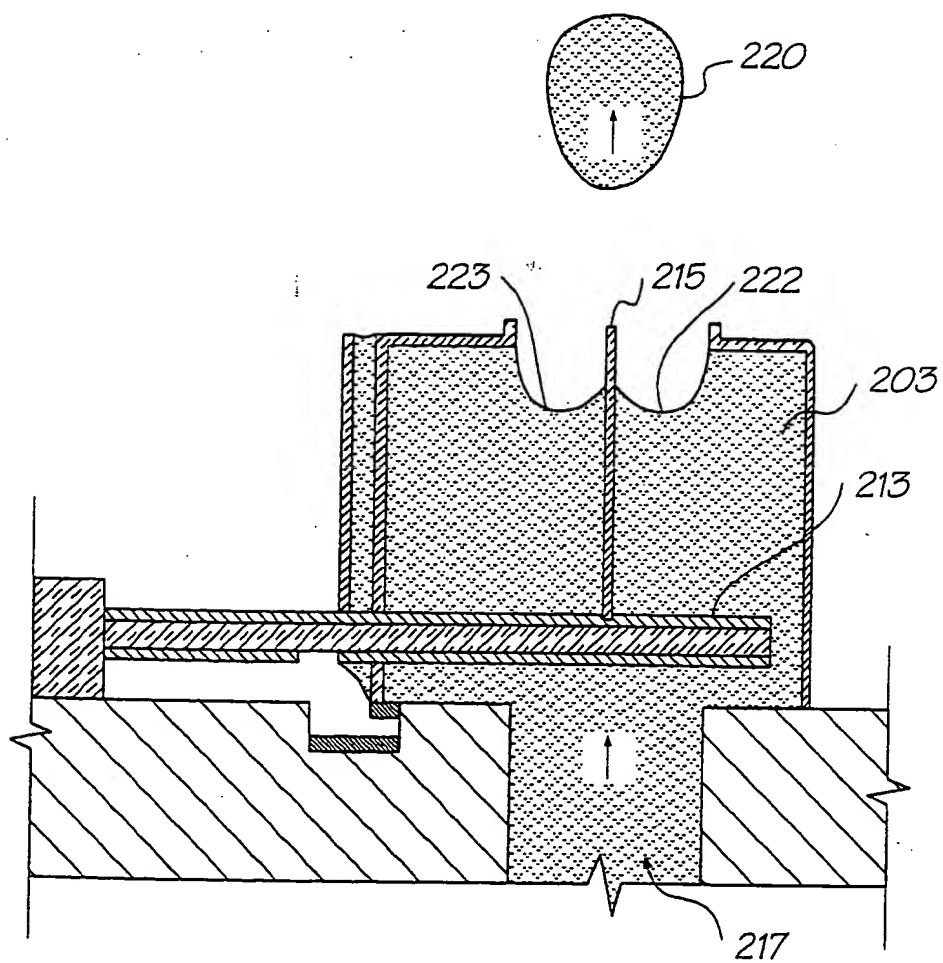


FIG. 106

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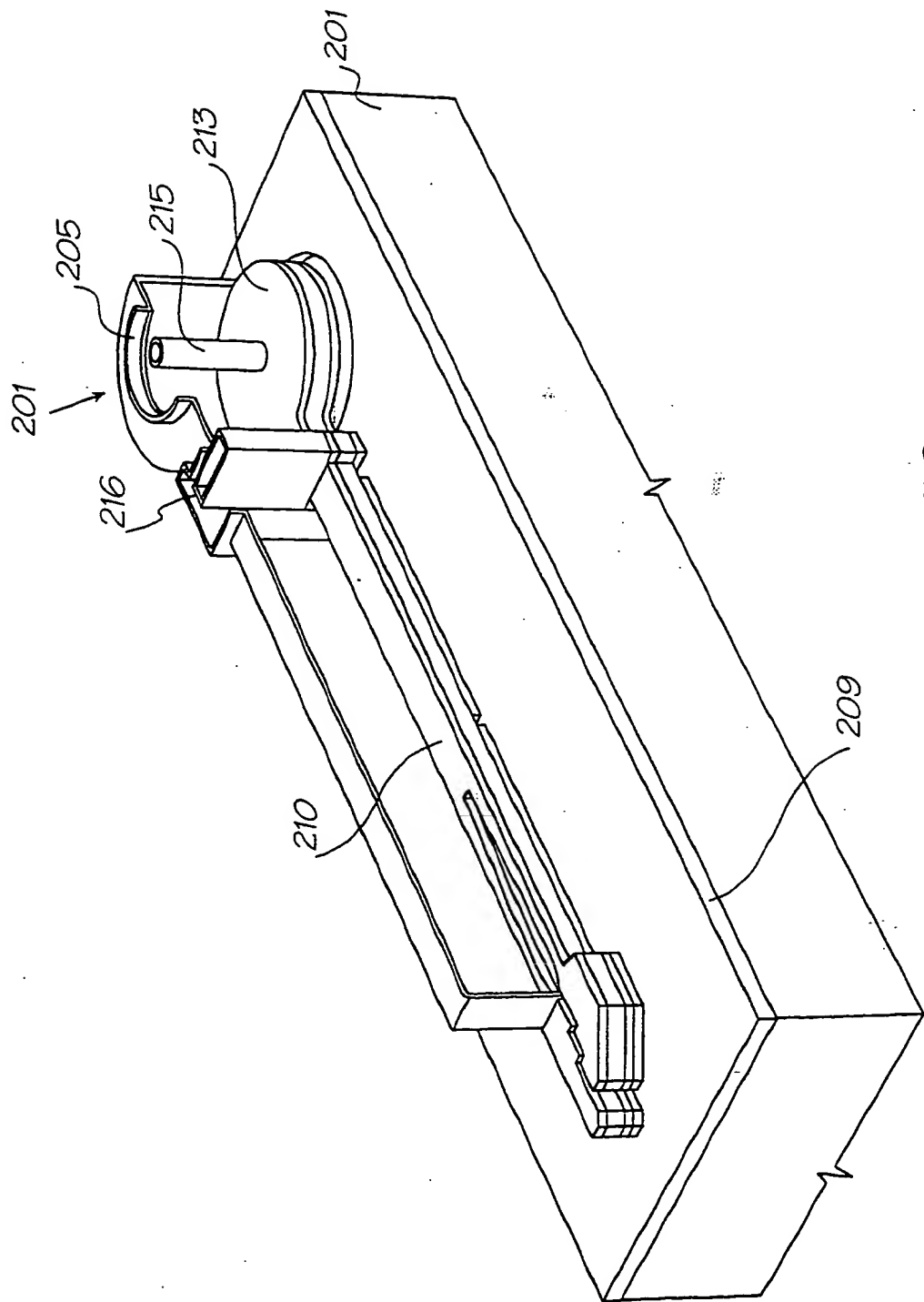


FIG. 107

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FIG. 108

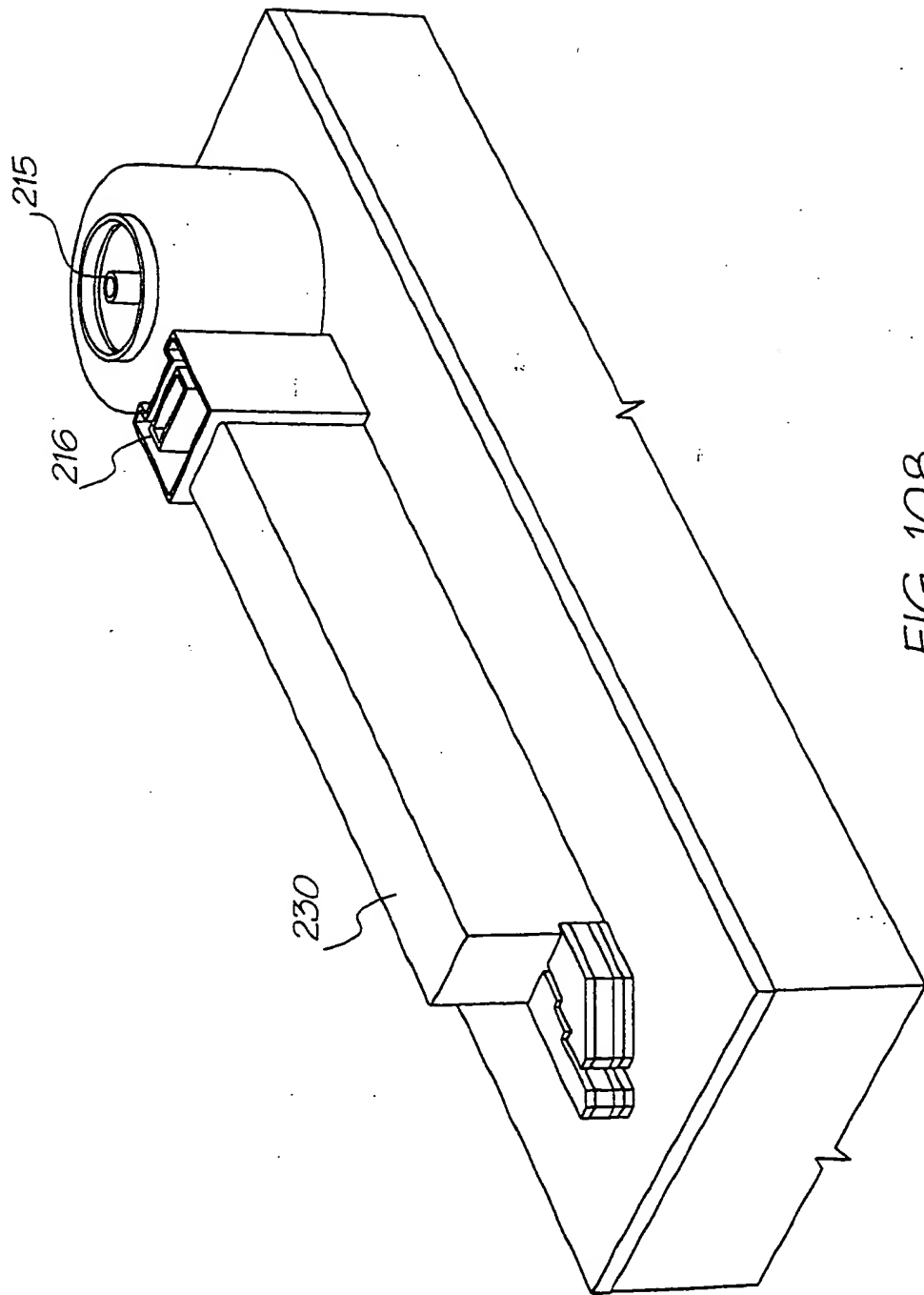


FIG. 108



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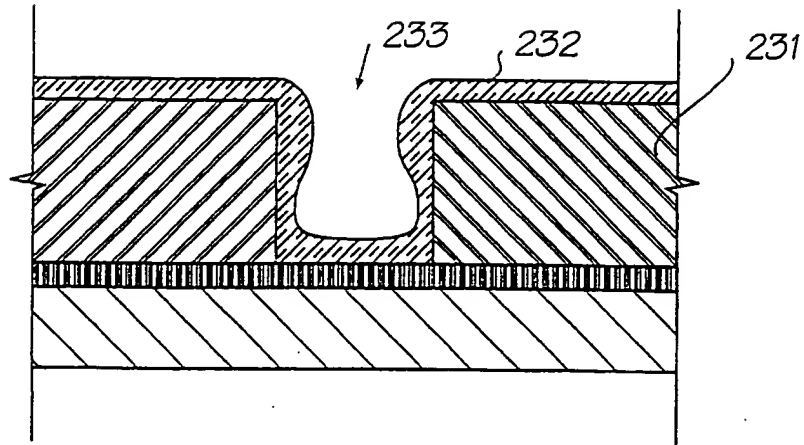


FIG. 109

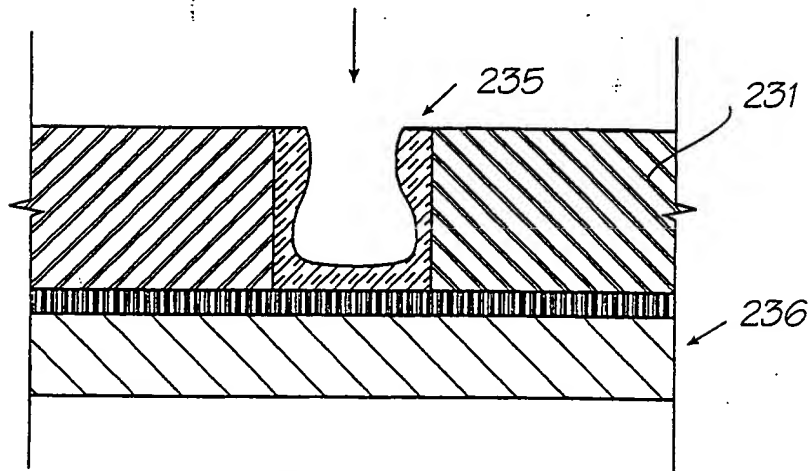


FIG. 110

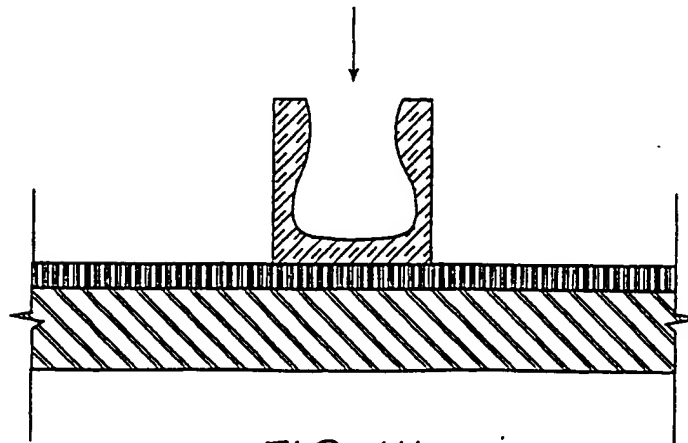


FIG. 111

FIG. 109